



Linko Semiconductor Co., Ltd.

LKS32MC07X with built-in 6N driver Datasheet

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1 Overview

1.1 Functions

LKS32MC070FL/071DO/074F/074D/074DO/076F are 32-bit MCU targeting motor control applications. With the three-phase full-bridge bootstrap gate driver, it can directly drive six N-channel MOSFETs.

● Features

- 96MHz 32-bit Cortex-M0 core
- Customized instruction set DSP for motor control
- Ultra low power sleep mode
- Three-phase full-bridge bootstrap gate driver
- Industrial temperature range
- High ESD and group pulse reliability

● Memory

- Built-in flash including 64kB/128kB main area and 1.5kB NVR
- Endurance: 100,000 Cycles(min)
- Data retention: more than 100 years under room temperature 25 °C
- Single byte program: 7.5us(max), Sector erase: 5ms(max)
- Sector size 512bytes, supporting Sector erase/program
- Flash data anti-theft by programming the last word of flash to any words other than 0xFFFFFFFF

● Operating Conditions

- Dual power supply. The MCU is powered by 2.5V ~ 5.5V voltage, with an integrated internal 1.5V LDO for the digital circuit. For the power supply of the drive module, please refer to the electrical parameters of the gate drive module according to the chip model. Some models integrate a 5V LDO.
- Operating Conditions: -40~105°C

● Clock

- 8MHz built-in high-precision RC oscillator, with an accuracy of $\pm 1\%$ at -40 ~ 105 °C
- 32KHz built-in low-speed clock for low-power mode
- Operating on an external 8MHz crystal is available
- Internal PLL up to 96 MHz

● Peripheral module

- Two UARTs
- One SPI, support master-slave mode
- One IIC, support master-slave mode



- Two 16-bit standard timers (TIM), support capture and edge-aligned PWM function
 - Two 32-bit standard timers (TIM), support capture and edge-aligned PWM function; support orthogonal code input, CW/CCW input, and pulse&symbol input
 - Motor control PWM module, supports 12 channels/6 pairs of PWM waveform output, independent dead-band control
 - Hall signal interface with speed measurement and debouncing function
 - Hardware watchdog
 - 4 Groups of 16bit GPIO at the most. 8 GPIOs could be used as wake-up source。 15 GPIOs could be used as external IRQ source
- **Simulation module**
 - Two 12bit SAR ADC, simultaneous double sampling, 3Msps sampling and conversion rate, and each sampling circuit supports up to 16 channels, including 4 OPA outputs and 10 external ADC channels for a total of 14 optional ADC channel signals
 - Four operational amplifiers. Differential PGA mode is available.
 - Three comparators. Hysteresis mode is available.
 - Two 12bit digital-to-analog converter (DAC)
 - $\pm 2\text{ }^{\circ}\text{C}$ built-in temperature sensor
 - 1.2V 0.8% built-in linear regulator
 - Low-power LDO and power monitoring circuit
 - RC oscillator with high precision and low temperature drift
 - Crystal oscillator circuits

1.2 Performance advantages

- High reliability, high integration level, small package size, saving BOM cost;
- Integrated 4 channels high-speed OPAs and 3 channels comparators, meeting the needs of different system topology like single resistance/double resistance/three resistance current sampling;
- High-speed OPA is integrated with over-voltage protection circuit, which allows high-voltage common-mode signals to be input, which could support direct current sampling of MOSFET resistance with the simplest circuit topology.
- Via a proprietary technique, ADC and high-speed OPA could cooperate well, making them able to handle a wider current dynamic range, while ensuring the sampling precision of high-speed small current and low-speed high current;
- The control circuit is simple and efficient, with strong anti-interference ability, stable and reliable;
- Three-phase full-bridge bootstrap gate driver is integrated
- Supports IEC/UL60730 functional safety certification



Applicable to control systems such as inductive BLDC/non-inductive BLDC/inductive FOC/non-inductive FOC and stepper motors, permanent magnet synchronous and asynchronous motors.



1.3 Naming Conventions

LKS32 MC 070 D 2 M 6 S 8 B (XX)	
Device series	
LKS32	= 32bit MCU
LKS5	= Gate Driver Products
LKS6	= Power IC Product
Product type	
MC	= Motor Control Applications
AT	= Automobile Applications
RV	= RISC-V for Motor Control
Device sub family	
070/071/075	= 2.5~5.5V, 2 ADC, 4 PGA, DSP
070FL/071DO/074D/DO	= 2.5~5.5V, 2 ADC, 4 PGA, DSP, 6N Driver
076/076F	= 2.5~5.5V, 2 ADC, 3 PGA, DSP, 6N Driver
072	= 2.5~5.5V, 2 ADC, 3 PGA
077	= 2.5~5.5V, 2 ADC, 2 PGA
077E	= 7.5~28V, 2 ADC, 2 PGA, 3P3N Driver
Gate Driver Functions	
D	= 3P3N Gate Driver
E/DL	= 3P3N + 5V LDO
S/F	= 6N Gate Driver
SL/FL	= 6N + 5V LDO
K	= High V 6N Gate Driver
O/L5	= 5V LDO/DCDC
L3	= 3.3V/3V LDO
N	= DCDC
P	= 3P3N/4P4N DrMOS
Q	= 6N/8N DrMOS
PL3	= 3P3N DrMOS + 3.3VLDO
PL5	= 3P3N DrMOS + 5VLDO
QL	= 6N DrMOS + LDO
X	= PHY
XL	= PHY + LDO
PKG/Driver Ver	
2	= 2 nd Ver
S	= S 侧面上锡
Pin count	
L	= 16 pins
H	= 20 pins
M	= 24 pins
Y	= 28 pins
K	= 32 pins
F	= 40 pins
G	= 42 pins
U	= 44 pins
C	= 48 pins
N	= 52 pins
E	= 54 pins
R	= 60 pins
P	= 64 pins
V	= 80 pins
Q	= 100 pins
Z	= 128 pins
Code size	
4	= 16Kbyte Flash Memory
6	= 32Kbyte Flash Memory
8	= 64Kbyte Flash Memory
B	= 128Kbyte Flash Memory
C	= 256Kbyte Flash Memory
D	= 384Kbyte Flash Memory
E	= 512Kbyte Flash Memory
Package	
P	= TSSOP
T	= TQFP/LQFP
Q	= QFN
S	= SSOP
H	= BGA
Temperature range	
6	= -40~85°
8	= -40~105°
9	= -40~125°
MCU Ver	
B	= B ver
Options	
TR	= Tape and reel packing
P	= ES

Fig.1-1 Naming Conventions of Linko Components



1.4 Resource Diagram

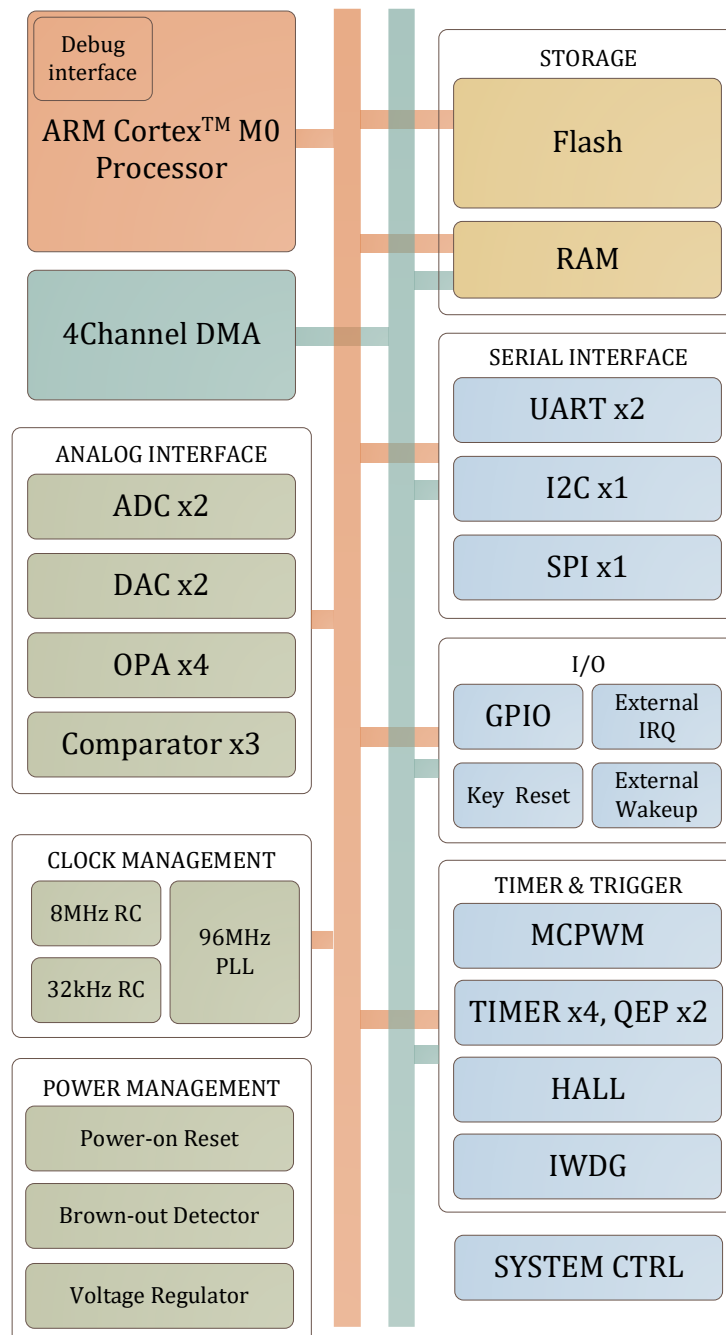
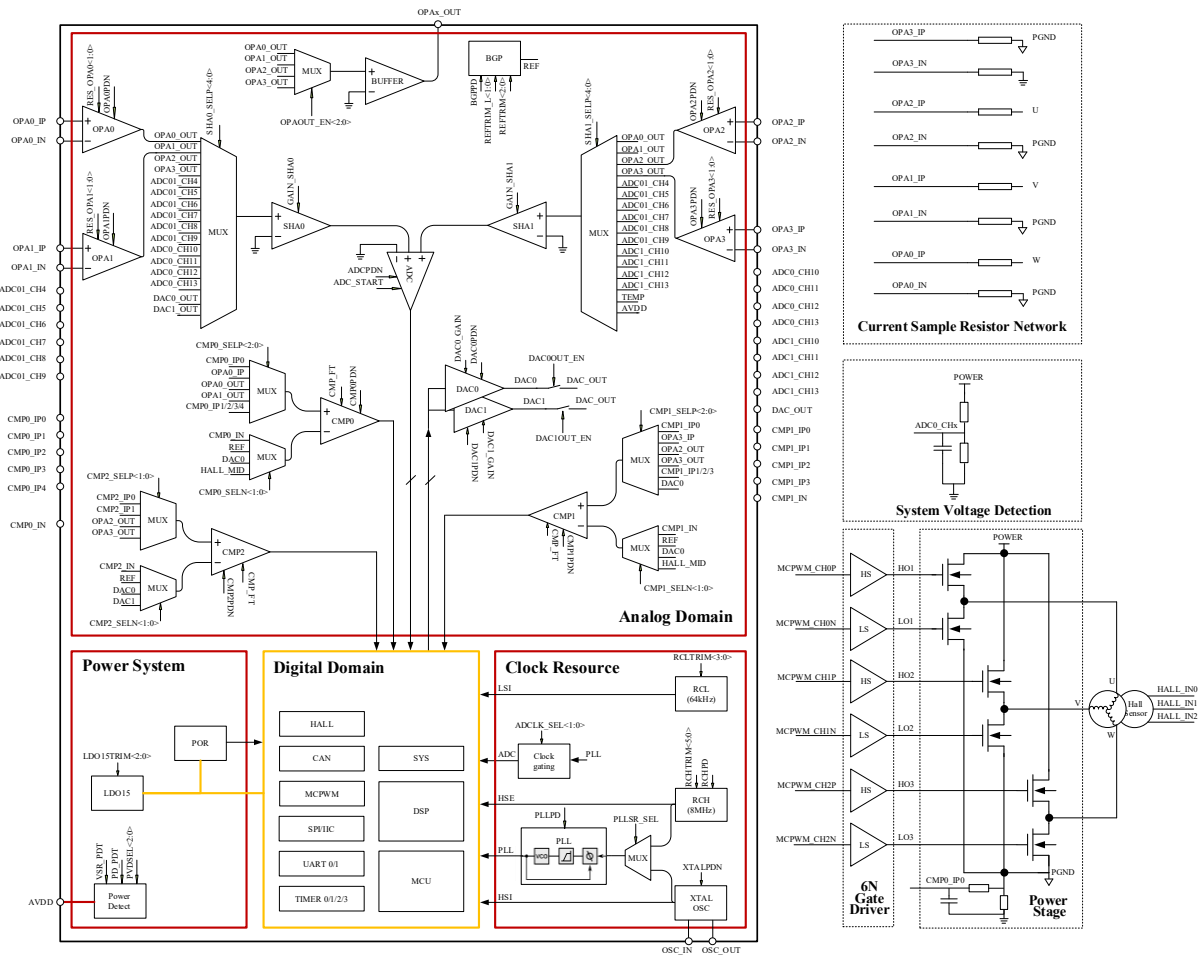


Fig. 1-2 LKS32MC07x Resource Diagram

1.5 FOC System Example



* ADC 0/1_CH4 ~ ADC 0/1_CH9 are common channels for ADC0 and ADC 1

Fig.1-3 LKS32MC076FNBQ8 Simplified Schematic of FOC System

2 Device selection table

Table 2-1 LKS07x Series Device Selection Table

	Frequency (MHz)	Flash (kB)	RAM (kB)	ADC ch.	DAC	Comparator	Comparator ch.	OPA	HALL	SPI	IIC	UART	CAN	Temp. Sensor	PLL	QEP	Gate driver	Gate Driver current (A)	Pre-drive supply (V)	Gate floating voltage (V)	Others	Package
LKS32MC070FLRBT8	96	128	12	14	12BITx2	3	10	4	3	1	1	2	Yes	Yes	Yes	Yes	6N	+1/-1	4.5~20	60	5V LDO	LQFP64
LKS32MC071DOC8T8	96	64	12	13	12BITx2	3	10	3	3	1	1	2	Yes	Yes	Yes	Yes	6N	+1/-1	4.5~20	60	5V LDO	LQFP48
LKS32MC074FF8Q8	96	64	12	10	12BITx2	3	9	3	3	1	1	2	Yes	Yes	Yes	Yes	6N	+1/-1	4.5~20	60	5V LDO	QFN5*5 40L-0.75
LKS32MC074DF8Q8	96	64	12	13	12BITx2	3	9	3	3	1	1	2		Yes	Yes	Yes	6N	+1.2/-1.5	7~20	200		QFN5*5 40L-0.75
LKS32MC074DOF8Q8	96	64	12	12	12BITx2	3	9	3	3	1	1	2		Yes	Yes	Yes	6N	+1/-1	4.5~20	250	5V LDO	QFN5*5 40L-0.75
LKS32MC076FNBQ8	96	128	12	12	12BITx2	3	11	4	3	1	1	2	Yes	Yes	Yes	Yes	6N	+1.2/-1.5	7~20	200		QFN52
LKS32MC078KUBQ8	96	128	12	10	12BITx2	3	9	3	3路	1	1	2		Yes	Yes	Yes	6N	+0.45/-1	4.5~20	600		量产

3 Pin Assignment

3.1 Pin Assignment and Pin Function Description

3.1.1 Special instructions

The MCU power supply pin AVDD with integrated 5V LDO pre-drive is connected to the 5V LDO output inside the MCU, and the AVDD does not require external power supply. Pre-drive MCUS without a 5V LDO require the full bridge drive power supply VCC pin and AVDD pin to be powered independently.

The red pin in the pin assignment figures below has built-in pull-up resistors:

RSTN has a 100kΩ built-in pull-up resistor, which is enabled automatically after power-up.

SWDIO/SWCLK has a 10kΩ built-in pull-up resistor, which is enabled automatically after power-up.

The remaining pins with PU function have 10kΩ built-in pull-up resistors, which could be software-enabled.

UARTx_TX(RX): UART TX and RX support interchange. When the second function of GPIO is selected as UART, and GPIO_PIE is input enabled, it can be used as UART_RX; when GPIO_POE is enabled, it can be used as UART_TX. Generally, the same GPIO does not enable input and output at the same time, otherwise the input PDI will receive the data sent by the PDO.

SPI_DI(DO): The DI and DO of SPI can also be interchanged. When the second function of GPIO is SPI, and GPIO_PIE is input enable, it can be used as SPI_DI; when GPIO_POE is output enable, it can be used as SPI_DO. Generally, the same GPIO does not enable input and output at the same time, otherwise the input PDI will receive the data sent by the PDO.

EN: Gate drive module G6 enabled, high level enable pre-drive output, low level off output. Built-in pull-up resistor, pull-up to 5V. In 074DO this function pin is connected to MCU P1.11 and can be enabled by configuring the P1.11 output level control gate drive.

3.1.2 LKS32MC070FLRBT8

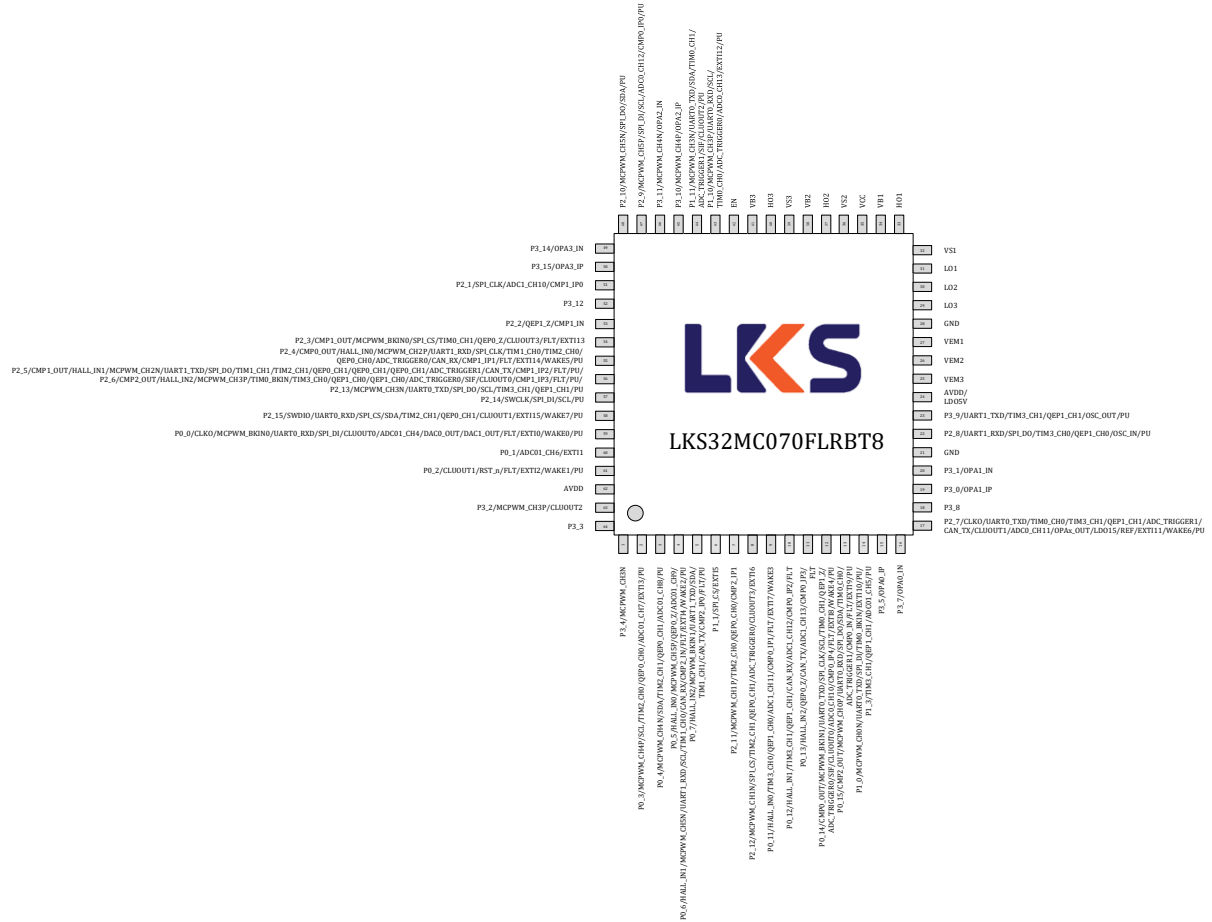


Fig.3-1 LKS32MC070FLRBT8 Pin Assignment

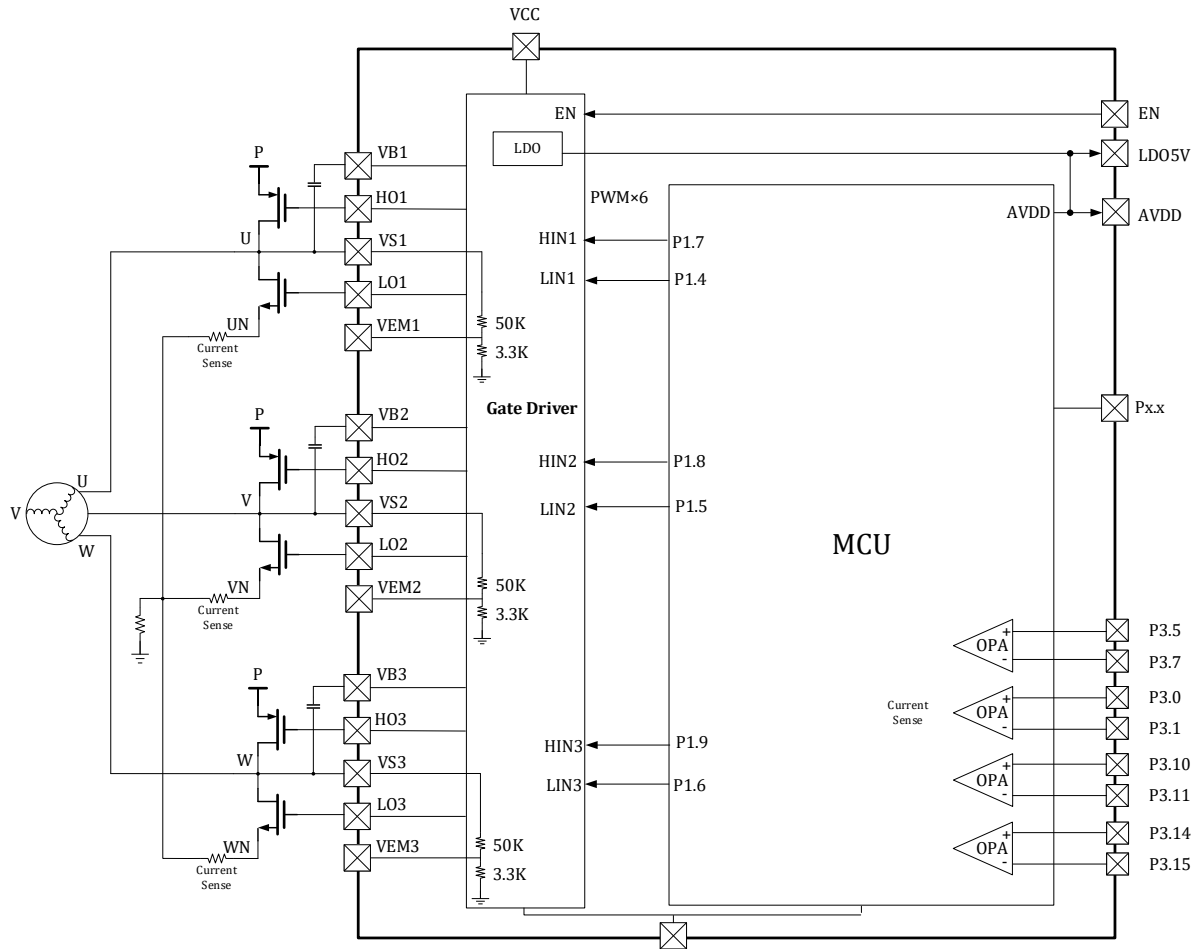


Fig.3-2 LKS32MC070FLRBT8 Schematic diagram of inner driver connection

Table 3-1 LKS32MC070FLRBT8 Pin Function Description

1	P3_4	P3.4
	MCPWM_CH3N	PWM channel 3 low-side
2	P0_3	P0.3
	MCPWM_CH4P	PWM channel 4 high-side
	SCL	I2C clock
	TIM2_CH0	Timer2 channel0
	QEP0_CH0	Encoder0 channel0
	ADC01_CH7	ADC01 channel 7
	EXTI3	External GPIO interrupt input signal 3
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
3	P0_4	P0.4
	MCPWM_CH4N	PWM channel 4 low-side
	SDA	I2C data
	TIM2_CH1	Timer2 channel1
	QEP0_CH1	Encoder0 channel1
	ADC01_CH8	ADC01 channel 8
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software

4	P0_5	P0.5
	HALL_IN0	Hall interface input 0
	MCPWM_CH5P	PWM channel 5 high-side
	QEP0_Z	QEP0 encoder Z phase
	ADC01_CH9	ADC0/1 channel 9
	P0_6	P0.6
	HALL_IN1	Hall interface input 1
	MCPWM_CH5N	PWM channel 5 low-side
	UART1_RXD	UART1 receive(transmit)
	SCL	I2C clock
	TIM1_CH0	Timer1 channel0
	CAN_RX	CAN Receive
	CMP2_IN	Comparator2 negative input
	FLT	IO filtering
	EXTI4	External GPIO interrupt input signal 4
	WAKE2	External wake-up signal 2
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
5	P0_7	P0.7
	HALL_IN2	Hall interface input 2
	MCPWM_BKIN1	PWM break signal 1
	UART1_TXD	UART1 transmit(receive)
	SDA	I2C data
	TIM1_CH1	Timer1 channel1
	CAN_TX	CAN Transmit
	CMP2_IP0	Comparator2 positive input0
	FLT	IO filtering
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
6	P1_1	P1.1
	SPI_CS	SPI chip select
	EXTI5	External GPIO interrupt input signal 5
7	P2_11	P2.11
	MCPWM_CH1P	PWM channel 1 high-side
	TIM2_CH0	Timer2 channel0
	QEP0_CH0	Encoder0 channel0
	CMP2_IP1	Comparator2 positive input1
8	P2_12	P2.12
	MCPWM_CH1N	PWM channel 1 low-side
	SPI_CS	SPI chip select
	TIM2_CH1	Timer2 channel1
	QEP0_CH1	Encoder0 channel1
	ADC_TRIGGER0	ADC0 trigger for debug
	CLUOUT3	CLU3 output
	EXTI6	External GPIO interrupt input signal 6

9	P0_11	P0.11
	HALL_IN0	Hall interface input 0
	TIM3_CH0	Timer3 channel0
	QEP1_CH0	Encoder1 channel0
	ADC1_CH11	ADC1 channel 11
	CMP0_IP1	Comparator0 positive input1
	FLT	IO filtering
	EXTI7	External GPIO interrupt input signal 7
	WAKE3	External wake-up signal 3
10	P0_12	P0.12
	HALL_IN1	Hall interface input 1
	TIM3_CH1	Timer3 channel1
	QEP1_CH1	Encoder1 channel1
	CAN_RX	CAN Receive
	ADC1_CH12	ADC1 channel 12
	CMP0_IP2	Comparator0 positive input2
	FLT	IO filtering
11	P0_13	P0.13
	HALL_IN2	Hall interface input 2
	QEP0_Z	QEP0 encoder Z phase
	CAN_TX	CAN Transmit
	ADC1_CH13	ADC1 channel 13
	CMP0_IP3	Comparator0 positive input3
	FLT	IO filtering
12	P0_14	P0.14
	CMP0_OUT	Comparator 0 output
	MCPWM_BKIN1	PWM break signal 1
	UART0_TXD	UART0 transmit(receive)
	SPI_CLK	SPI clock
	SCL	I2C clock
	TIM0_CH1	Timer0 channel1
	QEP1_Z	QEP1 encoder Z phase
	ADC_TRIGGER0	ADC0 trigger for debug
	SIF	Single line communication
	CLUOUT0	CLU0 output
	ADC0_CH10	ADC0 channel 10
	CMP0_IP4	Comparator0 positive input4
	FLT	IO filtering
	EXTI8	External GPIO interrupt input signal 8
	WAKE4	External wake-up signal 4
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
13	P0_15	P0.15
	CMP2_OUT	Comparator 2 output

	MCPWM_CH0P	PWM channel 0 high-side
	UART0_RXD	UART0 receive(transmit)
	SPI_DO	SPI data output(input)
	SDA	I2C data
	TIM0_CH0	Timer0 channel0
	ADC_TRIGGER1	ADC1 trigger for debug
	CMP0_IN	Comparator0 negative input
	FLT	IO filtering
	EXTI9	External GPIO interrupt input signal 9
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
14	P1_0	P1.0
	MCPWM_CH0N	PWM channel 0 low-side
	UART0_TXD	UART0 transmit(receive)
	SPI_DI	SPI data input(output)
	TIM0_BKIN	
	EXTI10	External GPIO interrupt input signal 10
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P1_3	P1.3
	TIM3_CH1	Timer3 channel1
	QEP1_CH1	Encoder1 channel1
	ADC01_CH5	ADC0/1 channel 5
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
15	P3_5	P3.5
	OPA0_IP	OPA0 positive input
16	P3_7	P3.7
	OPA0_IN	OPA0 negative input
17	P2_7	P2.7
	CLK0	Clock output for debug
	UART0_TXD	UART0 transmit(receive)
	TIM0_CH0	Timer0 channel0
	TIM3_CH1	Timer3 channel1
	QEP1_CH1	Encoder1 channel1
	ADC_TRIGGER1	ADC1 trigger for debug
	CAN_TX	CAN Transmit
	CLUOUT1	CLU1 output
	ADC0_CH11	ADC0 channel 11
	OPAx_OUT	OPA output
	LDO15	1.5V LDO output
	REF	Reference voltage output for debug
	EXTI11	External GPIO interrupt input signal 11
	WAKE6	External wake-up signal 6
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
18	P3_8	P3.8

19	P3_0	P3.0
	OPA1_IP	OPA1 positive input
20	P3_1	P3.1
	OPA1_IN	OPA1 negative input
21	GND	Chip ground. It is strongly recommended that multiple ground pins be grounded uniformly on the PCB.
22	P2_8	P2.8
	UART1_RXD	UART1 receive(transmit)
	SPI_DO	SPI data output(input)
	TIM3_CH0	Timer3 channel0
	QEP1_CH0	Encoder1 channel0
	OSC_IN	External crystal oscillator pin
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
23	P3_9	P3.9
	UART1_TXD	UART1 transmit(receive)
	TIM3_CH1	Timer3 channel1
	QEP1_CH1	Encoder1 channel1
	OSC_OUT	External crystal oscillator pin
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
24	AVDD	Power supply, 2.2~5.5V
	LDO5V	5V LDO output
25	VEM3	C phase VS 50k/3.3k cascaded resistor voltage divided output, built-in voltage 5V 30pF capacitor. The voltage ratio can be adjusted by adding external shunt resistor. If the voltage exceeds 5V, the sampled signal will be clamped by diode
26	VEM2	B phase VS 50k/3.3k cascaded resistor voltage divided output, built-in voltage 5V 30pF capacitor. The voltage ratio can be adjusted by adding external shunt resistor. If the voltage exceeds 5V, the sampled signal will be clamped by diode
27	VEM1	A phase VS 50k/3.3k cascaded resistor voltage divided output, built-in voltage 5V 30pF capacitor. The voltage ratio can be adjusted by adding external shunt resistor. If the voltage exceeds 5V, the sampled signal will be clamped by diode
28	GND	Chip ground. It is strongly recommended that multiple ground pins be grounded uniformly on the PCB.
29	LO3	Phase C low-side output, worked by MCU P1.6; the polarity of LO3 is the same as that of P1.6, i.e. when P1.6 = 1, LO3 = 1. You need to set MCPWM_SWAP = 1.
30	LO2	Phase B low-side output, worked by MCU P1.5; the polarity of LO2 is the same as that of P1.5, i.e. when P1.5 = 1, LO2 = 1. You need to set MCPWM_SWAP = 1.
31	LO1	Phase A low-side output, worked by MCU P1.4; the polarity of LO1 is the same as that of P1.4, i.e. when P1.4 = 1, LO1 = 1. You need to set MCPWM_SWAP = 1.
32	VS1	High-side floating bias voltage 1.
33	HO1	Phase A high-side output, worked by MCU P1.7; the polarity of HO1 is the same as that of P1.7, i.e. when P1.7 = 1, HO1 = 1. You need to set MCPWM_SWAP = 1.
34	VB1	High-side floating supply voltage 1.
35	VCC	Gate driver power supply

36	VS2	High-side floating bias voltage 2.
37	HO2	Phase B high-side output, worked by MCU P1.8; the polarity of HO2 is the same as that of P1.8, i.e. when P1.8 = 1, HO2 = 1. You need to set MCPWM_SWAP = 1.
38	VB2	High-side floating supply voltage 2.
39	VS3	High-side floating bias voltage 3.
40	HO3	Phase C high-side output, worked by MCU P1.9; the polarity of HO3 is the same as that of P1.9, i.e. when P1.9 = 1, HO3 = 1. You need to set MCPWM_SWAP = 1.
41	VB3	High-side floating supply voltage 3.
42	EN	Gate drive Enable. High level enables driver output, low level disables output. Built-in pull-up resistor, pull-up to 5V
43	P1_10	P1.10
	MCPWM_CH3P	PWM channel 3 high-side
	UART0_RXD	UART0 receive(transmit)
	SCL	I2C clock
	TIM0_CH0	Timer0 channel0
	ADC_TRIGGER0	ADC0 trigger for debug
	ADC0_CH13	ADC0 channel 13
	EXTI12	External GPIO interrupt input signal 12
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
44	P1_11	P1.11
	MCPWM_CH3N	PWM channel 3 low-side
	UART0_TXD	UART0 transmit(receive)
	SDA	I2C data
	TIM0_CH1	Timer0 channel1
	ADC_TRIGGER1	ADC1 trigger for debug
	SIF	Single line communication
	CLUOUT2	CLU2 output
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
45	P3_10	P3.10
	MCPWM_CH4P	PWM channel 4 high-side
	OPA2_IP	OPA2 positive input
46	P3_11	P3.11
	MCPWM_CH4N	PWM channel 4 low-side
	OPA2_IN	OPA2 negative input
47	P2_9	P2.9
	MCPWM_CH5P	PWM channel 5 high-side
	SPI_DI	SPI data input(output)
	SCL	I2C clock
	ADC0_CH12	ADC0 channel 12
	CMP0_IP0	Comparator0 positive input0
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
48	P2_10	P2.10
	MCPWM_CH5N	PWM channel 5 low-side

	SPI_DO	SPI data output(input)
	SDA	I2C data
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
49	P3_14	P3.14
	OPA3_IN	OPA3 negative input
50	P3_15	P3.15
	OPA3_IP	OPA3 positive input
51	P2_1	P2.1
	SPI_CLK	SPI clock
	ADC1_CH10	ADC1 channel 10
	CMP1_IP0	Comparator1 positive input0
52	P3_12	P3.12
53	P2_2	P2.2
	QEP1_Z	QEP1 encoder Z phase
	CMP1_IN	Comparator1 negative input
54	P2_3	P2.3
	CMP1_OUT	Comparator 1 output
	MCPWM_BKIN0	PWM break signal 0
	SPI_CS	SPI chip select
	TIM0_CH1	Timer0 channel1
	QEP0_Z	QEP0 encoder Z phase
	CLUOUT3	CLU3 output
	FLT	IO filtering
	EXTI13	External GPIO interrupt input signal 13
55	P2_4	P2.4
	CMP0_OUT	Comparator 0 output
	HALL_IN0	Hall interface input 0
	MCPWM_CH2P	PWM channel 2 high-side
	UART1_RXD	UART1 receive(transmit)
	SPI_CLK	SPI clock
	TIM1_CH0	Timer1 channel0
	TIM2_CH0	Timer2 channel0
	QEP0_CH0	Encoder0 channel0
	ADC_TRIGGER0	ADC0 trigger for debug
	CAN_RX	CAN Receive
	CMP1_IP1	Comparator1 positive input1
	FLT	IO filtering
	EXTI14	External GPIO interrupt input signal 14
	WAKE5	External wake-up signal 5
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
56	P2_5	P2.5
	CMP1_OUT	Comparator 1 output
	HALL_IN1	Hall interface input 1

	MCPWM_CH2N	PWM channel 2 low-side
	UART1_TXD	UART1 transmit(receive)
	SPI_DO	SPI data output(input)
	TIM1_CH1	Timer1 channel1
	TIM2_CH1	Timer2 channel1
	QEP0_CH1	Encoder0 channel1
	QEP0_CH1	Encoder0 channel1
	QEP0_CH1	Encoder0 channel1
	ADC_TRIGGER1	ADC1 trigger for debug
	CAN_TX	CAN Transmit
	CMP1_IP2	Comparator1 positive input2
	FLT	IO filtering
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P2_6	P2.6
	CMP2_OUT	Comparator 2 output
	HALL_IN2	Hall interface input 2
	MCPWM_CH3P	PWM channel 3 high-side
	TIM0_BKIN	
	TIM3_CH0	Timer3 channel0
	QEP1_CH0	Encoder1 channel0
	QEP1_CH0	Encoder1 channel0
	ADC_TRIGGER0	ADC0 trigger for debug
	SIF	Single line communication
	CLUOUT0	CLU0 output
	CMP1_IP3	Comparator1 positive input3
	FLT	IO filtering
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P2_13	P2.13
	MCPWM_CH3N	PWM channel 3 low-side
	UART0_TXD	UART0 transmit(receive)
	SPI_DO	SPI data output(input)
	SCL	I2C clock
	TIM3_CH1	Timer3 channel1
	QEP1_CH1	Encoder1 channel1
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
57	P2_14	P2.14
	SWCLK	SWD Clock
	SPI_DI	SPI data input(output)
	SCL	I2C clock
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
58	P2_15	P2.15
	SWDIO	SWD Data
	UART0_RXD	UART0 receive(transmit)

	SPI_CS	SPI chip select
	SDA	I2C data
	TIM2_CH1	Timer2 channel1
	QEP0_CH1	Encoder0 channel1
	CLUOUT1	CLU1 output
	EXTI15	External GPIO interrupt input signal 15
	WAKE7	External wake-up signal 7
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
59	P0_0	P0.0
	CLK0	Clock output for debug
	MCPWM_BKIN0	PWM break signal 0
	UART0_RXD	UART0 receive(transmit)
	SPI_DI	SPI data input(output)
	CLUOUT0	CLU0 output
	ADC01_CH4	ADC0/1 channel 4
	DAC0_OUT	DAC0 out put
	DAC1_OUT	DAC1 out put
	FLT	IO filtering
	EXTI0	External GPIO interrupt input signal 0
	WAKE0	External wake-up signal 0
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
60	P0_1	P0.1
	ADC01_CH6	ADC0/1 channel 6
	EXTI1	External GPIO interrupt input signal 1
61	P0_2	P0.2
	CLUOUT1	CLU1 output
	RST_n	P0.2 is used as RSTN by default. A 10nF-100nF capacitor should be connected to the ground. It is recommended a 10k-20k pull-up resistor is placed between RSTN and AVDD on PCB. If there is an external pull-up resistor, the capacitance of RSTN should be 100nF. The built-in 10kΩ pull-up resistor could be turned-off by software.
	FLT	IO filtering
	EXTI2	External GPIO interrupt input signal 2
	WAKE1	External wake-up signal 1
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
62	AVDD	Power supply, 2.2~5.5V
63	P3_2	P3.2
	MCPWM_CH3P	PWM channel 3 high-side
	CLUOUT2	CLU2 output
64	P3_3	P3.3

3.1.3 LKS32MC071DOC8T8

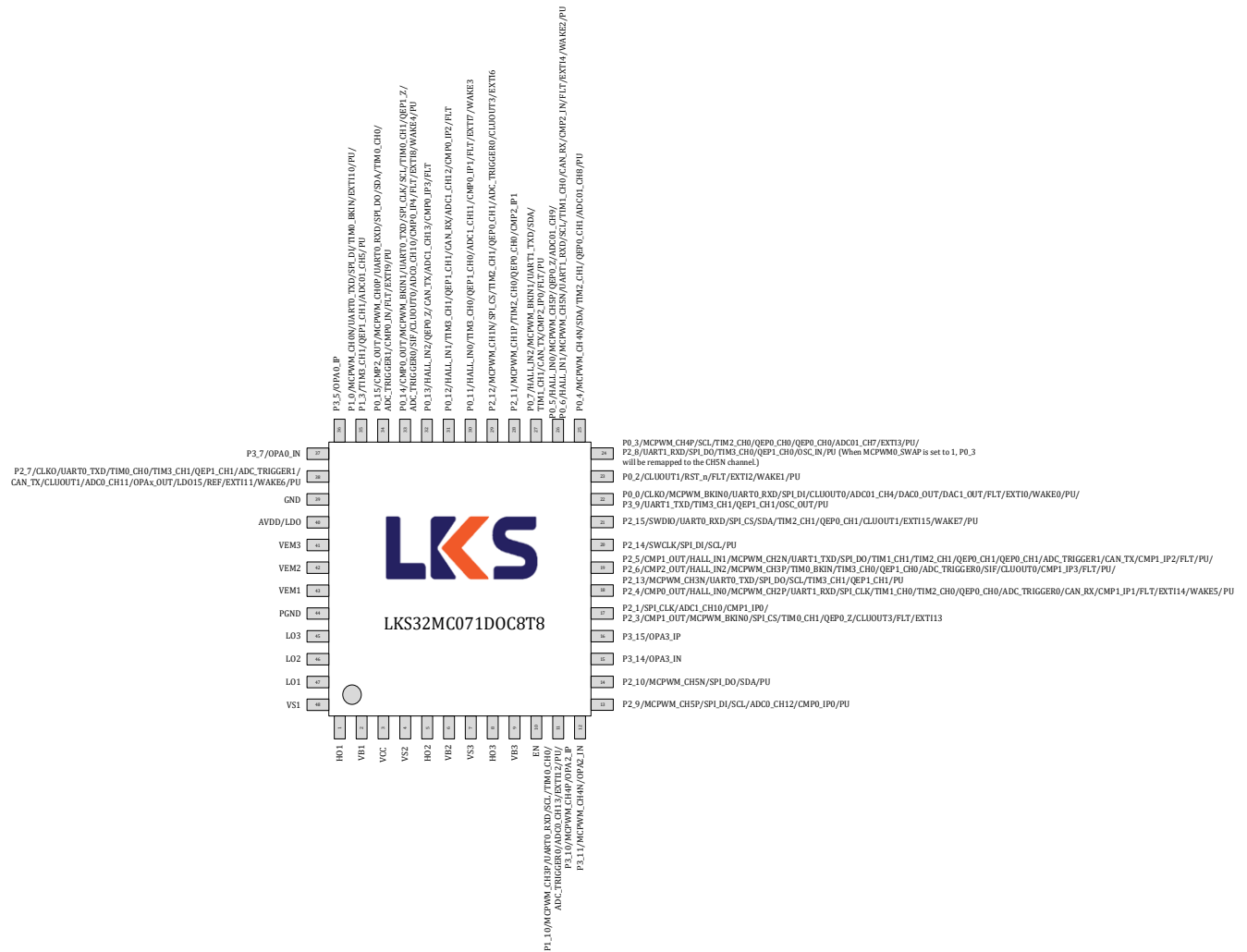


Fig.3-3 LKS32MC071DOC8T8 Pin Assignment

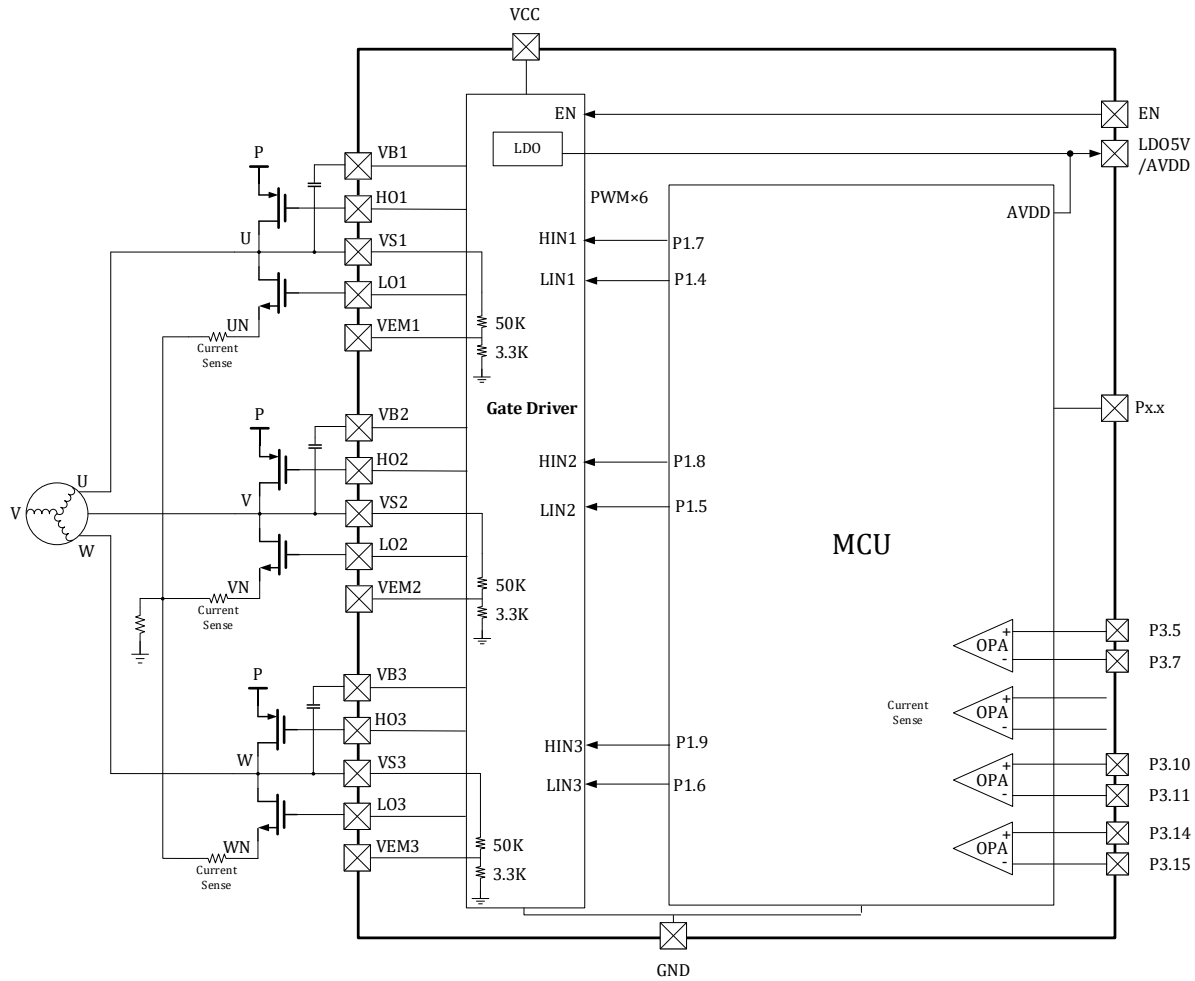


Fig.3-4 LKS32MC071DOC8T8 Schematic diagram of inner driver connection

Table 3-2 LKS32MC071DOC8T8 Pin Function Description

1	HO1	Phase A high-side output, worked by MCU P1.7; the polarity of HO1 is the same as that of P1.7, i.e. when P1.7 = 1, HO1 = 1. You need to set MCPWM_SWAP = 1.
2	VB1	High-side floating supply voltage 1.
3	VCC	Gate driver power supply
4	VS2	High-side floating bias voltage 2.
5	HO2	Phase B high-side output, worked by MCU P1.8; the polarity of HO2 is the same as that of P1.8, i.e. when P1.8 = 1, HO2 = 1. You need to set MCPWM_SWAP = 1.
6	VB2	High-side floating supply voltage 2.
7	VS3	High-side floating bias voltage 3.
8	HO3	Phase C high-side output, worked by MCU P1.9; the polarity of HO3 is the same as that of P1.9, i.e. when P1.9 = 1, HO3 = 1. You need to set MCPWM_SWAP = 1.
9	VB3	High-side floating supply voltage 3.
10	EN	Gate drive Enable. High level enables driver output, low level disables output. Built-in pull-up resistor, pull-up to 5V
11	P1_10	P1.10
	MCPWM_CH3P	PWM channel 3 high-side
	UART0_RXD	UART0 receive(transmit)

	SCL	I2C clock
	TIM0_CH0	Timer0 channel0
	ADC_TRIGGER0	ADC0 trigger for debug
	ADC0_CH13	ADC0 channel 13
	EXTI12	External GPIO interrupt input signal 12
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P3_10	P3.10
	MCPWM_CH4P	PWM channel 4 high-side
	OPA2_IP	OPA2 positive input
12	P3_11	P3.11
	MCPWM_CH4N	PWM channel 4 low-side
	OPA2_IN	OPA2 negative input
13	P2_9	P2.9
	MCPWM_CH5P	PWM channel 5 high-side
	SPI_DI	SPI data input(output)
	SCL	I2C clock
	ADC0_CH12	ADC0 channel 12
	CMP0_IP0	Comparator0 positive input0
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
14	P2_10	P2.10
	MCPWM_CH5N	PWM channel 5 low-side
	SPI_DO	SPI data output(input)
	SDA	I2C data
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
15	P3_14	P3.14
	OPA3_IN	OPA3 negative input
16	P3_15	P3.15
	OPA3_IP	OPA3 positive input
17	P2_1	P2.1
	SPI_CLK	SPI clock
	ADC1_CH10	ADC1 channel 10
	CMP1_IP0	Comparator1 positive input0
	P2_3	P2.3
	CMP1_OUT	Comparator 1 output
	MCPWM_BKIN0	PWM break signal 0
	SPI_CS	SPI chip select
	TIM0_CH1	Timer0 channel1
	QEP0_Z	QEP0 encoder Z phase
	CLUOUT3	CLU3 输出
	FLT	IO filtering
	EXTI13	External GPIO interrupt input signal 13
18	P2_4	P2.4
	CMP0_OUT	Comparator 0 output

	HALL_IN0	Hall interface input 0
	MCPWM_CH2P	PWM channel 2 high-side
	UART1_RXD	UART1 receive(transmit)
	SPI_CLK	SPI clock
	TIM1_CH0	Timer1 channel0
	TIM2_CH0	Timer2 channel0
	QEP0_CH0	QEP0 channel0
	ADC_TRIGGER0	ADC0 trigger for debug
	CAN_RX	CAN Receive
	CMP1_IP1	Comparator1 positive input1
	FLT	IO filtering
	EXTI14	External GPIO interrupt input signal 14
	WK5	External wake-up signal 5
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
19	P2_5	P2.5
	CMP1_OUT	Comparator 1 output
	HALL_IN1	Hall interface input 1
	MCPWM_CH2N	PWM channel 2 low-side
	UART1_TXD	UART1 transmit(receive)
	SPI_DO	SPI data output(input)
	TIM1_CH1	Timer1 channel1
	TIM2_CH1	Timer2 channel1
	QEP0_CH1	QEP0 channel1
	QEP0_CH1	QEP0 channel1
	ADC_TRIGGER1	ADC1 trigger for debug
	CAN_TX	CAN Transmit
	CMP1_IP2	Comparator1 positive input2
	FLT	IO filtering
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P2_6	P2.6
	CMP2_OUT	Comparator 2 output
	HALL_IN2	Hall interface input 2
	MCPWM_CH3P	PWM channel 3 high-side
	TIM0_BKIN	TIMER0_FAIL signal from GPIO
	TIM3_CH0	Timer3 channel0
	QEP1_CH0	QEP1 channel0
	ADC_TRIGGER0	ADC0 trigger for debug
	SIF	Single line communication
	CLUOUT0	CLU0 output
	CMP1_IP3	Comparator1 positive input3
	FLT	IO filtering
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P2_13	P2.13

	MCPWM_CH3N	PWM channel 3 low-side
	UART0_TXD	UART0 transmit(receive)
	SPI_DO	SPI data output(input)
	SCL	I2C clock
	TIM3_CH1	Timer3 channel1
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
20	P2_14	P2.14
	SWCLK	SWD Clock
	SPI_DI	SPI data input(output)
	SCL	I2C clock
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
21	P2_15	P2.15
	SWDIO	SWD Data
	UART0_RXD	UART0 receive(transmit)
	SPI_CS	SPI chip select
	SDA	I2C data
	TIM2_CH1	Timer2 channel1
	CLUOUT1	CLU1 output
	EXTI15	External GPIO interrupt input signal 15
	WK7	External wake-up signal 7
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
22	P0_0	P0.0
	CLK0	Clock output for debug
	MCPWM_BKIN0	PWM break signal 0
	UART0_RXD	UART0 receive(transmit)
	SPI_DI	SPI data input(output)
	CLUOUT0	CLU0 output
	ADC01_CH4	ADC0/1 channel 4
	DAC0_OUT	DAC0 output
	DAC1_OUT	DAC1 out put
	FLT	IO filtering
	EXTI0	External GPIO interrupt input signal 0
	WK0	External wake-up signal 0
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P3_9	P3.9
	UART1_TXD	UART1 transmit(receive)
	TIM3_CH1	Timer3 channel1
	OSC_OUT	External crystal oscillator pin
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
23	P0_2	P0.2
	CLUOUT1	CLU1 output
	RST_n	P0.2 is used as RSTN by default. A 10nF-100nF capacitor should be connected to the ground. It is recommended a 10k-20k pull-up resistor is placed between

		RSTN and AVDD on PCB. If there is an external pull-up resistor, the capacitance of RSTN should be 100nF. The built-in 10kΩ pull-up resistor could be turned-off by software.
	FLT	IO filtering
	EXTI2	External GPIO interrupt input signal 2
	WK1	External wake-up signal 1
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
24	P0_3	P0.3
	MCPWM_CH4P	PWM channel 4 high-side
	SCL	I2C clock
	TIM2_CH0	Timer2 channel0
	ADC01_CH7	ADC0/1 channel 7
	EXTI3	External GPIO interrupt input signal 3
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P2_8	P2.8
	UART1_RXD	UART1 receive(transmit)
	SPI_DO	SPI data output(input)
	TIM3_CH0	Timer3 channel0
	OSC_IN	External crystal oscillator pin
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
25	P0_4	P0.4
	MCPWM_CH4N	PWM channel 4 low-side
	SDA	I2C data
	TIM2_CH1	Timer2 channel1
	ADC01_CH8	ADC0/1 channel 8
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
26	P0_5	P0.5
	HALL_IN0	Hall interface input 0
	MCPWM_CH5P	PWM channel 5 high-side
	QEP0_Z	QEP0 encoder Z phase
	ADC01_CH9	ADC0/1 channel 9
	P0_6	P0.6
	HALL_IN1	Hall interface input 1
	MCPWM_CH5N	PWM channel 5 low-side
	UART1_RXD	UART1 receive(transmit)
	SCL	I2C clock
	TIM1_CH0	Timer1 channel0
	CAN_RX	CAN Receive
	CMP2_IN	Comparator2 negative input
	FLT	IO filtering
	EXTI4	External GPIO interrupt input signal 4
	WK2	External wake-up signal 2
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software

27	P0_7	P0.7
	HALL_IN2	Hall interface input 2
	MCPWM_BKIN1	PWM break signal 1
	UART1_TXD	UART1 transmit(receive)
	SDA	I2C data
	TIM1_CH1	Timer1 channel1
	CAN_TX	CAN Transmit
	CMP2_IP0	Comparator2 positive input0
	FLT	IO filtering
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
28	P2_11	P2.11
	MCPWM_CH1P	PWM channel 1 high-side
	TIM2_CH0	Timer2 channel0
	CMP2_IP1	Comparator2 positive input1
29	P2_12	P2.12
	MCPWM_CH1N	PWM channel 1 low-side
	SPI_CS	SPI chip select
	TIM2_CH1	Timer2 channel1
	ADC_TRIGGER0	ADC0 trigger for debug
	CLUOUT3	CLU3 output
	EXTI6	External GPIO interrupt input signal 6
30	P0_11	P0.11
	HALL_IN0	Hall interface input 0
	TIM3_CH0	Timer3 channel0
	ADC1_CH11	ADC1 channel 11
	CMP0_IP1	Comparator0 positive input1
	FLT	IO filtering
	EXTI7	External GPIO interrupt input signal 7
	WK3	External wake-up signal 3
31	P0_12	P0.12
	HALL_IN1	Hall interface input 1
	TIM3_CH1	Timer3 channel1
	CAN_RX	CAN Receive
	ADC1_CH12	ADC1 channel 12
	CMP0_IP2	Comparator0 positive input2
	FLT	IO filtering
32	P0_13	P0.13
	HALL_IN2	Hall interface input 2
	QEP0_Z	QEP0 encoder Z phase
	CAN_TX	CAN Transmit
	ADC1_CH13	ADC1 channel 13
	CMP0_IP3	Comparator0 positive input3
	FLT	IO filtering

33	P0_14	P0.14
	CMP0_OUT	Comparator 0 output
	MCPWM_BKIN1	PWM break signal 1
	UART0_TXD	UART0 transmit(receive)
	SPI_CLK	SPI clock
	SCL	I2C clock
	TIM0_CH1	Timer0 channel1
	QEP1_Z	QEP1 encoder Z phase
	ADC_TRIGGER0	ADC0 trigger for debug
	SIF	Single line communication
	CLUOUT0	CLU0 output
	ADC0_CH10	ADC0 channel 10
	CMP0_IP4	Comparator0 positive input4
	FLT	IO filtering
	EXTI8	External GPIO interrupt input signal 8
	WK4	External wake-up signal 4
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
34	P0_15	P0.15
	CMP2_OUT	Comparator 2 output
	MCPWM_CH0P	PWM channel 0 high-side
	UART0_RXD	UART0 receive(transmit)
	SPI_DO	SPI data output(input)
	SDA	I2C data
	TIM0_CH0	Timer0 channel0
	ADC_TRIGGER1	ADC1 trigger for debug
	CMP0_IN	Comparator0 negative input
	FLT	IO filtering
	EXTI9	External GPIO interrupt input signal 9
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
35	P1_0	P1.0
	MCPWM_CH0N	PWM channel 0 low-side
	UART0_TXD	UART0 transmit(receive)
	SPI_DI	SPI data input(output)
	TIM0_BKIN	TIMER0_FAIL Signal from GPIO
	EXTI10	External GPIO interrupt input signal 10
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P1_3	P1.3
	TIM3_CH1	Timer3 channel1
	ADC01_CH5	ADC0/1 channel 5
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
36	P3_5	P3.5
	OPA0_IP	OPA0 positive input
37	P3_7	P3.7

	OPA0_IN	OPA0 negative input
38	P2_7	P2.7
	CLK0	Clock output for debug
	UART0_TXD	UART0 transmit(receive)
	TIM0_CH0	Timer0 channel0
	TIM3_CH1	Timer3 channel1
	ADC_TRIGGER1	ADC1 trigger for debug
	CAN_TX	CAN Transmit
	CLUOUT1	CLU1 output
	ADC0_CH11	ADC0 channel 11
	OPAx_OUT	OPA output
	LDO15	1.5V LDO output
	REF	Reference voltage output for debug
	EXTI11	External GPIO interrupt input signal 11
	WK6	External wake-up signal 6
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
39	GND	Chip ground. It is strongly recommended that multiple ground pins be grounded uniformly on the PCB.
40	AVDD/LDO	MCU power supply, 5V LDO output, it is recommended to place 1uF filter capacitor near the chip
41	VEM3	C phase VS 50k/3.3k cascaded resistor voltage divided output, built-in voltage 5V 30pF capacitor. The voltage ratio can be adjusted by adding external shunt resistor. If the voltage exceeds 5V, the sampled signal will be clamped by diode
42	VEM2	B phase VS 50k/3.3k cascaded resistor voltage divided output, built-in voltage 5V 30pF capacitor. The voltage ratio can be adjusted by adding external shunt resistor. If the voltage exceeds 5V, the sampled signal will be clamped by diode
43	VEM1	A phase VS 50k/3.3k cascaded resistor voltage divided output, built-in voltage 5V 30pF capacitor. The voltage ratio can be adjusted by adding external shunt resistor. If the voltage exceeds 5V, the sampled signal will be clamped by diode
44	PGND	Power ground
45	LO3	Phase C low-side output, worked by MCU P1.6; the polarity of LO3 is the same as that of P1.6, i.e. when P1.6 = 1, LO3 = 1. You need to set MCPWM_SWAP = 1.
46	LO2	Phase B low-side output, worked by MCU P1.5; the polarity of LO2 is the same as that of P1.5, i.e. when P1.5 = 1, LO2 = 1. You need to set MCPWM_SWAP = 1.
47	LO1	Phase A low-side output, worked by MCU P1.4; the polarity of LO1 is the same as that of P1.4, i.e. when P1.4 = 1, LO1 = 1. You need to set MCPWM_SWAP = 1.
48	VS1	High-side floating bias voltage 1.

3.1.4 LKS32MC074FF8Q8

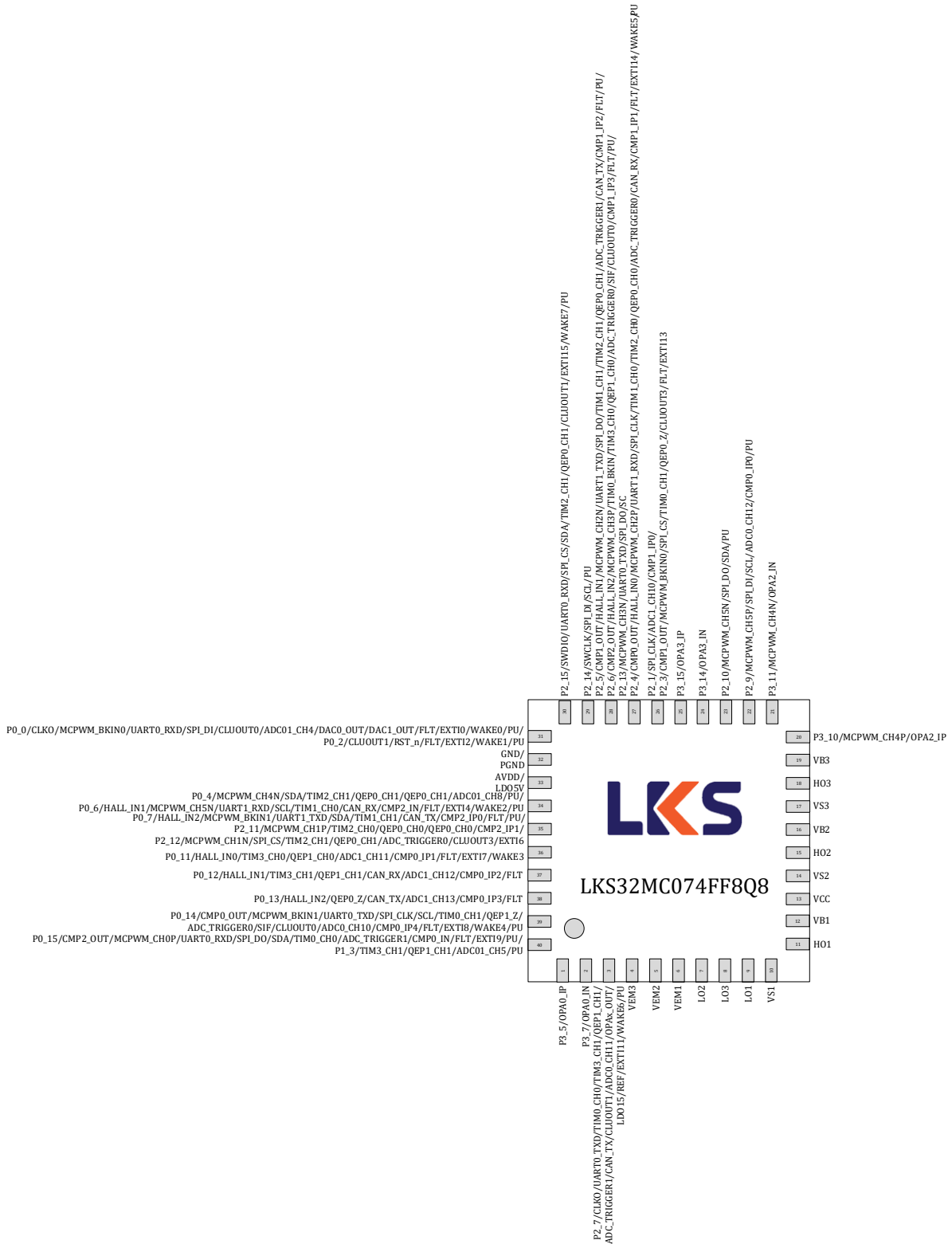


Fig.3-5 LKS32MC074FF8Q8 Pin Assignment

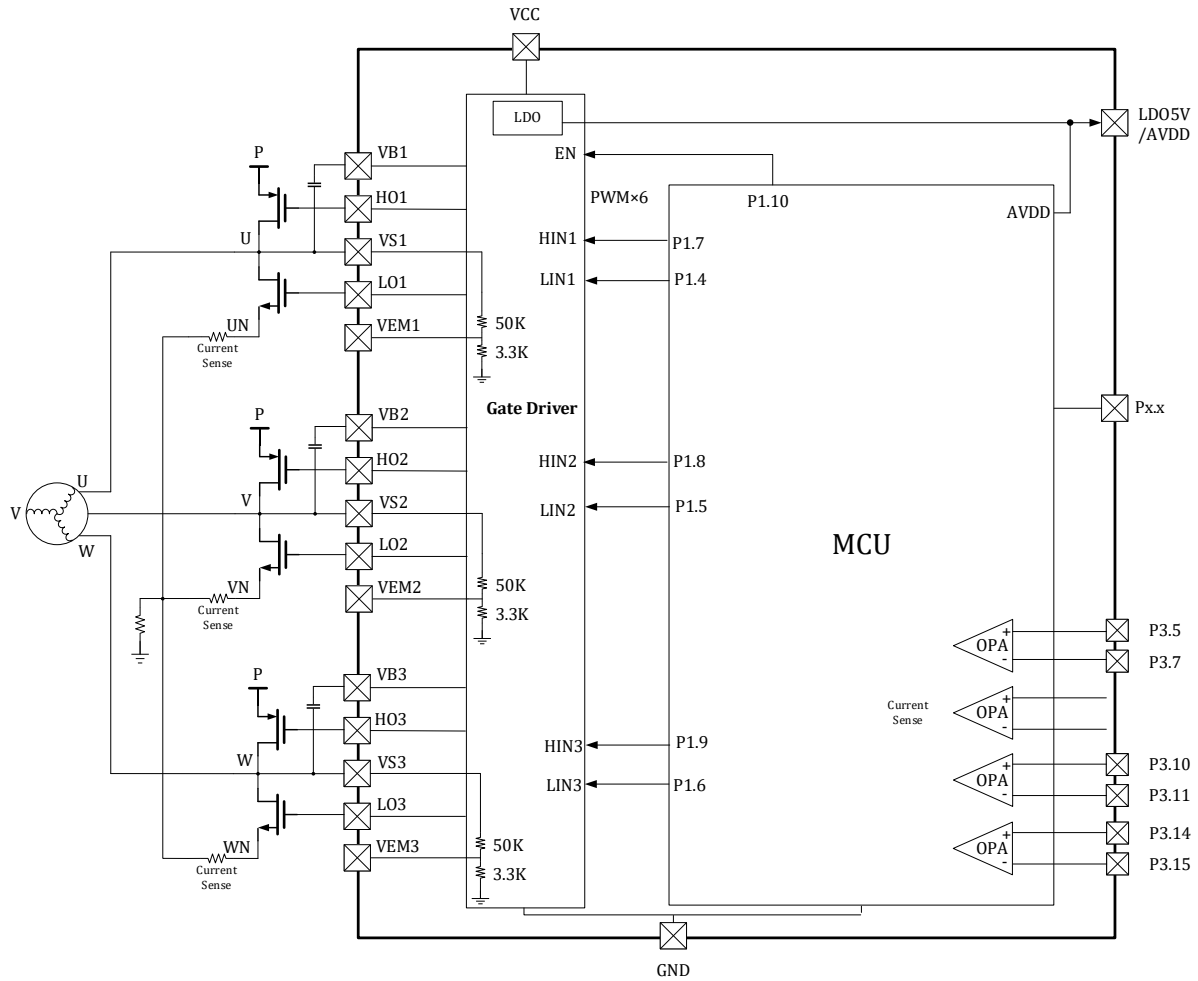


Fig.3-6 LKS32MC074FF8Q8 Schematic diagram of inner driver connection

Table 3-3 LKS32MC074FF8Q8 Pin Function Description

0	GND	Abdominal heat dissipation area, GND
1	P3_5	P3.5
	OPA0_IP	OPA0 positive input
2	P3_7	P3.7
	OPA0_IN	OPA0 negative input
3	P2_7	P2.7
	CLK0	Clock output for debug
	UART0_TXD	UART0 transmit(receive)
	TIM0_CH0	Timer0 channel0
	TIM3_CH1	Timer3 channel1
	QEP1_CH1	Encoder1 channel1
	ADC_TRIGGER1	ADC1 trigger for debug
	CAN_TX	CAN Transmit
	CLUOUT1	CLU1 output
	ADC0_CH11	ADC0 channel 11
	OPAx_OUT	OPA output
	LD015	1.5V LDO output

	REF	Reference voltage output for debug
	EXTI11	External GPIO interrupt input signal 11
	WAKE6	External wake-up signal 6
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
4	VEM3	Motor phase C 1:15 voltage divider
5	VEM2	Motor phase B 1:15 voltage divider
6	VEM1	Motor phase A 1:15 voltage divider
7	LO2	Phase B low-side output, worked by MCU P1.5; the polarity of LO2 is the same as that of P1.5, i.e. when P1.5 = 1, LO2 = 1. You need to set MCPWM_SWAP = 1.
8	LO3	Phase C low-side output, worked by MCU P1.6; the polarity of LO3 is the same as that of P1.6, i.e. when P1.6 = 1, LO3 = 1. You need to set MCPWM_SWAP = 1.
9	LO1	Phase A low-side output, worked by MCU P1.4; the polarity of LO1 is the same as that of P1.4, i.e. when P1.4 = 1, LO1 = 1. You need to set MCPWM_SWAP = 1.
10	VS1	High-side floating bias voltage 1.
11	HO1	Phase A high-side output, worked by MCU P1.7; the polarity of HO1 is the same as that of P1.7, i.e. when P1.7 = 1, HO1 = 1. You need to set MCPWM_SWAP = 1.
12	VB1	High-side floating supply voltage 1.
13	VCC	Gate driver power supply
14	VS2	High-side floating bias voltage 2.
15	HO2	Phase B high-side output, worked by MCU P1.8; the polarity of HO2 is the same as that of P1.8, i.e. when P1.8 = 1, HO2 = 1. You need to set MCPWM_SWAP = 1.
16	VB2	High-side floating supply voltage 2.
17	VS3	High-side floating bias voltage 3.
18	HO3	Phase C high-side output, worked by MCU P1.9; the polarity of HO3 is the same as that of P1.9, i.e. when P1.9 = 1, HO3 = 1. You need to set MCPWM_SWAP = 1.
19	VB3	High-side floating supply voltage 3.
20	P3_10	P3.10
	MCPWM_CH4P	PWM channel 4 high-side
	OPA2_IP	OPA2 positive input
21	P3_11	P3.11
	MCPWM_CH4N	PWM channel 4 low-side
	OPA2_IN	OPA2 negative input
22	P2_9	P2.9
	MCPWM_CH5P	PWM channel 5 high-side
	SPI_DI	SPI data input(output)
	SCL	I2C clock
	ADC0_CH12	ADC0 channel 12
	CMP0_IP0	Comparator0 positive input0
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
23	P2_10	P2.10
	MCPWM_CH5N	PWM channel 5 low-side
	SPI_DO	SPI data output(input)
	SDA	I2C data

	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
24	P3_14	P3.14
	OPA3_IN	OPA3 negative input
25	P3_15	P3.15
	OPA3_IP	OPA3 positive input
26	P2_1	P2.1
	SPI_CLK	SPI clock
	ADC1_CH10	ADC1 channel 10
	CMP1_IP0	Comparator1 positive input0
	P2_3	P2.3
	CMP1_OUT	Comparator 1 output
	MCPWM_BKIN0	PWM break signal 0
	SPI_CS	SPI chip select
	TIM0_CH1	Timer0 channel1
	QEP0_Z	QEP0 encoder Z phase
	CLUOUT3	CLU3 output
	FLT	IO filter
	EXTI13	External GPIO interrupt input signal 13
27	P2_4	P2.4
	CMP0_OUT	Comparator 0 output
	HALL_IN0	Hall interface input 0
	MCPWM_CH2P	PWM channel 2 high-side
	UART1_RXD	UART1 receive(transmit)
	SPI_CLK	SPI clock
	TIM1_CH0	Timer1 channel0
	TIM2_CH0	Timer2 channel0
	QEP0_CH0	Encoder0 channel0
	ADC_TRIGGER0	ADC0 trigger for debug
	CAN_RX	CAN Receive
	CMP1_IP1	Comparator1 positive input1
	FLT	IO filter
	EXTI14	External GPIO interrupt input signal 14
	WAKE5	External wake-up signal 5
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
28	P2_5	P2.5
	CMP1_OUT	Comparator 1 output
	HALL_IN1	Hall interface input 1
	MCPWM_CH2N	PWM channel 2 low-side
	UART1_TXD	UART1 transmit(receive)
	SPI_DO	SPI data output(input)
	TIM1_CH1	Timer1 channel1
	TIM2_CH1	Timer2 channel1
	QEP0_CH1	Encoder0 channel1

	ADC_TRIGGER1	ADC1 trigger for debug
	CAN_TX	CAN Transmit
	CMP1_IP2	Comparator1 positive input2
	FLT	IO filter
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P2_6	P2.6
	CMP2_OUT	Comparator 2 output
	HALL_IN2	Hall interface input 2
	MCPWM_CH3P	PWM channel 3 high-side
	TIM0_BKIN	
	TIM3_CH0	Timer3 channel0
	QEP1_CH0	Encoder1 channel0
	ADC_TRIGGER0	ADC0 trigger for debug
	SIF	
	CLUOUT0	CLU0 output
	CMP1_IP3	Comparator1 positive input3
	FLT	IO filter
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P2_13	P2.13
	MCPWM_CH3N	PWM channel 3 low-side
	UART0_TXD	UART0 transmit(receive)
	SPI_DO	SPI data output(input)
	SCL	I2C clock
	TIM3_CH1	Timer3 channel1
	QEP1_CH1	Encoder1 channel1
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
29	P2_14	P2.14
	SWCLK	SWD Clock
	SPI_DI	SPI data input(output)
	SCL	I2C clock
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
30	P2_15	P2.15
	SWDIO	SWD Data
	UART0_RXD	UART0 receive(transmit)
	SPI_CS	SPI chip select
	SDA	I2C data
	TIM2_CH1	Timer2 channel1
	QEP0_CH1	Encoder0 channel1
	CLUOUT1	CLU1 output
	EXTI15	External GPIO interrupt input signal 15
	WAKE7	External wake-up signal 7
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
31	P0_0	P0.0

	CLKO	Clock output for debug
	MCPWM_BKIN0	PWM break signal 0
	UART0_RXD	UART0 receive(transmit)
	SPI_DI	SPI data input(output)
	CLUOUT0	CLU0 output
	ADC01_CH4	ADC0/1 channel 4
	DAC0_OUT	DAC0 out put
	DAC1_OUT	DAC1 out put
	FLT	IO filter
	EXTI0	External GPIO interrupt input signal 0
	WAKE0	External wake-up signal 0
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P0_2	P0.2
	CLUOUT1	CLU1 output
	RST_n	P0.2 is used as RSTN by default. A 10nF-100nF capacitor should be connected to the ground. It is recommended a 10k-20k pull-up resistor is placed between RSTN and AVDD on PCB. If there is an external pull-up resistor, the capacitance of RSTN should be 100nF. The built-in 10kΩ pull-up resistor could be turned-off by software.
	FLT	IO filter
	EXTI2	External GPIO interrupt input signal 2
	WAKE1	External wake-up signal 1
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
32	GND	Ground
	PGND	Power ground
33	AVDD	Power supply, 2.2~5.5V
	LDO5V	5V LDO output
34	P0_4	P0.4
	MCPWM_CH4N	PWM channel 4 low-side
	SDA	I2C data
	TIM2_CH1	Timer2 channel1
	QEPO_CH1	Encoder0 channel1
	QEPO_CH1	Encoder0 channel1
	ADC01_CH8	ADC0/1 channel 8
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P0_6	P0.6
	HALL_IN1	Hall interface input 1
	MCPWM_CH5N	PWM channel 5 low-side
	UART1_RXD	UART1 receive(transmit)
	SCL	I2C clock
	TIM1_CH0	Timer1 channel0
	CAN_RX	CAN Receive
	CMP2_IN	Comparator2 negative input
	FLT	IO filter

	EXTI4	External GPIO interrupt input signal 4
	WAKE2	External wake-up signal 2
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
35	P0_7	P0.7
	HALL_IN2	Hall interface input 2
	MCPWM_BKIN1	PWM break signal 1
	UART1_TXD	UART1 transmit(receive)
	SDA	I2C data
	TIM1_CH1	Timer1 channel1
	CAN_TX	CAN Transmit
	CMP2_IP0	Comparator2 positive input0
	FLT	IO filter
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P2_11	P2.11
	MCPWM_CH1P	PWM channel 1 high-side
	TIM2_CH0	Timer2 channel0
	QEP0_CH0	Encoder0 channel0
	CMP2_IP1	Comparator2 positive input1
	P2_12	P2.12
	MCPWM_CH1N	PWM channel 1 low-side
	SPI_CS	SPI chip select
	TIM2_CH1	Timer2 channel1
	QEP0_CH1	Encoder0 channel1
	ADC_TRIGGER0	ADC0 trigger for debug
	CLUOUT3	CLU3 output
	EXTI6	External GPIO interrupt input signal 6
36	P0_11	P0.11
	HALL_IN0	Hall interface input 0
	TIM3_CH0	Timer3 channel0
	QEP1_CH0	Encoder1 channel0
	ADC1_CH11	ADC1 channel 11
	CMP0_IP1	Comparator0 positive input1
	FLT	IO filter
	EXTI7	External GPIO interrupt input signal 7
	WAKE3	External wake-up signal 3
37	P0_12	P0.12
	HALL_IN1	Hall interface input 1
	TIM3_CH1	Timer3 channel1
	QEP1_CH1	Encoder1 channel1
	CAN_RX	CAN Receive
	ADC1_CH12	ADC1 channel 12
	CMP0_IP2	Comparator0 positive input2
	FLT	IO filter

38	P0_13	P0.13
	HALL_IN2	Hall interface input 2
	QEP0_Z	QEP0 encoder Z phase
	CAN_TX	CAN Transmit
	ADC1_CH13	ADC1 channel 13
	CMP0_IP3	Comparator0 positive input3
	FLT	IO filter
39	P0_14	P0.14
	CMP0_OUT	Comparator 0 output
	MCPWM_BKIN1	PWM break signal 1
	UART0_TXD	UART0 transmit(receive)
	SPI_CLK	SPI clock
	SCL	I2C clock
	TIM0_CH1	Timer0 channel1
	QEP1_Z	QEP1 encoder Z phase
	ADC_TRIGGER0	ADC0 trigger for debug
	SIF	
	CLUOUT0	CLU0 output
	ADC0_CH10	ADC0 channel 10
	CMP0_IP4	Comparator0 positive input4
	FLT	IO filter
	EXTI8	External GPIO interrupt input signal 8
	WAKE4	External wake-up signal 4
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
40	P0_15	P0.15
	CMP2_OUT	Comparator 2 output
	MCPWM_CH0P	PWM channel 0 high-side
	UART0_RXD	UART0 receive(transmit)
	SPI_DO	SPI data output(input)
	SDA	I2C data
	TIM0_CH0	Timer0 channel0
	ADC_TRIGGER1	ADC1 trigger for debug
	CMP0_IN	Comparator0 negative input
	FLT	IO filter
	EXTI9	External GPIO interrupt input signal 9
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P1_3	P1.3
	TIM3_CH1	Timer3 channel1
	QEP1_CH1	Encoder1 channel1
	ADC01_CH5	ADC0/1 channel 5
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software

3.1.5 LKS32MC074DF8Q8

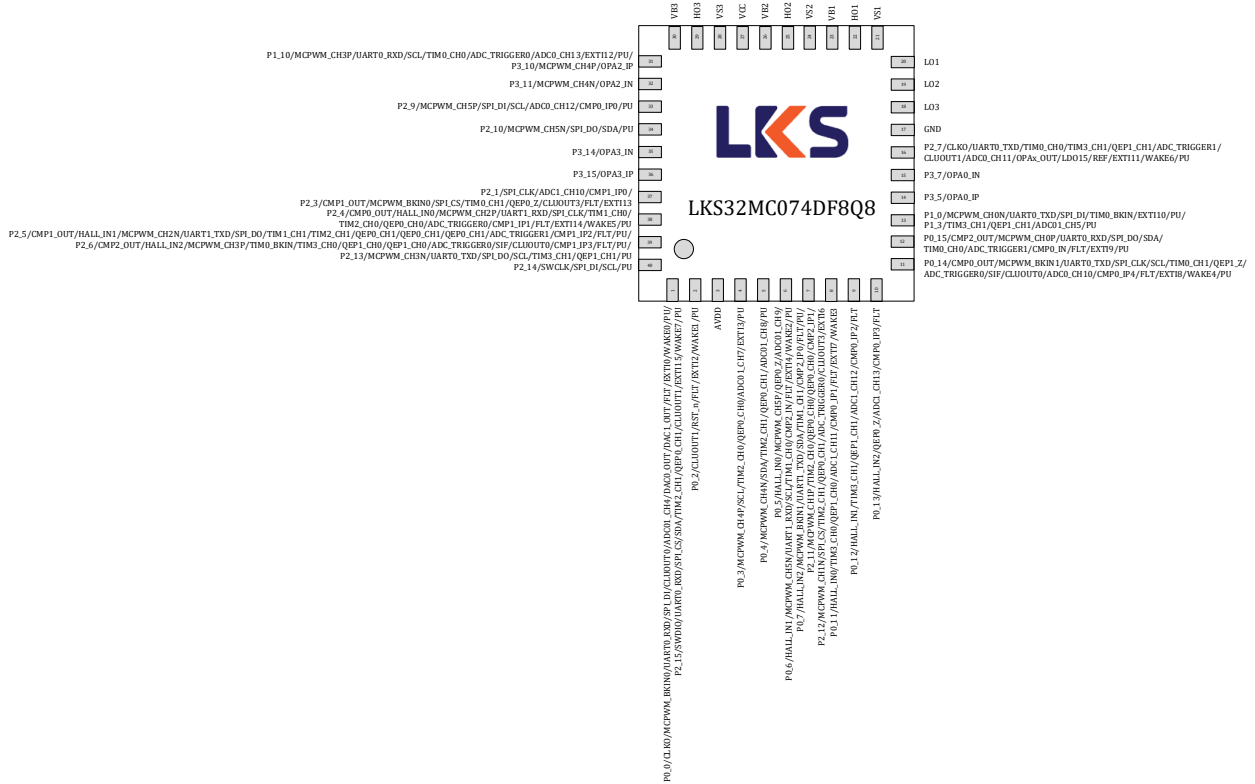


Fig.3-7 LKS32MC074DF8Q8 Pin Assignment

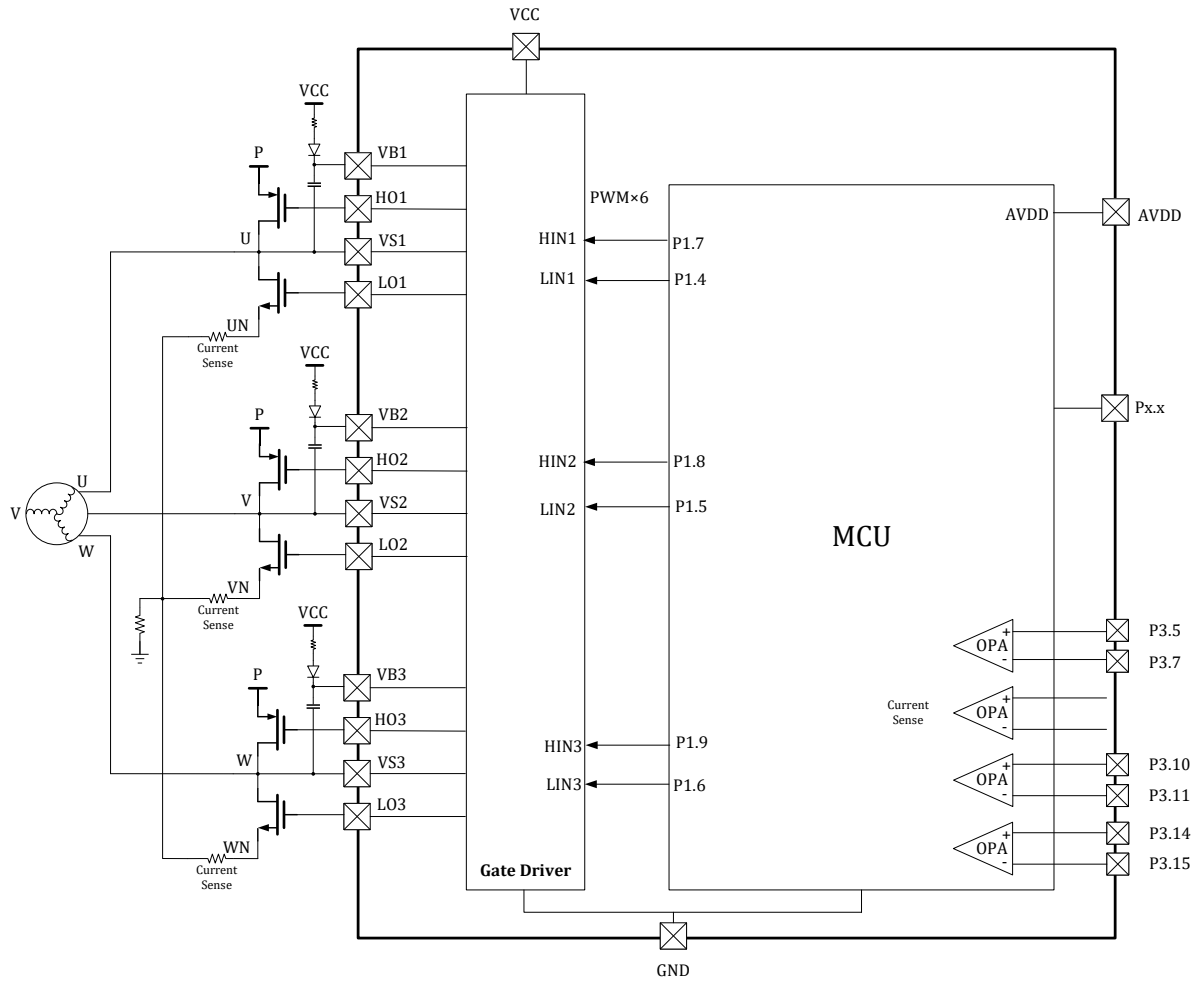


Fig.3-8 LKS32MC074DF8Q8 Schematic diagram of inner driver connection

Table 3-4 LKS32MC074DF8Q8 Pin Function Description

0	GND	In the heat dissipation area of the abdomen, Pad is the chip GND
1	P0_0	P0.0
	CLKO	Clock output (for debugging)
	MCPWM_BKIN0	PWM shutdown input signal 0
	UART0_RXD	Serial port 0 receive (send)
	SPI_DI	SPI Data In (Out)
	CLUOUT0	CLU0 output
	ADC01_CH4	ADC 0/ADC1 Channel 4
	DAC0_OUT	DAC0 output
	DAC1_OUT	DAC1 Output
	FLT	IO filtering
	EXTI0	External GPIO Interrupt Signal 0
	WK0	External wake-up signal 0
	PU	Built-in 10kΩ pull-up resistor, software switchable
	P2_15	P2.15
	SWDIO	SWD data
	UART0_RXD	Serial port 0 receive (send)

	SPI_CS	SPI chip select
	SDA	I2C data
	TIM2_CH1	Timer2 channel 1
	CLUOUT1	CLU1 output
	EXTI15	External GPIO Interrupt 15
	WK7	External wake-up signal 7
	PU	Built-in 10kΩ pull-up resistor, software switchable
2	P0_2	P0.2
	CLUOUT1	CLU1 output
	RST_n	Reset pin, P0.2 used as RSTN by default. It is recommended to connect a 10 nF to 100 nF capacitor to ground and place a 10 K to 20 K pull-up resistor between RSTN and AVDD. If there is an external pull-up resistor, the capacitance of RSTN should be 100 nF. P0.2 can be switched as a GPIO, which turns off the 10 kΩ pull-up resistor.
	FLT	IO filtering
	EXTI2	External GPIO Interrupt Signal 2
	WK1	External wake-up signal 1
	PU	Built-in 10kΩ pull-up resistor, software switchable
3	AVDD	Chip power supply, power supply range 2.5 ~ 5.5V
4	P0_3	P0.3
	MCPWM_CH4P	PWM Channel 4 High Side
	SCL	I2C clock
	TIM2_CH0	Timer2 channel 0
	ADC01_CH7	ADC0/ADC1 Channel 7
	EXTI3	External GPIO Interrupt Signal 3
	PU	Built-in 10kΩ pull-up resistor, software switchable
5	P0_4	P0.4
	MCPWM_CH4N	PWM Channel 4 Low Side
	SDA	I2C data
	TIM2_CH1	Timer2 channel 1
	ADC01_CH8	ADC0/ADC1 Channel 8
	PU	Built-in 10kΩ pull-up resistor, software switchable
6	P0_5	P0.5
	HALL_IN0	Hall interface input 0
	MCPWM_CH5P	PWM channel 5 high-side
	QEP0_Z	QEP0 encoder Z phase
	ADC01_CH9	ADC0/1 channel 9
	P0_6	P0.6
	HALL_IN1	HALL interface input 1
	MCPWM_CH5N	PWM Channel 5 Low Side
	UART1_RXD	Serial port 1 receive (send)
	SCL	I2C clock
	TIM1_CH0	Timer1 channel 0
	CMP2_IN	Comparator 2 Negative Terminal Input

	FLT	IO filtering
	EXTI4	External GPIO Interrupt 4
	WK2	External wake-up signal 2
	PU	Built-in 10kΩ pull-up resistor, software switchable
7	P0_7	P0.7
	HALL_IN2	HALL interface input 2
	MCPWM_BKIN1	PWM Shutdown Input Signal 1
	UART1_TXD	Serial port 1 send (receive)
	SDA	I2C data
	TIM1_CH1	Timer1 channel 1
	CMP2_IP0	Positive input 0 of comparator 2
	FLT	IO filtering
	PU	Built-in 10kΩ pull-up resistor, software switchable
	P2_11	P2.11
	MCPWM_CH1P	PWM Channel 1 High Side
	TIM2_CH0	Timer2 channel 0
	CMP2_IP1	Positive Input 1 of Comparator 2
	P2_12	P2.12
	MCPWM_CH1N	PWM Channel 1 Low Side
	SPI_CS	SPI chip select
	TIM2_CH1	Timer2 channel 1
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	CLUOUT3	CLU3 output
	EXTI6	External GPIO Interrupt 6
8	P0_11	P0.11
	HALL_IN0	HALL interface input 0
	TIM3_CH0	Timer3 channel 0
	ADC1_CH11	ADC1 Channel 11
	CMP0_IP1	Comparator 0 positive input 1
	FLT	IO filtering
	EXTI7	External GPIO Interrupt Signal 7
	WK3	External wake-up signal 3
9	P0_12	P0.12
	HALL_IN1	HALL interface input 1
	TIM3_CH1	Timer3 channel 1
	ADC1_CH12	ADC1 Channel 12
	CMP0_IP2	Comparator 0 positive input 2
	FLT	IO filtering
10	P0_13	P0.13
	HALL_IN2	HALL interface input 2
	QEP0_Z	QEP0 Encoder Phase Z
	ADC1_CH13	ADC1 Channel 13
	CMP0_IP3	Comparator 0 positive input 3

	FLT	IO filtering
11	P0_14	P0.14
	CMP0_OUT	Comparator 0 Output
	MCPWM_BKIN1	PWM Shutdown Input Signal 1
	UART0_TXD	Serial port 0 send (receive)
	SPI_CLK	SPI clock
	SCL	I2C clock
	TIM0_CH1	Timer0 channel 1
	QEP1_Z	Phase Z of QEP1 encoder
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	SIF	Single line communication
	CLUOUT0	CLU0 output
	ADC0_CH10	ADC0 Channel 10
	CMP0_IP4	Comparator 0 positive input 4
	FLT	IO filtering
	EXTI8	External GPIO Interrupt Signal 8
	WK4	External wake-up signal 4
	PU	Built-in 10kΩ pull-up resistor, software can be turned off
12	P0_15	P0.15
	CMP2_OUT	Comparator 2 Output
	MCPWM_CH0P	PWM Channel 0 High Side
	UART0_RXD	Serial port 0 receive (send)
	SPI_DO	SPI Data Output (Input)
	SDA	I2C data
	TIM0_CH0	Timer0 channel 0
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	CMP0_IN	Comparator 0 negative input
	FLT	IO filtering
	EXTI9	External GPIO Interrupt 9
	PU	Built-in 10kΩ pull-up resistor, software switchable
13	P1_0	P1.0
	MCPWM_CH0N	PWM Channel 0 Low Side
	UART0_TXD	Serial port 0 send (receive)
	SPI_DI	SPI Data In (Out)
	TIM0_BKIN	TIMER0_FAIL signal from GPIO
	EXTI10	External GPIO Interrupt Signal 10
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P1_3	P1.3
	TIM3_CH1	Timer3 channel 1
	ADC01_CH5	ADC0/1 channel 5
	PU	Built-in 10kΩ pull-up resistor, software switchable
14	P3_5	P3.5
	OPA0_IP	Positive terminal input of operational amplifier 0

15	P3_7	P3.7
	OPA0_IN	Input of negative terminal of operational amplifier 0
16	P2_7	P2.7
	CLK0	Clock output (for debugging)
	UART0_TXD	Serial port 0 send (receive)
	TIM0_CH0	Timer0 channel 0
	TIM3_CH1	Timer3 channel 1
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	CLUOUT1	CLU1 output
	ADC0_CH11	ADC0 Channel 11
	OPAx_OUT	Op Amp Output
	LDO15	1.5V LDO Output
	REF	Reference Voltage
	EXTI11	External GPIO Interrupt Signal 11
	WK6	External wake-up signal 6
	PU	Built-in 10kΩ pull-up resistor; software switchable
17	GND	Chip ground. It is strongly recommended that multiple ground pins be grounded uniformly on the PCB.
18	LO3	Phase A low-side output, controlled by MCU P1.6, LO3 polarity is the same as P1.6, that is, when P1.6 = 1, LO3 = 1. PWM _ SWAP = 1 needs to be set.
19	LO2	Phase B low-side output, controlled by MCU P1.5, LO2 polarity is the same as P1.5, that is, when P1.5 = 1, LO2 = 1. PWM _ SWAP = 1 needs to be set.
20	LO1	Phase C low-side output, controlled by MCU P1.4, LO1 polarity is the same as P1.4, that is, when P1.4 = 1, LO1 = 1. PWM _ SWAP = 1 needs to be set.
21	VS1	High-side floating bias voltage 1
22	HO1	Phase C high-side output is controlled by MCU P1.7. The polarity of HO1 is the same as P1.9, that is, when P1.7 = 1, HO1 = 1. PWM _ SWAP = 1 needs to be set.
23	VB1	High-Side Float Supply Voltage 1
24	VS2	High-side floating bias voltage 2.
25	HO2	Phase B high-side output is controlled by MCU P1.8. The polarity of HO2 is the same as P1.8. That is, when P1.8 = 1, HO2 = 1. PWM _ SWAP = 1 needs to be set.
26	VB2	High-side floating supply voltage 2.
27	VCC	Full-bridge drive power supply
28	VS3	High-side floating bias voltage 3
29	HO3	Phase A high-side output is controlled by MCU P1.9, and the polarity of HO3 is the same as P1.9, that is, when P1.9 = 1, HO3 = 1. PWM _ SWAP = 1 needs to be set.
30	VB3	High-side floating supply voltage 3
31	P1_10	P1.10
	MCPWM_CH3P	PWM channel 3 high-side
	UART0_RXD	UART0 receive(transmit)
	SCL	I2C clock
	TIM0_CH0	Timer0 channel0
	ADC_TRIGGER0	ADC0 trigger for debug

	ADC0_CH13	ADC0 channel 13
	EXTI12	External GPIO interrupt input signal 12
	PU	Built-in 10kΩ Pull-up resistor which could be turn-off by software
	P3_10	P3.10
	MCPWM_CH4P	PWM Channel 4 High Side
	OPA2_IP	Positive input of operational amplifier 2
32	P3_11	P3.11
	MCPWM_CH4N	PWM Channel 4 Low Side
	OPA2_IN	Op Amp 2 Negative Input
33	P2_9	P2.9
	MCPWM_CH5P	PWM Channel 5 High Side
	SPI_DI	SPI Data In (Out)
	SCL	I2C clock
	ADC0_CH12	ADC0 Channel 12
	CMP0_IP0	Comparator 0 positive input 0
	PU	Built-in 10kΩ pull-up resistor; software switchable
34	P2_10	P2.10
	MCPWM_CH5N	PWM Channel 5 Low Side
	SPI_DO	SPI Data Output (Input)
	SDA	I2C data
	PU	Built-in 10kΩ pull-up resistor; software switchable
35	P3_14	P3.14
	OPA3_IN	Op Amp 3 Negative Input
36	P3_15	P3.15
	OPA3_IP	Positive input of operational amplifier 3
37	P2_1	P2.1
	SPI_CLK	SPI clock
	ADC1_CH10	ADC1 channel 10
	CMP1_IP0	Comparator1 positive input0
	P2_3	P2.3
	CMP1_OUT	Comparator 1 Output
	MCPWM_BKIN0	PWM shutdown input signal 0
	SPI_CS	SPI chip select
	TIM0_CH1	Timer0 channel 1
	QEP0_Z	QEP0 Encoder Phase Z
	CLUOUT3	CLU3 output
	FLT	IO filtering
	EXTI13	External GPIO Interrupt Signal 13
38	P2_4	P2.4
	CMP0_OUT	Comparator 0 Output
	HALL_IN0	HALL interface input 0
	MCPWM_CH2P	PWM Channel 2 High Side
	UART1_RXD	Serial port 1 receive (send)

	SPI_CLK	SPI clock
	TIM1_CH0	Timer1 channel 0
	TIM2_CH0	Timer2 channel 0
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	CMP1_IP1	Comparator 1 positive input 1
	FLT	IO filtering
	EXTI14	External GPIO Interrupt Signal 14
	WK5	External wake-up signal 5
	PU	Built-in 10kΩ pull-up resistor, software switchable
39	P2_5	P2.5
	CMP1_OUT	Comparator 1 Output
	HALL_IN1	HALL interface input 1
	MCPWM_CH2N	PWM Channel 2 Low Side
	UART1_TXD	Serial port 1 send (receive)
	SPI_DO	SPI Data Output (Input)
	TIM1_CH1	Timer1 channel 1
	TIM2_CH1	Timer2 channel 1
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	CMP1_IP2	Comparator 1 positive input 2
	FLT	IO filtering
	PU	Built-in 10kΩ pull-up resistor, software switchable
	P2_6	P2.6
	CMP2_OUT	Comparator 2 Output
	HALL_IN2	HALL interface input 2
	MCPWM_CH3P	PWM Channel 3 High-Side
	TIM0_BKIN	TIMER0_FAIL signal from GPIO
	TIM3_CH0	Timer3 channel 0
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	SIF	Single line communication
	CLUOUT0	CLU0 output
	CMP1_IP3	Comparator 1 positive input 3
	FLT	IO filtering
	PU	Built-in 10kΩ pull-up resistor, software switchable
	P2_13	P2.13
	MCPWM_CH3N	PWM Channel 3 Low Side
	UART0_TXD	Serial port 0 send (receive)
	SPI_DO	SPI Data Output (Input)
	SCL	I2C clock
	TIM3_CH1	Timer3 channel 1
	PU	Built-in 10kΩ pull-up resistor, software switchable
40	P2_14	P2.14
	SWCLK	SWD clock
	SPI_DI	SPI Data In (Out)

	SCL	I2C clock
	PU	Built-in 10kΩ pull-up resistor, software switchable

3.1.6 LKS32MC074DOF8Q8

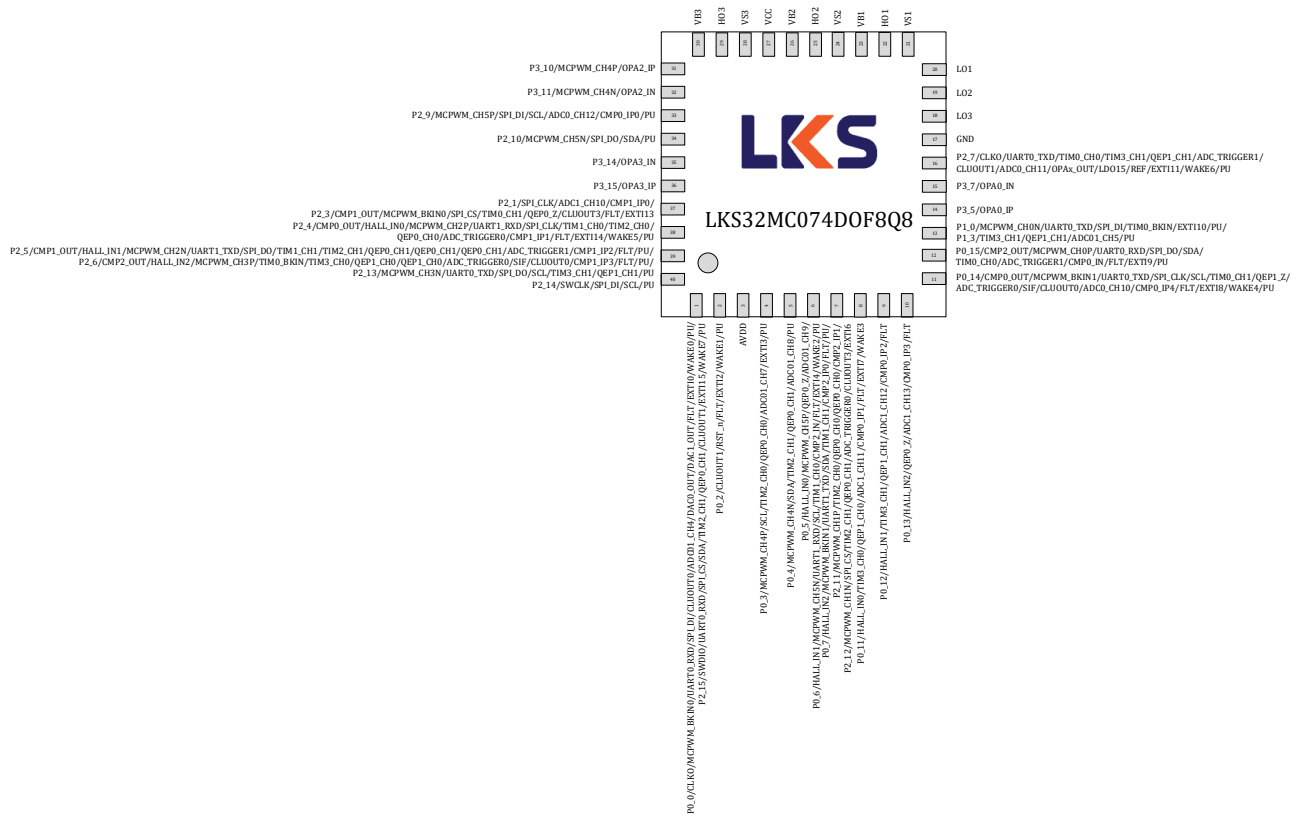


Fig.3-9 LKS32MC074DOF8Q8 Pin Assignment

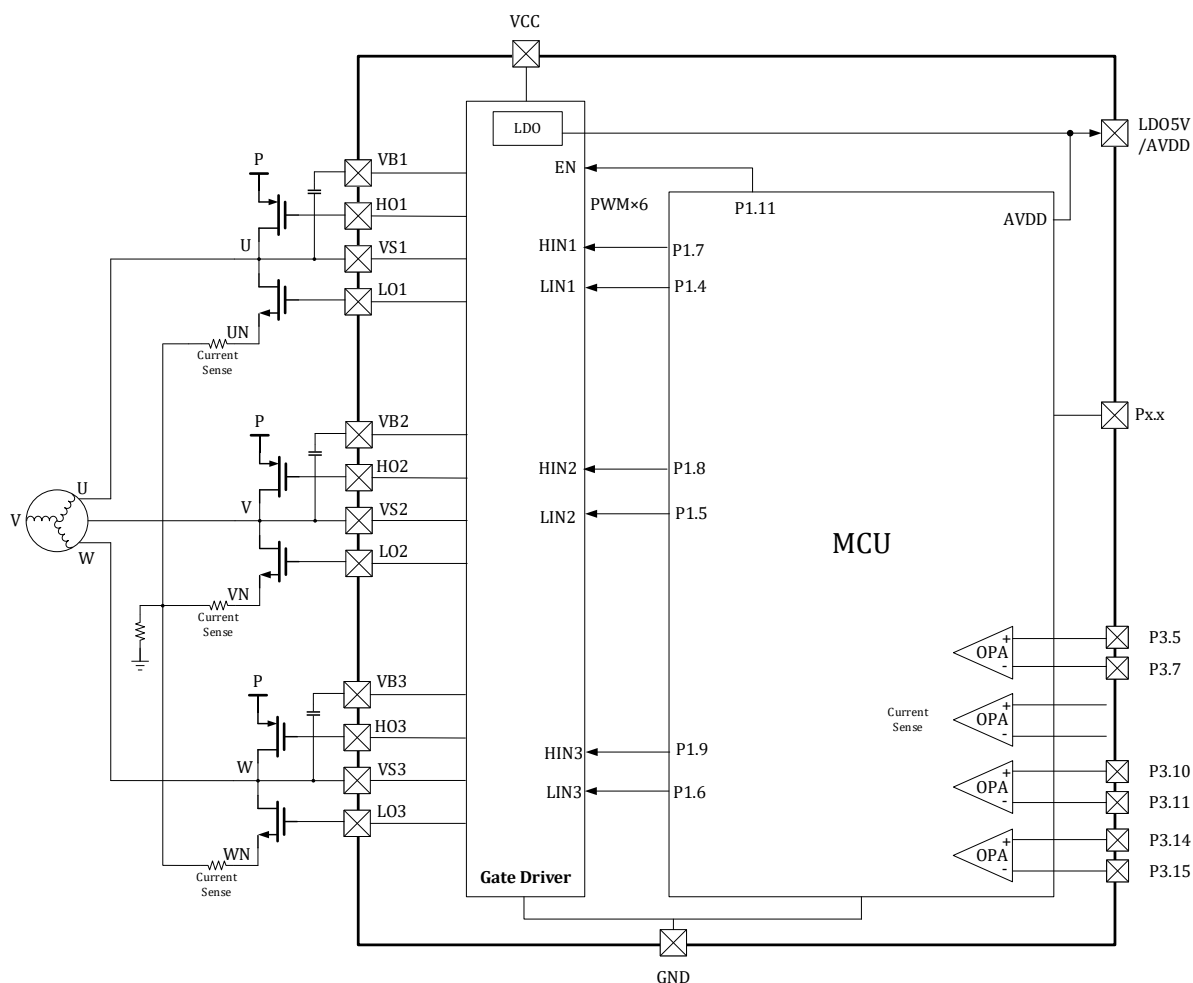


Fig.3-10 LKS32MC074DOF8Q8 Schematic diagram of inner driver connection

Table 3-5 LKS32MC074DOF8Q8 Pin Function Description

0	GND	In the heat dissipation area of the abdomen, Pad is the chip GND
1	P0_0	P0.0
	CLK0	Clock output (for debugging)
	MCPWM_BKIN0	PWM shutdown input signal 0
	UART0_RXD	Serial port 0 receive (send)
	SPI_DI	SPI Data In (Out)
	CLUOUT0	CLU0 output
	ADC01_CH4	ADC 0/ADC1 Channel 4
	DAC0_OUT	DAC0 output
	DAC1_OUT	DAC1 Output
	FLT	IO filtering
	EXTI0	External GPIO Interrupt Signal 0
	WK0	External wake-up signal 0
	PU	Built-in 10kΩ pull-up resistor, software switchable
	P2_15	P2.15
	SWDIO	SWD data
UART0_RXD	Serial port 0 receive (send)	

	SPI_CS	SPI chip select
	SDA	I2C data
	TIM2_CH1	Timer2 channel 1
	CLUOUT1	CLU1 output
	EXTI15	External GPIO Interrupt 15
	WK7	External wake-up signal 7
	PU	Built-in 10kΩ pull-up resistor, software switchable
2	P0_2	P0.2
	CLUOUT1	CLU1 output
	RST_n	Reset pin, P0.2 used as RSTN by default. It is recommended to connect a 10 nF to 100 nF capacitor to ground and place a 10 K to 20 K pull-up resistor between RSTN and AVDD. If there is an external pull-up resistor, the capacitance of RSTN should be 100 nF. P0.2 can be switched as a GPIO, which turns off the 10 kΩ pull-up resistor.
	FLT	IO filtering
	EXTI2	External GPIO Interrupt Signal 2
	WK1	External wake-up signal 1
	PU	Built-in 10kΩ pull-up resistor, software switchable
3	AVDD/LDO	MCU power supply, 5V LDO output, it is recommended to place 1uF filter capacitor near the chip
4	P0_3	P0.3
	MCPWM_CH4P	PWM Channel 4 High Side
	SCL	I2C clock
	TIM2_CH0	Timer2 channel 0
	ADC01_CH7	ADC0/ADC1 Channel 7
	EXTI3	External GPIO Interrupt Signal 3
	PU	Built-in 10kΩ pull-up resistor, software switchable
5	P0_4	P0.4
	MCPWM_CH4N	PWM Channel 4 Low Side
	SDA	I2C data
	TIM2_CH1	Timer2 channel 1
	ADC01_CH8	ADC0/ADC1 Channel 8
	PU	Built-in 10kΩ pull-up resistor, software switchable
6	P0_5	P0.5
	HALL_IN0	Hall interface input 0
	MCPWM_CH5P	PWM channel 5 high-side
	QEP0_Z	QEP0 encoder Z phase
	ADC01_CH9	ADC0/1 channel 9
	P0_6	P0.6
	HALL_IN1	HALL interface input 1
	MCPWM_CH5N	PWM Channel 5 Low Side
	UART1_RXD	Serial port 1 receive (send)
	SCL	I2C clock
	TIM1_CH0	Timer1 channel 0

	CMP2_IN	Comparator 2 Negative Terminal Input
	FLT	IO filtering
	EXTI4	External GPIO Interrupt 4
	WK2	External wake-up signal 2
	PU	Built-in 10kΩ pull-up resistor, software switchable
7	P0_7	P0.7
	HALL_IN2	HALL interface input 2
	MCPWM_BKIN1	PWM Shutdown Input Signal 1
	UART1_TXD	Serial port 1 send (receive)
	SDA	I2C data
	TIM1_CH1	Timer1 channel 1
	CMP2_IP0	Positive input 0 of comparator 2
	FLT	IO filtering
	PU	Built-in 10kΩ pull-up resistor, software switchable
	P2_11	P2.11
	MCPWM_CH1P	PWM Channel 1 High Side
	TIM2_CH0	Timer2 channel 0
	CMP2_IP1	Positive Input 1 of Comparator 2
	P2_12	P2.12
	MCPWM_CH1N	PWM Channel 1 Low Side
	SPI_CS	SPI chip select
	TIM2_CH1	Timer2 channel 1
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	CLUOUT3	CLU3 output
	EXTI6	External GPIO Interrupt 6
8	P0_11	P0.11
	HALL_IN0	HALL interface input 0
	TIM3_CH0	Timer3 channel 0
	ADC1_CH11	ADC1 Channel 11
	CMP0_IP1	Comparator 0 positive input 1
	FLT	IO filtering
	EXTI7	External GPIO Interrupt Signal 7
	WK3	External wake-up signal 3
9	P0_12	P0.12
	HALL_IN1	HALL interface input 1
	TIM3_CH1	Timer3 channel 1
	ADC1_CH12	ADC1 Channel 12
	CMP0_IP2	Comparator 0 positive input 2
	FLT	IO filtering
10	P0_13	P0.13
	HALL_IN2	HALL interface input 2
	QEP0_Z	QEP0 Encoder Phase Z
	ADC1_CH13	ADC1 Channel 13

	CMP0_IP3	Comparator 0 positive input 3
	FLT	IO filtering
11	P0_14	P0.14
	CMP0_OUT	Comparator 0 Output
	MCPWM_BKIN1	PWM Shutdown Input Signal 1
	UART0_TXD	Serial port 0 send (receive)
	SPI_CLK	SPI clock
	SCL	I2C clock
	TIM0_CH1	Timer0 channel 1
	QEP1_Z	Phase Z of QEP1 encoder
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	SIF	Single line communication
	CLUOUT0	CLU0 output
	ADC0_CH10	ADC0 Channel 10
	CMP0_IP4	Comparator 0 positive input 4
	FLT	IO filtering
	EXTI8	External GPIO Interrupt Signal 8
	WK4	External wake-up signal 4
	PU	Built-in 10kΩ pull-up resistor; software can be turned off
12	P0_15	P0.15
	CMP2_OUT	Comparator 2 Output
	MCPWM_CH0P	PWM Channel 0 High Side
	UART0_RXD	Serial port 0 receive (send)
	SPI_DO	SPI Data Output (Input)
	SDA	I2C data
	TIM0_CH0	Timer0 channel 0
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	CMP0_IN	Comparator 0 negative input
	FLT	IO filtering
	EXTI9	External GPIO Interrupt 9
	PU	Built-in 10kΩ pull-up resistor; software switchable
13	P1_0	P1.0
	MCPWM_CH0N	PWM Channel 0 Low Side
	UART0_TXD	Serial port 0 send (receive)
	SPI_DI	SPI Data In (Out)
	TIM0_BKIN	TIMER0_FAIL signal from GPIO
	EXTI10	External GPIO Interrupt Signal 10
	PU	Built-in 10kΩ pull-up resistor; software switchable
	P1_3	P1.3
	TIM3_CH1	Timer3 channel 1
	ADC01_CH5	ADC0/1 channel 5
	PU	Built-in 10kΩ pull-up resistor; software switchable
14	P3_5	P3.5

	OPA0_IP	Positive terminal input of operational amplifier 0
15	P3_7	P3.7
	OPA0_IN	Input of negative terminal of operational amplifier 0
16	P2_7	P2.7
	CLKO	Clock output (for debugging)
	UART0_TXD	Serial port 0 send (receive)
	TIM0_CH0	Timer0 channel 0
	TIM3_CH1	Timer3 channel 1
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	CLUOUT1	CLU1 output
	ADC0_CH11	ADC0 Channel 11
	OPAx_OUT	Op Amp Output
	LD015	1.5V LDO Output
	REF	Reference Voltage
	EXTI11	External GPIO Interrupt Signal 11
	WK6	External wake-up signal 6
	PU	Built-in 10kΩ pull-up resistor, software switchable
17	GND	Chip ground. It is strongly recommended that multiple ground pins be grounded uniformly on the PCB.
18	LO3	Phase C low-side output, worked by MCU P1.6; the polarity of LO3 is the same as that of P1.6, i.e. when P1.6 = 1, LO3 = 1. You need to set MCPWM_SWAP = 1.
19	LO2	Phase B low-side output, worked by MCU P1.5; the polarity of LO2 is the same as that of P1.5, i.e. when P1.5 = 1, LO2 = 1. You need to set MCPWM_SWAP = 1.
20	LO1	Phase A low-side output, worked by MCU P1.4; the polarity of LO1 is the same as that of P1.4, i.e. when P1.4 = 1, LO1 = 1. You need to set MCPWM_SWAP = 1.
21	VS1	High-side floating bias voltage 1.
22	HO1	Phase A high-side output, worked by MCU P1.7; the polarity of HO1 is the same as that of P1.7, i.e. when P1.7 = 1, HO1 = 1. You need to set MCPWM_SWAP = 1.
23	VB1	High-side floating supply voltage 1.
24	VS2	High-side floating bias voltage 2.
25	HO2	Phase B high-side output, worked by MCU P1.8; the polarity of HO2 is the same as that of P1.8, i.e. when P1.8 = 1, HO2 = 1. You need to set MCPWM_SWAP = 1.
26	VB2	High-side floating supply voltage 2.
27	VCC	Gate driver power supply
28	VS3	High-side floating bias voltage 3.
29	HO3	Phase C high-side output, worked by MCU P1.9; the polarity of HO3 is the same as that of P1.9, i.e. when P1.9 = 1, HO3 = 1. You need to set MCPWM_SWAP = 1.
30	VB3	High-side floating supply voltage 3.
31	P3_10	P3.10
	MCPWM_CH4P	PWM Channel 4 High Side
	OPA2_IP	Positive input of operational amplifier 2
32	P3_11	P3.11
	MCPWM_CH4N	PWM Channel 4 Low Side

	OPA2_IN	Op Amp 2 Negative Input
33	P2_9	P2.9
	MCPWM_CH5P	PWM Channel 5 High Side
	SPI_DI	SPI Data In (Out)
	SCL	I2C clock
	ADC0_CH12	ADC0 Channel 12
	CMP0_IP0	Comparator 0 positive input 0
	PU	Built-in 10kΩ pull-up resistor, software switchable
34	P2_10	P2.10
	MCPWM_CH5N	PWM Channel 5 Low Side
	SPI_DO	SPI Data Output (Input)
	SDA	I2C data
	PU	Built-in 10kΩ pull-up resistor, software switchable
35	P3_14	P3.14
	OPA3_IN	Op Amp 3 Negative Input
36	P3_15	P3.15
	OPA3_IP	Positive input of operational amplifier 3
37	P2_1	P2.1
	SPI_CLK	SPI clock
	ADC1_CH10	ADC1 channel 10
	CMP1_IP0	Comparator1 positive input0
	P2_3	P2.3
	CMP1_OUT	Comparator 1 Output
	MCPWM_BKIN0	PWM shutdown input signal 0
	SPI_CS	SPI chip select
	TIM0_CH1	Timer0 channel 1
	QEP0_Z	QEP0 Encoder Phase Z
	CLUOUT3	CLU3 output
	FLT	IO filtering
	EXTI13	External GPIO Interrupt Signal 13
38	P2_4	P2.4
	CMP0_OUT	Comparator 0 Output
	HALL_IN0	HALL interface input 0
	MCPWM_CH2P	PWM Channel 2 High Side
	UART1_RXD	Serial port 1 receive (send)
	SPI_CLK	SPI clock
	TIM1_CH0	Timer1 channel 0
	TIM2_CH0	Timer2 channel 0
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	CMP1_IP1	Comparator 1 positive input 1
	FLT	IO filtering
	EXTI14	External GPIO Interrupt Signal 14
	WK5	External wake-up signal 5

	PU	Built-in 10kΩ pull-up resistor, software switchable
39	P2_5	P2.5
	CMP1_OUT	Comparator 1 Output
	HALL_IN1	HALL interface input 1
	MCPWM_CH2N	PWM Channel 2 Low Side
	UART1_TXD	Serial port 1 send (receive)
	SPI_DO	SPI Data Output (Input)
	TIM1_CH1	Timer1 channel 1
	TIM2_CH1	Timer2 channel 1
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	CMP1_IP2	Comparator 1 positive input 2
	FLT	IO filtering
	PU	Built-in 10kΩ pull-up resistor, software switchable
	P2_6	P2.6
	CMP2_OUT	Comparator 2 Output
	HALL_IN2	HALL interface input 2
	MCPWM_CH3P	PWM Channel 3 High-Side
	TIMO_BKIN	TIMER0_FAIL signal from GPIO
	TIM3_CH0	Timer3 channel 0
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	SIF	Single line communication
	CLUOUT0	CLU0 output
	CMP1_IP3	Comparator 1 positive input 3
	FLT	IO filtering
	PU	Built-in 10kΩ pull-up resistor, software switchable
	P2_13	P2.13
	MCPWM_CH3N	PWM Channel 3 Low Side
	UART0_TXD	Serial port 0 send (receive)
	SPI_DO	SPI Data Output (Input)
	SCL	I2C clock
	TIM3_CH1	Timer3 channel 1
	PU	Built-in 10kΩ pull-up resistor, software switchable
40	P2_14	P2.14
	SWCLK	SWD clock
	SPI_DI	SPI Data In (Out)
	SCL	I2C clock
	PU	Built-in 10kΩ pull-up resistor, software switchable

3.1.7 LKS32MC076FNBQ8



Fig.3-11 LKS32MC076FNBQ8 Pin Assignment

图 3-12 LKS32MC078KUBQ8 管脚分布图

0	GND	腹部散热区域, 为芯片 GND
1	P2_14	P2.14
	SWCLK	SWD 时钟
	SPI_DI	SPI 数据输入(输出)
	SCL	I2C 时钟
	PU	内置 10kΩ 上拉电阻, 软件可关闭
2	P2_15	P2.15
	SWDIO	SWD 数据
	UART0_RXD	串口 0 接收(发送)
	SPI_CS	SPI 片选
	SDA	I2C 数据
	TIM2_CH1	Timer2 通道 1
	QEP0_CH1	编码器 0 通道 1
	CLUOUT1	CLU1 输出
	EXTI15	外部 GPIO 中断信号 15
	WAKE7	外部唤醒信号 7
	PU	内置 10kΩ 上拉电阻, 软件可关闭
3	P0_0	P0.0

	CLKO	时钟输出(用于调试)
	MCPWM_BKIN0	PWM 停机输入信号 0
	UART0_RXD	串口 0 接收(发送)
	SPI_DI	SPI 数据输入(输出)
	CLUOUT0	CLU0 输出
	ADC01_CH4	ADC01 通道 4
	DAC0_OUT	DAC0 输出
	DAC1_OUT	DAC1 输出
	FLT	IO 滤波
	EXTI0	外部 GPIO 中断信号 0
	WAKE0	外部唤醒信号 0
	PU	内置 10kΩ 上拉电阻, 软件可关闭
4	P0_2	P0.2
	CLUOUT1	CLU1 输出
	RST_n	复位引脚, P0.2 默认用作 RSTN。建议接一个 10nF~100nF 的电容到地, 并在 RSTN 和 AVDD 之间放置一个 10k~20k 的上拉电阻。如果外部有上拉电阻, RSTN 的电容应为 100nF。P0.2 可切换为 GPIO, 切换后可关闭 10kΩ 上拉电阻。
	FLT	IO 滤波
	EXTI2	外部 GPIO 中断信号 2
	WAKE1	外部唤醒信号 1
	PU	内置 10kΩ 上拉电阻, 软件可关闭
5	AVDD	芯片电源, 供电范围 2.2~5.5V
6	P0_3	P0.3
	MCPWM_CH4P	PWM 通道 4 高边
	SCL	I2C 时钟
	TIM2_CH0	Timer2 通道 0
	QEP0_CH0	编码器 0 通道 0
	ADC01_CH7	ADC01 通道 7
	EXTI3	外部 GPIO 中断信号 3
	PU	内置 10kΩ 上拉电阻, 软件可关闭
7	P0_4	P0.4
	MCPWM_CH4N	PWM 通道 4 低边
	SDA	I2C 数据
	TIM2_CH1	Timer2 通道 1
	QEP0_CH1	编码器 0 通道 1
	ADC01_CH8	ADC01 通道 8
	PU	内置 10kΩ 上拉电阻, 软件可关闭
8	P0_6	P0.6
	HALL_IN1	HALL 接口输入 1
	MCPWM_CH5N	PWM 通道 5 低边
	UART1_RXD	串口 1 接收(发送)
	SCL	I2C 时钟
	TIM1_CH0	Timer1 通道 0

	CAN_RX	CAN 接收端
	CMP2_IN	比较器 2 负端输入
	FLT	IO 滤波
	EXTI4	外部 GPIO 中断信号 4
	WAKE2	外部唤醒信号 2
	PU	内置 10kΩ 上拉电阻, 软件可关闭
9	P2_11	P2.11
	MCPWM_CH1P	PWM 通道 1 高边
	TIM2_CH0	Timer2 通道 0
	QEP0_CH0	编码器 0 通道 0
	CMP2_IP1	比较器 2 正端输入 1
10	P2_12	P2.12
	MCPWM_CH1N	PWM 通道 1 低边
	SPI_CS	SPI 片选
	TIM2_CH1	Timer2 通道 1
	QEP0_CH1	编码器 0 通道 1
	ADC_TRIGGER0	ADC0 触发信号输出(用于调试)
	CLUOUT3	CLU3 输出
	EXTI6	外部 GPIO 中断信号 6
11	P0_11	P0.11
	HALL_IN0	HALL 接口输入 0
	TIM3_CH0	Timer3 通道 0
	QEP1_CH0	编码器 1 通道 0
	ADC1_CH11	ADC1 通道 11
	CMP0_IP1	比较器 0 正端输入 1
	FLT	IO 滤波
	EXTI7	外部 GPIO 中断信号 7
	WAKE3	外部唤醒信号 3
12	P0_12	P0.12
	HALL_IN1	HALL 接口输入 1
	TIM3_CH1	Timer3 通道 1
	QEP1_CH1	编码器 1 通道 1
	CAN_RX	CAN 接收端
	ADC1_CH12	ADC1 通道 12
	CMP0_IP2	比较器 0 正端输入 2
	FLT	IO 滤波
13	P0_13	P0.13
	HALL_IN2	HALL 接口输入 2
	QEP0_Z	QEP0 编码器 Z 相
	CAN_TX	CAN 发送端
	ADC1_CH13	ADC1 通道 13
	CMP0_IP3	比较器 0 正端输入 3
	FLT	IO 滤波

14	P0_14	P0.14
	CMP0_OUT	比较器 0 输出
	MCPWM_BKIN1	PWM 停机输入信号 1
	UART0_TXD	串口 0 发送(接收)
	SPI_CLK	SPI 时钟
	SCL	I2C 时钟
	TIM0_CH1	Timer0 通道 1
	QEP1_Z	QEP1 编码器 Z 相
	ADC_TRIGGER0	ADC0 触发信号输出(用于调试)
	SIF	单线通讯
	CLUOUT0	CLU0 输出
	ADC0_CH10	ADC0 通道 10
	CMP0_IP4	比较器 0 正端输入 4
	FLT	IO 滤波
	EXTI8	外部 GPIO 中断信号 8
	WAKE4	外部唤醒信号 4
	PU	内置 10kΩ 上拉电阻, 软件可关闭
15	P0_15	P0.15
	CMP2_OUT	比较器 2 输出
	MCPWM_CH0P	PWM 通道 0 高边
	UART0_RXD	串口 0 接收(发送)
	SPI_DO	SPI 数据输出(输入)
	SDA	I2C 数据
	TIM0_CH0	Timer0 通道 0
	ADC_TRIGGER1	ADC1 触发信号输出(用于调试)
	CMP0_IN	比较器 0 负端输入
	FLT	IO 滤波
	EXTI9	外部 GPIO 中断信号 9
	PU	内置 10kΩ 上拉电阻, 软件可关闭
16	P1_0	P1.0
	MCPWM_CH0N	PWM 通道 0 低边
	UART0_TXD	串口 0 发送(接收)
	SPI_DI	SPI 数据输入(输出)
	TIM0_BKIN	TIMER0_FAIL 信号来自 GPIO
	EXTI10	外部 GPIO 中断信号 10
	PU	内置 10kΩ 上拉电阻, 软件可关闭
17	P3_5	P3.5
	OPA0_IP	运放 0 正端输入
18	P3_7	P3.7
	OPA0_IN	运放 0 负端输入
19	P2_7	P2.7
	CLKO	时钟输出(用于调试)
	UART0_TXD	串口 0 发送(接收)

	TIM0_CH0	Timer0 通道 0
	TIM3_CH1	Timer3 通道 1
	QEP1_CH1	编码器 1 通道 1
	ADC_TRIGGER1	ADC1 触发信号输出(用于调试)
	CAN_TX	CAN 发送端
	CLUOUT1	CLU1 输出
	ADC0_CH11	ADC0 通道 11
	OPAx_OUT	运放输出
	LDO15	1.5V LDO 输出
	REF	参考电压
	EXTI11	外部 GPIO 中断信号 11
	WAKE6	外部唤醒信号 6
	PU	内置 10kΩ 上拉电阻, 软件可关闭
20	CIN	CIN
21	VCC1	下桥预驱供电电源 1, 芯片内部未与预驱供电电源 2 连接, 需要分别供电。
22	LO1	低侧栅极驱动信号输出 1, 由 MCU P1.13 控制, LO1 极性与 P1.13 相同, 即 P1.13=1 时, LO1=1, 需要设置 PWM_SWAP=2
23	LO2	低侧栅极驱动信号输出 2, 由 MCU P1.14 控制, LO2 极性与 P1.14 相同, 即 P1.14=1 时, LO2=1, 需要设置 PWM_SWAP=2
24	LO3	低侧栅极驱动信号输出 3, 由 MCU P1.15 控制, LO3 极性与 P1.15 相同, 即 P1.15=1 时, LO3=1, 需要设置 PWM_SWAP=2
25	VCC2	下桥预驱供电电源 2, 芯片内部未与预驱供电电源 1 连接, 需要分别供电。
26	VB3	高边浮动电源电压 3
27	VS3	高边浮动偏置电压 3
28	HO3	高侧栅极驱动信号输出 3, 由 MCU P1.5 控制, HO1 极性与 P1.5 相同, 即 P1.5=1 时, HO1=1, 需要设置 PWM_SWAP=2
29	VB2	高边浮动电源电压 2
30	VS2	高边浮动偏置电压 2
31	HO2	高侧栅极驱动信号输出 2, 由 MCU P1.4 控制, HO1 极性与 P1.4 相同, 即 P1.4=1 时, HO1=1, 需要设置 PWM_SWAP=2
32	VS1	高边浮动偏置电压 1
33	HO1	高侧栅极驱动信号输出 1, 由 MCU P2.0 控制, HO1 极性与 P2.0 相同, 即 P2.0=1 时, HO1=1, 需要设置 PWM_SWAP=2
34	VB1	高边浮动电源电压 1
35	P1_11	P1.11
	MCPWM_CH3N	PWM 通道 3 低边
	UART0_TXD	串口 0 发送(接收)
	SDA	I2C 数据
	TIM0_CH1	Timer0 通道 1
	ADC_TRIGGER1	ADC1 触发信号输出(用于调试)
	SIF	单线通讯
	CLUOUT2	CLU2 输出
	PU	内置 10kΩ 上拉电阻, 软件可关闭

36	P3_10	P3.10
	MCPWM_CH4P	PWM 通道 4 高边
	OPA2_IP	运放 2 正端输入
37	P3_11	P3.11
	MCPWM_CH4N	PWM 通道 4 低边
	OPA2_IN	运放 2 负端输入
38	P2_9	P2.9
	MCPWM_CH5P	PWM 通道 5 高边
	SPI_DI	SPI 数据输入(输出)
	SCL	I2C 时钟
	ADC0_CH12	ADC0 通道 12
	CMP0_IP0	比较器 0 正端输入 0
	PU	内置 10kΩ 上拉电阻, 软件可关闭
39	P2_10	P2.10
	MCPWM_CH5N	PWM 通道 5 低边
	SPI_DO	SPI 数据输出(输入)
	SDA	I2C 数据
	PU	内置 10kΩ 上拉电阻, 软件可关闭
40	P3_14	P3.14
	OPA3_IN	运放 3 负端输入
41	P3_15	P3.15
	OPA3_IP	运放 3 正端输入
42	P2_1	P2.1
	SPI_CLK	SPI 时钟
	ADC1_CH10	ADC1 通道 10
	CMP1_IP0	比较器 1 正端输入 0
43	P2_3	P2.3
	CMP1_OUT	比较器 1 输出
	MCPWM_BKIN0	PWM 停机输入信号 0
	SPI_CS	SPI 片选
	TIM0_CH1	Timer0 通道 1
	QEP0_Z	QEP0 编码器 Z 相
	CLUOUT3	CLU3 输出
	FLT	IO 滤波
	EXTI13	外部 GPIO 中断信号 13
44	P2_4	P2.4
	CMP0_OUT	比较器 0 输出
	HALL_IN0	HALL 接口输入 0
	MCPWM_CH2P	PWM 通道 2 高边
	UART1_RXD	串口 1 接收(发送)
	SPI_CLK	SPI 时钟
	TIM1_CH0	Timer1 通道 0
	TIM2_CH0	Timer2 通道 0

	QEP0_CH0	编码器 0 通道 0
	ADC_TRIGGER0	ADC0 触发信号输出(用于调试)
	CAN_RX	CAN 接收端
	CMP1_IP1	比较器 1 正端输入 1
	FLT	IO 滤波
	EXTI14	外部 GPIO 中断信号 14
	WAKE5	外部唤醒信号 5
	PU	内置 10kΩ 上拉电阻, 软件可关闭
45	P2_5	P2.5
	CMP1_OUT	比较器 1 输出
	HALL_IN1	HALL 接口输入 1
	MCPWM_CH2N	PWM 通道 2 低边
	UART1_TXD	串口 1 发送(接收)
	SPI_DO	SPI 数据输出(输入)
	TIM1_CH1	Timer1 通道 1
	TIM2_CH1	Timer2 通道 1
	QEP0_CH1	编码器 0 通道 1
	QEP0_CH1	编码器 0 通道 1
	ADC_TRIGGER1	ADC1 触发信号输出(用于调试)
	CAN_TX	CAN 发送端
	CMP1_IP2	比较器 1 正端输入 2
	FLT	IO 滤波
	PU	内置 10kΩ 上拉电阻, 软件可关闭
	P2_13	P2.13
	MCPWM_CH3N	PWM 通道 3 低边
	UART0_TXD	串口 0 发送(接收)
	SPI_DO	SPI 数据输出(输入)
	SCL	I2C 时钟
	TIM3_CH1	Timer3 通道 1
	QEP1_CH1	编码器 1 通道 1
	PU	内置 10kΩ 上拉电阻, 软件可关闭

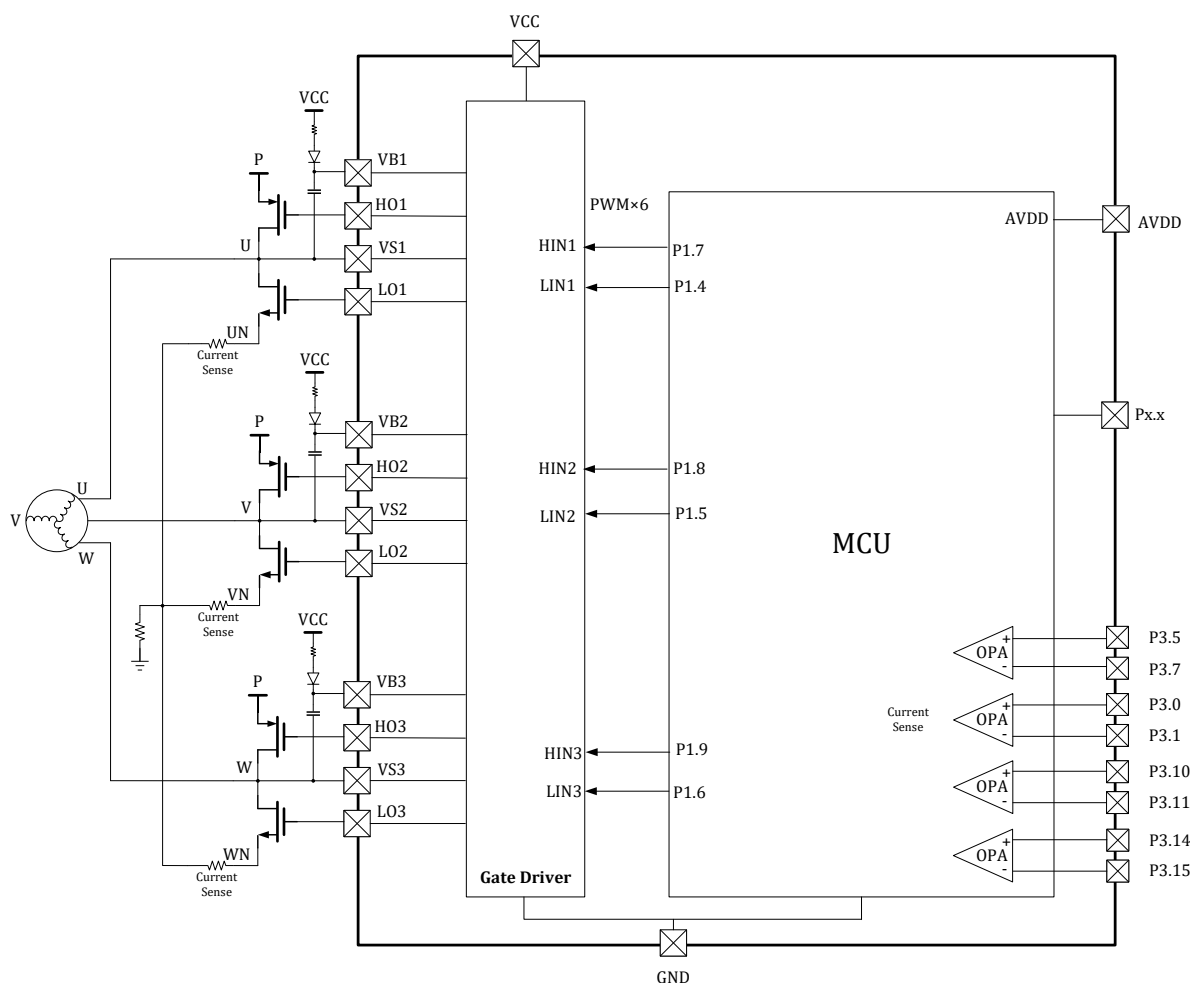


Fig.3-13 LKS32MC076FNBQ8 Schematic diagram of inner driver connection

Table 3-7 LKS32MC076FNBQ8 Pin Function Description

0	GND	In the heat dissipation area of the abdomen, Pad is the chip GND
1	P0_0	P0.0
	CLK0	Clock output (for debugging)
	MCPWM_BKIN0	PWM shutdown input signal 0
	UART0_RXD	Serial port 0 receive (send)
	SPI_DI	SPI Data In (Out)
	CLUOUT0	CLU0 output
	ADC01_CH4	ADC 0/ADC1 Channel 4
	DAC0_OUT	DAC0 output
	DAC1_OUT	DAC1 Output
	FLT	IO filtering
	EXTI0	External GPIO Interrupt Signal 0
	WK0	External wake-up signal 0
	PU	Built-in 10kΩ pull-up resistor, software switchable
2	P0_2	P0.2
	CLUOUT1	CLU1 output

	RST_n	Reset pin, P0.2 used as RSTN by default. It is recommended to connect a 10 nF to 100 nF capacitor to ground and place a 10 K to 20 K pull-up resistor between RSTN and AVDD. If there is an external pull-up resistor, the capacitance of RSTN should be 100 nF. P0.2 can be switched as a GPIO, which turns off the 10 kΩ pull-up resistor.
	FLT	IO filtering
	EXTI2	External GPIO Interrupt Signal 2
	WK1	External wake-up signal 1
	PU	Built-in 10kΩ pull-up resistor, software switchable
3	AVDD	Chip power supply, power supply range 2.5 ~ 5.5V
4	P0_3	P0.3
	MCPWM_CH4P	PWM Channel 4 High Side
	SCL	I2C clock
	TIM2_CH0	Timer2 channel 0
	ADC01_CH7	ADC0/ADC1 Channel 7
	EXTI3	External GPIO Interrupt Signal 3
	PU	Built-in 10kΩ pull-up resistor, software switchable
5	P0_4	P0.4
	MCPWM_CH4N	PWM Channel 4 Low Side
	SDA	I2C data
	TIM2_CH1	Timer2 channel 1
	ADC01_CH8	ADC0/ADC1 Channel 8
	PU	Built-in 10kΩ pull-up resistor, software switchable
6	P0_5	P0.5
	HALL_IN0	HALL interface input 0
	MCPWM_CH5P	PWM Channel 5 High Side
	QEP0_Z	QEP0 Encoder Phase Z
	ADC01_CH9	ADC0/ADC1 Channel 9
7	P0_6	P0.6
	HALL_IN1	HALL interface input 1
	MCPWM_CH5N	PWM Channel 5 Low Side
	UART1_RXD	Serial port 1 receive (send)
	SCL	I2C clock
	TIM1_CH0	Timer1 channel 0
	CAN_RX	CAN 接收端
	CMP2_IN	Comparator 2 Negative Terminal Input
	FLT	IO filtering
	EXTI4	External GPIO Interrupt 4
	WK2	External wake-up signal 2
	PU	Built-in 10kΩ pull-up resistor, software switchable
8	P0_7	P0.7
	HALL_IN2	HALL interface input 2
	MCPWM_BKIN1	PWM Shutdown Input Signal 1
	UART1_TXD	Serial port 1 send (receive)

	SDA	I2C data
	TIM1_CH1	Timer1 channel 1
	CAN_TX	CAN 发送端
	CMP2_IP0	Positive input 0 of comparator 2
	FLT	IO filtering
	PU	Built-in 10kΩ pull-up resistor, software can be turned off
9	P2_11	P2.11
	MCPWM_CH1P	PWM Channel 1 High Side
	TIM2_CH0	Timer2 channel 0
	CMP2_IP1	Positive Input 1 of Comparator 2
10	P2_12	P2.12
	MCPWM_CH1N	PWM Channel 1 Low Side
	SPI_CS	SPI chip select
	TIM2_CH1	Timer2 channel 1
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	CLUOUT3	CLU3 output
	EXTI6	External GPIO Interrupt 6
11	P0_11	P0.11
	HALL_IN0	HALL interface input 0
	TIM3_CH0	Timer3 channel 0
	ADC1_CH11	ADC1 Channel 11
	CMP0_IP1	Comparator 0 positive input 1
	FLT	IO filtering
	EXTI7	External GPIO Interrupt Signal 7
	WK3	External wake-up signal 3
12	P0_12	P0.12
	HALL_IN1	HALL interface input 1
	TIM3_CH1	Timer3 channel 1
	ADC1_CH12	ADC1 Channel 12
	CAN_RX	CAN 接收端
	CMP0_IP2	Comparator 0 positive input 2
	FLT	IO filtering
13	P0_13	P0.13
	HALL_IN2	HALL interface input 2
	QEP0_Z	QEP0 Encoder Phase Z
	ADC1_CH13	ADC1 Channel 13
	CAN_TX	CAN 发送端
	CMP0_IP3	Comparator 0 positive input 3
	FLT	IO filtering
14	P0_14	P0.14
	CMP0_OUT	Comparator 0 Output
	MCPWM_BKIN1	PWM Shutdown Input Signal 1
	UART0_TXD	Serial port 0 send (receive)

	SPI_CLK	SPI clock
	SCL	I2C clock
	TIM0_CH1	Timer0 channel 1
	QEP1_Z	Phase Z of QEP1 encoder
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	SIF	Single line communication
	CLUOUT0	CLU0 output
	ADC0_CH10	ADC0 Channel 10
	CMP0_IP4	Comparator 0 positive input 4
	FLT	IO filtering
	EXTI8	External GPIO Interrupt Signal 8
	WK4	External wake-up signal 4
	PU	Built-in 10kΩ pull-up resistor, software switchable
15	P0_15	P0.15
	CMP2_OUT	Comparator 2 Output
	MCPWM_CH0P	PWM Channel 0 High Side
	UART0_RXD	Serial port 0 receive (send)
	SPI_DO	SPI Data Output (Input)
	SDA	I2C data
	TIM0_CH0	Timer0 channel 0
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	CMP0_IN	Comparator 0 negative input
	FLT	IO filtering
	EXTI9	External GPIO Interrupt 9
	PU	Built-in 10kΩ pull-up resistor, software switchable
16	P1_0	P1.0
	MCPWM_CH0N	PWM Channel 0 Low Side
	UART0_TXD	Serial port 0 send (receive)
	SPI_DI	SPI Data In (Out)
	TIM0_BKIN	TIMER0_FAIL signal from GPIO
	EXTI10	External GPIO Interrupt Signal 10
	PU	Built-in 10kΩ pull-up resistor, software switchable
17	P3_5	P3.5
	OPA0_IP	Positive terminal input of operational amplifier 0
18	P3_7	P3.7
	OPA0_IN	Input of negative terminal of operational amplifier 0
19	P2_7	P2.7
	CLKO	Clock output (for debugging)
	UART0_TXD	Serial port 0 send (receive)
	TIM0_CH0	Timer0 channel 0
	TIM3_CH1	Timer3 channel 1
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	CAN_TX	CAN 发送端

	CLUOUT1	CLU1 output
	ADC0_CH11	ADC0 Channel 11
	OPA _x _OUT	Op Amp Output
	LD015	1.5V LDO Output
	REF	Reference Voltage
	EXTI11	External GPIO Interrupt Signal 11
	WK6	External wake-up signal 6
	PU	Built-in 10kΩ pull-up resistor, software switchable
20	P3_0	P3.0
	OPA1_IP	Positive input of operational amplifier 1
	P3_9	P3.9
	UART1_TXD	Serial port 1 send (receive)
	TIM3_CH1	Timer3 channel 1
	OSC_OUT	External crystal pin
	PU	Built-in 10kΩ pull-up resistor, software switchable
21	P3_1	P3.1
	OPA1_IN	Op Amp 1 Negative Input
	P2_8	P2.8
	UART1_RXD	Serial port 1 receive (send)
	SPI_DO	SPI Data Output (Input)
	TIM3_CH0	Timer3 channel 0
	OSC_IN	External crystal pin
	PU	Built-in 10kΩ pull-up resistor, software switchable
22	VCC	Full-bridge drive power supply
23	LO1	A phase low-side output, controlled by MCU P1.4, LO1 polarity is the same as P1.4, that is, when P1.4 = 1, LO1 = 1. PWM_SWAP = 1 needs to be set.
24	LO2	Phase B low-side output, controlled by MCU P1.5, LO2 polarity is the same as P1.5, that is, when P1.5 = 1, LO2 = 1. PWM_SWAP = 1 needs to be set.
25	LO3	Phase C low-side output, controlled by MCU P1.6, LO3 polarity is the same as P1.6, that is, when P1.6 = 1, LO3 = 1. PWM_SWAP = 1 needs to be set.
26	VS1	High-side floating bias voltage 1.
27	HO1	Phase A high-side output is controlled by MCU P1.7, and the polarity of HO1 is the same as P1.7, that is, when P1.7 = 1, HO1 = 1. PWM_SWAP = 1 needs to be set.
28	VB1	High-side floating supply voltage 1.
29	VS2	High-side floating bias voltage 2.
30	HO2	Phase B high-side output is controlled by MCU P1.8. The polarity of HO2 is the same as P1.8. That is, when P1.8 = 1, HO2 = 1. PWM_SWAP = 1 needs to be set.
31	VB2	High-side floating supply voltage 2.
32	VS3	High-side floating bias voltage 3.
33	HO3	Phase C high-side output is controlled by MCU P1.9. The polarity of HO3 is the same as P1.9, that is, when P1.9 = 1, HO3 = 1. PWM_SWAP = 1 needs to be set.
34	VB3	High-Side Float Supply Voltage 3.
35	NC	Do not connect

36	P1_10	P1.10
	MCPWM_CH3P	PWM Channel 3 High-Side
	UART0_RXD	Serial port 0 receive (send)
	SCL	I2C clock
	TIM0_CH0	Timer0 channel 0
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	ADC0_CH13	ADC0 Channel 13
	EXTI12	External GPIO Interrupt Signal 12
	PU	Built-in 10kΩ pull-up resistor, software switchable
37	P1_11	P1.11
	MCPWM_CH3N	PWM Channel 3 Low Side
	UART0_TXD	Serial port 0 send (receive)
	SDA	I2C data
	TIM0_CH1	Timer0 channel 1
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	SIF	Single line communication
	CLUOUT2	CLU2 output
	PU	Built-in 10kΩ pull-up resistor, software switchable
38	P3_10	P3.10
	MCPWM_CH4P	PWM Channel 4 High Side
	OPA2_IP	Positive input of operational amplifier 2
39	P3_11	P3.11
	MCPWM_CH4N	PWM Channel 4 Low Side
	OPA2_IN	Op Amp 2 Negative Input
40	P2_9	P2.9
	MCPWM_CH5P	PWM Channel 5 High Side
	SPI_DI	SPI Data In (Out)
	SCL	I2C clock
	ADC0_CH12	ADC0 Channel 12
	CMP0_IP0	Comparator 0 positive input 0
	PU	Built-in 10kΩ pull-up resistor, software can be turned off
41	P2_10	P2.10
	MCPWM_CH5N	PWM Channel 5 Low Side
	SPI_DO	SPI Data Output (Input)
	SDA	I2C data
	PU	Built-in 10kΩ pull-up resistor, software switchable
42	P3_14	P3.14
	OPA3_IN	Op Amp 3 Negative Input
43	P3_15	P3.15
	OPA3_IP	Positive input of operational amplifier 3
44	P2_1	P2.1
	SPI_CLK	SPI clock
	ADC1_CH10	ADC1 Channel 10

	CMP1_IP0	Positive input 0 of comparator 1
45	P2_2	P2.2
	QEP1_Z	Phase Z of QEP1 encoder
	CMP1_IN	Comparator 1 Negative Input
46	P2_3	P2.3
	CMP1_OUT	Comparator 1 Output
	MCPWM_BKIN0	PWM shutdown input signal 0
	SPI_CS	SPI chip select
	TIM0_CH1	Timer0 channel 1
	QEP0_Z	QEP0 Encoder Phase Z
	CLUOUT3	CLU3 output
	FLT	IO filtering
	EXTI13	External GPIO Interrupt Signal 13
47	P2_4	P2.4
	CMP0_OUT	Comparator 0 Output
	HALL_IN0	HALL interface input 0
	MCPWM_CH2P	PWM Channel 2 High Side
	UART1_RXD	Serial port 1 receive (send)
	SPI_CLK	SPI clock
	TIM1_CH0	Timer1 channel 0
	TIM2_CH0	Timer2 channel 0
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	CAN_RX	CAN 接收端
	CMP1_IP1	Comparator 1 positive input 1
	FLT	IO filtering
	EXTI14	External GPIO Interrupt Signal 14
	WK5	External wake-up signal 5
	PU	Built-in 10kΩ pull-up resistor, software switchable
48	P2_5	P2.5
	CMP1_OUT	Comparator 1 Output
	HALL_IN1	HALL interface input 1
	MCPWM_CH2N	PWM Channel 2 Low Side
	UART1_TXD	Serial port 1 send (receive)
	SPI_DO	SPI Data Output (Input)
	TIM1_CH1	Timer1 channel 1
	TIM2_CH1	Timer2 channel 1
	ADC_TRIGGER1	ADC1 trigger signal output (for debugging)
	CAN_TX	CAN 发送端
	CMP1_IP2	Comparator 1 positive input 2
	FLT	IO filtering
	PU	Built-in 10kΩ pull-up resistor, software switchable
49	P2_6	P2.6
	CMP2_OUT	Comparator 2 Output

	HALL_IN2	HALL interface input 2
	MCPWM_CH3P	PWM Channel 3 High-Side
	TIM0_BKIN	TIMER0_FAIL signal from GPIO
	TIM3_CH0	Timer3 channel 0
	ADC_TRIGGER0	ADC0 trigger signal output (for debugging)
	SIF	Single line communication
	CLUOUT0	CLU0 output
	CMP1_IP3	Comparator 1 positive input 3
	FLT	IO filtering
	PU	Built-in 10kΩ pull-up resistor, software switchable
50	P2_13	P2.13
	MCPWM_CH3N	PWM Channel 3 Low Side
	UART0_TXD	Serial port 0 send (receive)
	SPI_DO	SPI Data Output (Input)
	SCL	I2C clock
	TIM3_CH1	Timer3 channel 1
	PU	Built-in 10kΩ pull-up resistor, software switchable
51	P2_14	P2.14
	SWCLK	SWD clock
	SPI_DI	SPI Data In (Out)
	SCL	I2C clock
	PU	Built-in 10kΩ pull-up resistor, software switchable
52	P2_15	P2.15
	SWDIO	SWD data
	UART0_RXD	Serial port 0 receive (send)
	SPI_CS	SPI chip select
	SDA	I2C data
	TIM2_CH1	Timer2 channel 1
	CLUOUT1	CLU1 output
	EXTI15	External GPIO Interrupt 15
	WK7	External wake-up signal 7
	PU	Built-in 10kΩ pull-up resistor, software switchable

3.2 Description of Pin Multiplex Function

Table 3-8 LKS32MC07X Pin Function Selection

Port	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF0
P0.0	CLKO		MCPWM_BKIN0	UART0_RXD	SPI_DI							CLUOUT0	ADC01_CH4/ DAC0_OUT/ DAC1_OUT
P0.1													ADC01_CH6
P0.2												CLUOUT1	
P0.3			MCPWM_CH4P			SCL		TIM2_CH0					ADC01_CH7
P0.4			MCPWM_CH4N			SDA		TIM2_CH1					ADC01_CH8
P0.5		HALL_IN0	MCPWM_CH5P					QEPO_Z					ADC01_CH9
P0.6		HALL_IN1	MCPWM_CH5N	UART1_RXD		SCL	TIM1_CH0			CAN_RX			CMP2_IN
P0.7		HALL_IN2	MCPWM_BKIN1	UART1_TXD		SDA	TIM1_CH1			CAN_TX			CMP2_IP0
P0.8													
P0.9						SCL		TIM2_CH0					
P0.10						SDA		TIM2_CH1					
P0.11		HALL_IN0						TIM3_CH0					ADC1_CH11/ CMP0_IP1
P0.12		HALL_IN1						TIM3_CH1		CAN_RX			ADC1_CH12/ CMP0_IP2
P0.13		HALL_IN2						QEPO_Z		CAN_TX			ADC1_CH13/ CMP0_IP3
P0.14	CMP0_OUT		MCPWM_BKIN1	UART0_TXD	SPI_CLK	SCL	TIM0_CH1	QEP1_Z	ADC_TRIGGER0		SIF	CLUOUT0	ADC0_CH10/ CMP0_IP4
P0.15	CMP2_OUT		MCPWM_CH0P	UART0_RXD	SPI_DO	SDA	TIM0_CH0		ADC_TRIGGER1				CMP0_IN



Table 3-9 LKS32MC07X Pin Function Selection (continued)

Port	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF0
P1.0			MCPWM_CH0N	UART0_TXD	SPI_DI		TIM0_BKIN						
P1.1					SPI_CS								
P1.2								TIM3_CH0					
P1.3								TIM3_CH1					ADC01_CH5
P1.4			MCPWM_CH0P					QEP0_Z					
P1.5			MCPWM_CH0N										
P1.6			MCPWM_CH1P										
P1.7			MCPWM_CH1N										
P1.8			MCPWM_CH2P										
P1.9			MCPWM_CH2N										
P1.10			MCPWM_CH3P	UART0_RXD		SCL	TIM0_CH0		ADC_TRIGGER0				ADC0_CH13
P1.11			MCPWM_CH3N	UART0_TXD		SDA	TIM0_CH1		ADC_TRIGGER1		SIF	CLUOUT2	
P1.12													
P1.13			MCPWM_CH5P		SPI_CLK		TIM0_CH0						
P1.14			MCPWM_CH5N		SPI_DO		TIM0_CH1						
P1.15			MCPWM_CH4P		SPI_DI			TIM2_CH0					

Table 3-10 LKS32MC07X Pin Function Selection (continued)

Port	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF0
P2.0			MCPWM_CH4N		SPI_CS			TIM2_CH1					
P2.1					SPI_CLK								ADC1_CH10/ CMP1_IP0
P2.2								QEP1_Z					CMP1_IN
P2.3	CMP1_OUT		MCPWM_BKIN0		SPI_CS		TIM0_CH1	QEP0_Z				CLUOUT3	
P2.4	CMP0_OUT	HALL_IN0	MCPWM_CH2P	UART1_RXD	SPI_CLK		TIM1_CH0	TIM2_CH0	ADC_TRIGGER0	CAN_RX			CMP1_IP1
P2.5	CMP1_OUT	HALL_IN1	MCPWM_CH2N	UART1_TXD	SPI_DO		TIM1_CH1	TIM2_CH1	ADC_TRIGGER1	CAN_TX			CMP1_IP2
P2.6	CMP2_OUT	HALL_IN2	MCPWM_CH3P				TIM0_BKIN	TIM3_CH0	ADC_TRIGGER0		SIF	CLUOUT0	CMP1_IP3
P2.7	CLKO			UART0_TXD			TIM0_CH0	TIM3_CH1	ADC_TRIGGER1	CAN_TX		CLUOUT1	ADC0_CH11/ OPA _x _OUT/ LDO15/REF
P2.8				UART1_RXD	SPI_DO			TIM3_CH0					OSC_IN
P2.9			MCPWM_CH5P		SPI_DI	SCL							ADC0_CH12/ CMP0_IP0
P2.10			MCPWM_CH5N		SPI_DO	SDA							
P2.11			MCPWM_CH1P					TIM2_CH0					CMP2_IP1
P2.12			MCPWM_CH1N		SPI_CS			TIM2_CH1	ADC_TRIGGER0			CLUOUT3	
P2.13			MCPWM_CH3N	UART0_TXD	SPI_DO	SCL		TIM3_CH1					
P2.14	SWCLK				SPI_DI	SCL							
P2.15	SWDIO			UART0_RXD	SPI_CS	SDA		TIM2_CH1				CLUOUT1	

Table 3-11 LKS32MC07X Pin Function Selection (continued)

Port	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF0
P3.0													OPA1_IP
P3.1													OPA1_IN
P3.2			MCPWM_CH3P									CLUOUT2	
P3.3													
P3.4			MCPWM_CH3N										
P3.5													OPA0_IP
P3.6													
P3.7													OPA0_IN
P3.8													
P3.9				UART1_TXD				TIM3_CH1					OSC_OUT
P3.10			MCPWM_CH4P										OPA2_IP
P3.11			MCPWM_CH4N										OPA2_IN
P3.12													
P3.13													
P3.14													OPA3_IN
P3.15													OPA3_IP

For all MCUs with pre-drivers, the MCPWM0_SWAP must be uniformly configured to 1. Taking the P0.3 pin as an example, it is mapped to the CH4P channel by default after power-on. When MCPWM0_SWAP is set to 1, this pin switches to the CH5N channel. All pin alternate functions are labeled based on the configuration where MCPWM0_SWAP = 1.



4 Package size

4.1 LKS32MC070FLRBT8

LQFP64 Profile Quad Flat Package:

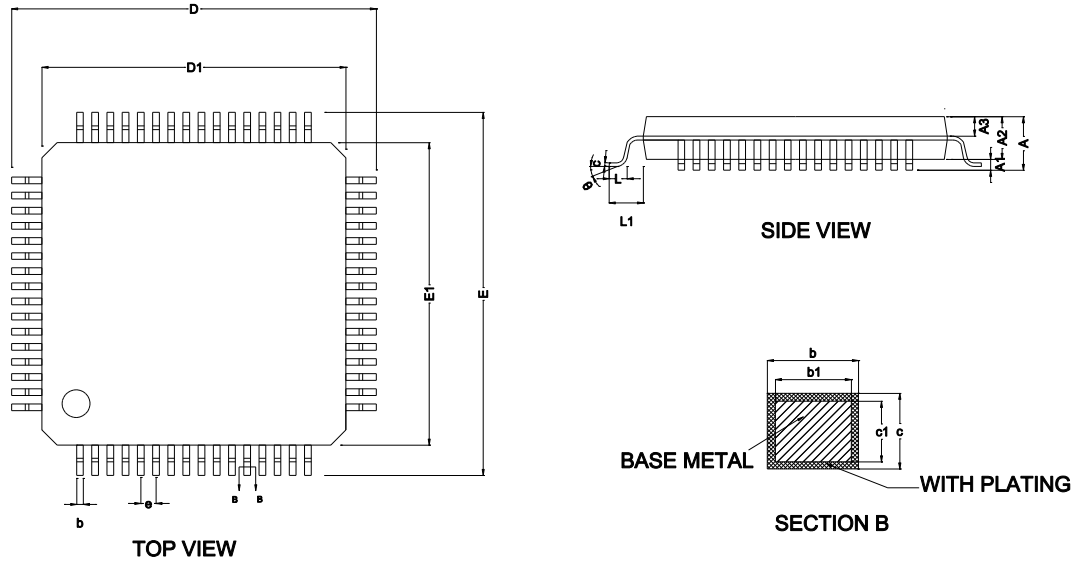


Fig.4-1 LKS32MC070FLRBT8 Package Diagram

Table 4-1 LKS32MC070FLRBT8 Package Dimension

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
A3	0.59	0.64	0.69
b	0.18	-	0.26
b1	0.17	0.20	0.23
c	0.13	-	0.17
c1	0.12	0.13	0.14
D	11.80	12.00	12.20
D1	9.90	10.00	10.10
E	11.80	12.00	12.20
E1	9.90	10.00	10.10
e	0.50BSC		
L	0.45	-	0.75
L1	1.00REF		
θ	0	-	7°

4.2 LKS32MC071DOC8T8

LQFP48 Profile Quad Flat Package:

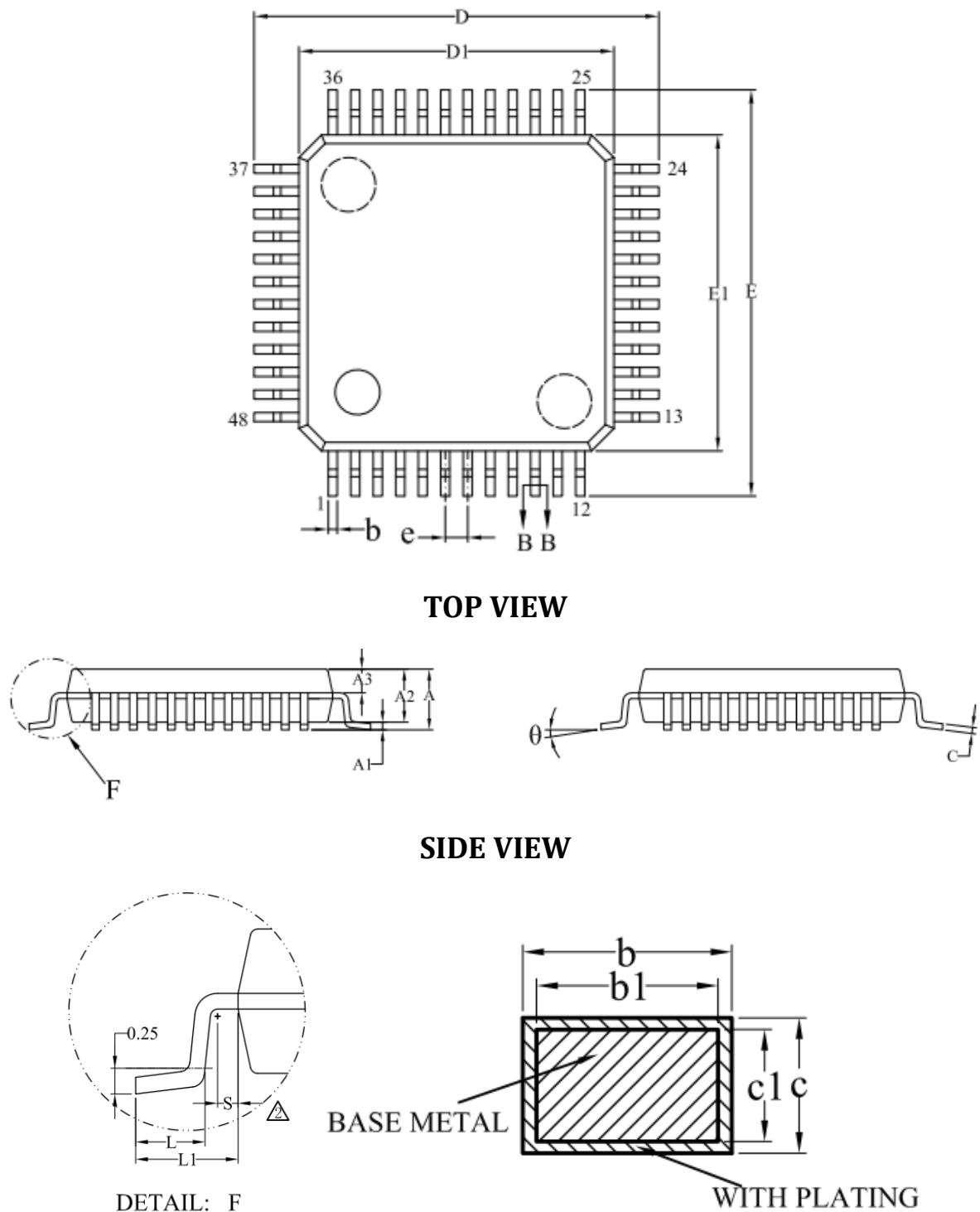


Fig.4-2 LKS32MC071DOC8T8 Package Diagram

Table 4-2 LKS32MC071DOC8T8 Package Dimension

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	—	—	1.60
A1	0.05	—	0.15
A2	1.35	1.40	1.45
A3	0.59	0.64	0.69
b	0.18	—	0.26
b1	0.17	0.20	0.23
c	0.13	—	0.17
c1	0.12	0.13	0.14
D	8.80	9.00	9.20
D1	6.90	7.00	7.10
E	8.80	9.00	9.20
E1	6.90	7.00	7.10
e	0.50BSC		
L	0.45	—	0.75
L1	1.00REF		
θ	0°	—	7°
△ S	0.20	—	—

4.3 LKS32MC074DF8Q8/ LKS32MC074DOF8Q8/ LKS32MC074FF8Q8

QFN5*5 40L-0.75 Profile Quad Flat Package:

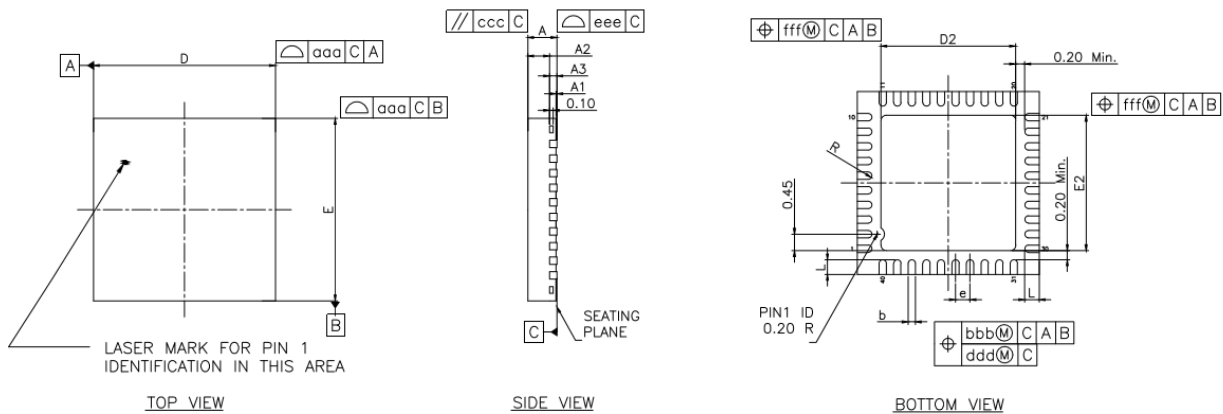


Fig.4-3 LKS32MC074DF8Q8/ LKS32MC074DOF8Q8 Package Diagram

Table 4-3 LKS32MC074DF8Q8/ LKS32MC074DOF8Q8 Package Dimension

SYMBOL	MILLIMETER			INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	0.028	0.030	0.032

A1	0.00	0.02	0.05	0.000	0.0008	0.002
A2	0.50	0.55	0.75	0.020	0.022	0.030
A3	0.2 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	4.90	5.00	5.10	0.193	0.197	0.201
D2	3.20	3.70	3.80	0.126	0.146	0.150
E	4.90	5.00	5.10	0.193	0.197	0.201
E2	3.20	3.70	3.80	0.126	0.146	0.150
L	0.30	0.40	0.50	0.012	0.016	0.020
e	0.4 bsc			0.016 bsc		
R	0.075	-	-	0.003	-	-
TOLERANCE OF FORM AND POSITION						
aaa	0.10			0.004		
bbb	0.07			0.003		
ccc	0.10			0.004		
ddd	0.05			0.002		
eee	0.08			0.003		
fff	0.10			0.004		

4.4 LKS32MC076FNBQ8

QFN52 Profile Quad Flat Package:

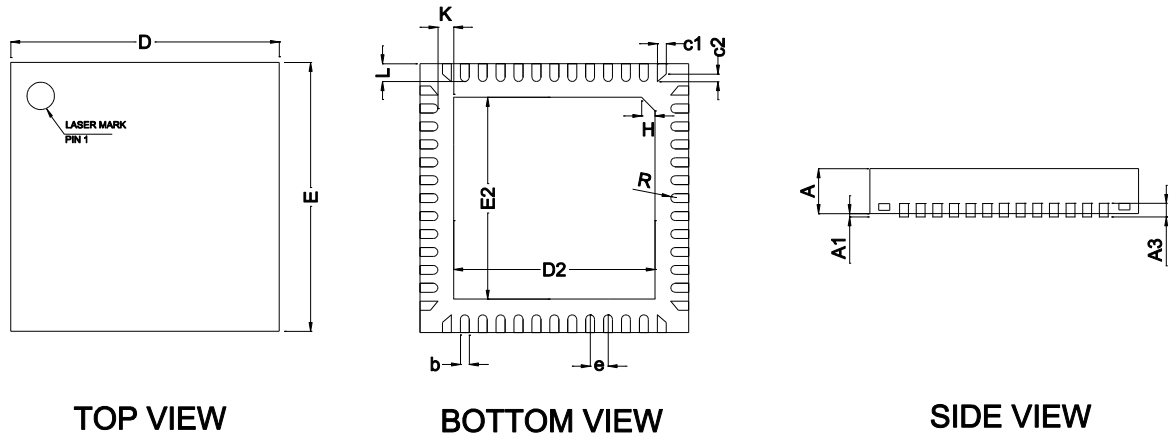


Fig 4-4 LKS32MC076FNBQ8 Package Diagram

Table 4-4 LKS32MC076FNBQ8 Package Dimension

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.20REF		
b	0.15	0.20	0.25
D	5.90	6.00	6.10
E	5.90	6.00	6.10
D2	4.40	4.50	4.60
E2	4.40	4.50	4.60
e	0.30	0.40	0.45
H	0.35REF		
K	0.25	-	-
L	0.35	0.40	0.45
R	0.075	-	-
c1	-	0.17	-
c2	-	0.17	-

4.5 LKS32MC078KUBQ8

QFN45(8*8) Profile Quad Flat Package:

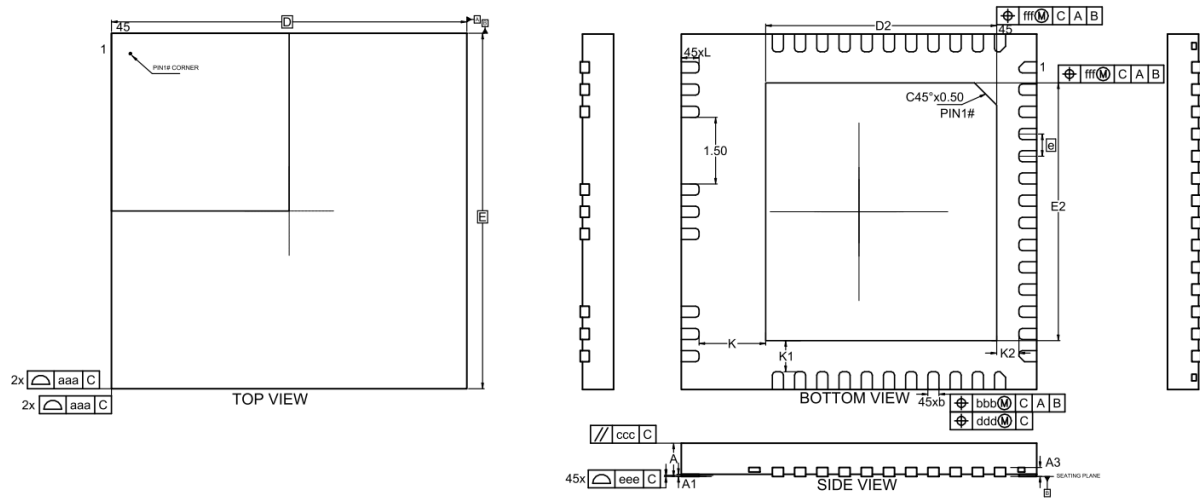


图 4-5 LKS32MC078KUBQ8 封装图示

表 4-5 LKS32MC078KUBQ8 封装尺寸

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.20REF		
b	0.20	0.25	0.30
D	7.90	8.00	8.10
E	7.90	8.00	8.10
D2	5.10	5.20	5.30
E2	5.70	5.80	5.90
e	0.50BSC		
L	0.35	0.40	0.45
K	-	1.50	-
K1	-	0.70	-
K2	-	0.50	-
aaa	0.15		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		
fff	0.10		

5 Electrical performance parameters

The electrical characteristics of integrated 6N Driver for LKS32MC071D0/076F/074D/074D0 are shown in the following table.

Table 5-1 LKS32MC07x 6N electrical absolute characteristics

Parameter	Min.	Max.	Unit	Explain
MCU Power Supply Voltage (AVDD)	-0.3	+6.0	V	
Gate Driver Power Supply Voltage (VCC)	-0.3	+22.0	V	LKS32MC074DF8Q8 LKS32MC076FNBQ8
	-0.3	+25.0	V	LKS32MC070FLRBT8 LKS32MC071DOC8T8 LKS32MC074FF8Q8 LKS32MC074DOF8Q8 LKS32MC078KUBQ8
Operating temperature	-40	+105	°C	
Storage temperature	-40	+150	°C	
Junction temperature	-	125	°C	
Pin temperature (soldering for 10 seconds)	-	260	°C	

Table 5-2 LKS32MC07x 6N Recommended working condition parameters

Parameter	Mini.	Typ.	Max.	Unit	Explain
MCU Power Supply Voltage (AVDD)	2.5	5	5.5	V	
Analog Power Supply Voltage (AVDD _A)	3.3	5	5.5	V	REF2VDD = 0, ADC selects 2.4 V internal reference
	2.8	5	5.5	V	REF2VDD = 1, ADC selects AVDD as reference
Gate Driver Power supply voltage (VCC)	7		20	V	LKS32MC074DF8Q8 LKS32MC076FNBQ8
	4.5		20		LKS32MC070FLRBT8 LKS32MC071DOC8T8 LKS32MC074FF8Q8 LKS32MC074DOF8Q8 LKS32MC078KUBQ8

OPA could work under 2.2V, but the output range will be limited.

Table 5-3 LKS32MC07x 6N ESD Parameters

Item	Pin	Minimal	Max	Unit
ESD Test (HBM)	MCU Pin	-6000	6000	V
	Gate Driver G2 Pin	-2000	2000	V



	Gate Driver G6 Pin	-2500	2500	V
	Gate Driver G7 Pin	-2000	2000	V

According to "MIL-STD-883J Method 3015.9", under the environment of 25°C and 55% relative humidity, electrostatic discharge is applied to all IO pins of the tested chip for 3 times, with an interval of 1s each time.

Table 5-4 LKS32MC07x 6N Latch-up parameters

Item	Minimal	Max	Unit
Latch-up current (85 °C)	-200	200	mA

According to "JEDEC STANDARD NO.78E NOVEMBER 2016", a current of 200 ma is injected on each signal IO. The test results show that the anti-latch-up level of the chip is 200 mA.

Table 5-5 LKS32MC07x 6N IO absolute characteristics

Parameter	Description	Min.	Max.	Unit
V _{IN}	GPIO Signal Input Voltage Range	-0.3	6.0	V
I _{INJ_PAD}	Maximum Injection Current of A Single GPIO	-11.2	11.2	mA
I _{INJ_SUM}	Maximum Injection Current of All GPIOs	-50	50	mA

Table 5-6 LKS32MC07x 6N IO DC Parameters

Parameter	Description	AVDD	Conditions	Min.	Max.	Unit
V _{IH}	High input level of digital IO	5V	-	3.06		V
		3.3V		2.07		
V _{IL}	Low input level of digital IO	5V	-		0.3*AVDD	V
		3.3V			0.8	
V _{HYS}	Schmidt hysteresis range	5V	-	0.1*AVDD		V
		3.3V				
I _{IH}	Digital IO current consumption when input is high	5V	-		1	uA
		3.3V				
I _{IL}	Digital IO current consumption when input is low	5V	-	-1		uA
		3.3V				
V _{OH}	High output level of digital IO		Current = 11.2mA	AVDD-0.8		V
V _{OL}	Low output level of digital IO		Current = 11.2mA		0.5	V
R _{pup}	Pull-up resistor*			8	12	kΩ
R _{io-ana}	Connection resistance between IO and internal analog circuit			100	200	Ω
C _{IN}	Digital IO Input-capacitance	5V	-		10	pF
		3.3V				

* Only some IOs have built-in pull-up, see pin description section for details

Table 5-7 LKS32MC07x Module Current/IDD

模块	Min	Typ	Max	单位
Comparator x1		0.005		mA
OPA x1		0.450		mA
ADC		3.710		mA
DAC		0.710		mA
Temp Sensor		0.150		mA
Band-Gap		0.154		mA
4MHz RC Clock		0.105		mA
PLL		0.080		mA
CPU+flash+SRAM (96MHz)		8.667		mA
CPU+flash+SRAM (12MHz)		1.600		mA
CRC		0.070		mA
DSP		3.421		mA
UART		0.107		mA
DMA		1.340		mA
MCPWM		0.053		mA
TIMER		0.269		mA
SPI		0.500		mA
IIC		0.500		mA
CAN		2.200		mA
MCU Sleep Mode	9	12	20	uA

6 Analog Characteristics

The analog characteristics are shown in the following table.

Table 6-1 LKS32MC07x 6N analog characteristics

Parameter	Min.	Typ.	Max.	Unit	Explain
Analog-to-digital converter (ADC)					
Power Supply	3.3	5	5.5	V	ADC use 2.4V internal reference
	2.8	5	5.5	V	ADC use AVDD external reference source
Sampling rate		3		MHz	fadc/16
Differential Input Signal Range	-5.0 +0.144		+5.0 -0.144	V	When ADCx_GAIN = 1; REF=2.4V;
	-3.6 +0.072		+3.6 -0.072	V	When ADCx_GAIN = 0; REF=2.4V;
Single-ended Input Signal Range	-0.3		AVDD +0.3	V	Limited by the input voltage of the IO port
The differential signal is usually the signal output from the OPA inside the chip to the ADC; Single-ended signals are typically sampled externally via an IO input: The ADC should measure the signal amplitude no more than $\pm 98\%$ of the full scale, regardless of the internal/external reference used. In particular, when using an external reference, it is recommended that the sampling conductor not exceed 90% of the scale.					
DC offset		5	10	mV	Correctable
Effective number of bits (ENOB)	10.5	11		bit	
INL		2	3	LSB	
DNL		1	2	LSB	
SNR	63	66		dB	
Input Resistance	100k			Ohm	
Input Capacitance		10pF		F	
Reference Voltage (REF)					
Power Supply	2.2	5	5.5	V	
Output Deviation	-9		9	mV	
Rejection Ratio of Power Supply		70		dB	
Temperature Coefficient		20		ppm/°C	
Output Voltage		1.2		V	
Digital-to-Analog Converter (DAC)					
Power Supply	2.2	5	5.5	V	
Load Resistance	5k			Ohm	Output BUFFER is on
Load capacitance			50p	F	

Parameter	Min.	Typ.	Max.	Unit		Explain
Output voltage range	0.05		AVDD-0.1	V		
Conversion speed			1M	Hz		
DNL		1	2	LSB		
INL		2	4	LSB		
OFFSET		5	10	mV		
SNR	57	60	66	dB		
Operational Amplifier (OPA)						
Power Supply	2.8	5	5.5	V		
Bandwidth		10M	20M	Hz		
Load Resistance	20k			Ohm		
Load Capacitance			5p	F		
Input Common Mode Voltage Range (VICM)	0		AVDD	V		
Output Signal Range	0		2Vcm	V		Under minimum load resistance
Common Mode Voltage (Vcm)	1.45	1.8	2.2	V	32 times	Measurement condition: normal temperature. Operational amplifier swing=2 × min(AVDD-Vcm, Vcm). It is recommended that the application using OPA single output should be powered on to measure Vcm and make software subtraction correction. For more analysis, please refer to the official website application note "ANN009 - Differences between Operational Amplifier Differential and Single Operating Mode".
	1.5V	1.8	2.2	V	16 times	
	1.55	1.8	2.2	V	8 times	
	1.6	1.8	2.2	V	4 times	
OFFSET		10	15.0	mV		32 times
		10	16.5	mV		16 times
		10	18.5	mV		8 times

Parameter	Min.	Typ.	Max.	Unit	Explain
		10	20.5	mV	4 times
This OFFSET is the equivalent differential input deviation obtained when the OPA differential input is short-circuited and OPA OUT is measured from 0 level. The output deviation of OPA is OPA magnification x OFFSET. The Flash NVR area records the OPA offset for factory tests.					
Common Mode Rejection Ratio (CMRR)		80		dB	
Power Supply Rejection Ratio (PSRR)		80		dB	
Load Current			500	uA	
Slew Rate		5		V/us	
Phase Margin (PM)		60		Degree	
Comparator (CMP)					
Power Supply	2.2	5	5.5	V	
Input Signal Range	0		AVDD	V	
OFFSET	-36	-10	12	mV	0 mV hysteresis, CMP output transitions from low to high
	-36	-10	12	mV	0 mV hysteresis, CMP output transitions from high to low
	-14.5	-10	33.5	mV	20 mV hysteresis, CMP output transitions from low to high
	-14.5	11.5	33.5	mV	20 mV hysteresis, CMP output transitions from high to low
Delay		50		nS	Default power consumption
		200		nS	Low power consumption
Hysteresis		20		mV	HYS='0'
		0		mV	HYS='1'

Analog register table description:

The names of the analog registers are SYS_AFE_REG0 to SYS_AFE_REG6, corresponding to addresses 0x4000_0010 to 0x4000_0028. Address 0x4000_001C to 0x4000_0028 are the calibration registers of each analog module. These registers will fill their respective calibration values into the Flash info area before leaving the factory, and will be automatically loaded to the SYS_AFE_REG3 to SYS_AFE_REG6 after power-on. In general, the user should not configure or change these values. If



fine-tuning is required, please read the original settings first, and then adjust based on those values.

Addresses space of 0x4000_0000 to 0x4000_0018 are registers open to users. The blank registers must be configured to 0 (these registers will be reset to 0 after power on). Other registers could be configured in situations.

7 Power management system

AVDD Power System

The power management system is composed of LDO15 module, power detection module (PVD), power-on/power-off reset module (POR).

AVDD is powered by a 2.5V ~ 5.5V supply, and all internal digital circuits and PLL modules are powered by an internal LDO15.

The LDO15 is automatically turned on after power-on. No software configuration is necessary. And the LDO15 output voltage can be adjusted by software.

The output voltage of LDO15 can be adjusted by setting register LDO15TRIM<2:0>. The corresponding value of the register can be seen in the analog register table. LDO15 has been calibrated before it leaves the factory. Generally, users do not need to configure these registers again. If fine-tuning of the LDO output voltage is required, please read the original configuration value first, and then calculate the new settings accordingly.

The POR module monitors the voltage of the LDO15. When the voltage of the LDO15 is lower than 1.26V, for example, at the beginning of power-on or at the time of power-off, it will provide a reset signal for the digital circuit to avoid any abnormal operation.

The PVD module monitors the 5V input power. If it is below a certain threshold, it will remind the MCU by sending an alarm (interrupt) signal. The interrupt reminder threshold can be set to different voltages through the PVDSEL<1:0> registers. The PVD module can be turned off by setting PD_PDT = '1'. For the corresponding value of specific register, please refer to the analog register table.

VCC Power System

The operating power supply voltage range of VCC is 4.5 ~ 20V, which provides power for the on-chip gate driver module. If this voltage is below 4V it will be considered as undervoltage.

8 Clock system

The clock system consists of a 32KHz RC oscillator, a 8MHz RC oscillator, an external 8MHz crystal oscillator, and a PLL.

The 32K RC clock is used in the MCU system as a slow clock for modules such as reset/wakeup source filters or used in the low power mode; The 8MHz RC clock can be used as the main clock of the MCU, and can provide a reference clock to PLL. PLL clock is up to 96MHz; The external 8MHz crystal oscillator is used as a backup clock.

Both 32k and 8M RC clocks will be through factory calibration. In the range of -40 ~ 105 °C, the accuracy of the 32K RC clock is $\pm 50\%$, and the accuracy of the 8M RC clock is $\pm 1\%$.

The frequency of the 32K RC clock can be set by the register RCLTRIM<3:0>, and the frequency of the 8M RC clock can be set by the register RCHTRIM <5:0>. For the corresponding value of specific register, please refer to the analog register table.

The chip has been calibrated before it leaves the factory. Generally, users do not need to configure these registers again. If fine-tuning of the frequency is required, please read the original configuration value first, and then calculate the new settings accordingly.

The 8M RC clock is turned on by setting RCHPD = '0' (ON by default, turn off when set to '1'). The RC clock needs a reference voltage and current provided by the Bandgap voltage reference module; thus, do remember to turn on the BGP module before turning on the RC clock. When the chip is powered on, the 8M RC clock and BGP module are both turned on automatically. The 32K RC clock is always on and cannot be turned off.

The PLL multiplies the 8M RC clock to provide a higher frequency clock for modules like MCU and ADC. The highest frequency of MCU and PWM module is 96MHz, and the typical working frequency of ADC module is 48MHz. It can be set to different frequency by the register ADCLKSEL <1:0>.

PLL is turned on by setting PLLPDN = '1' (OFF by default, turn on when set to '1'). Before turning on the PLL module, the BGP (Bandgap) module should be turned on first. After the PLL is turned on, it needs a settling time of 6us to achieve a stable frequency output. When the chip is powered on, the RCH clock and BGP module are both turned on. PLL is OFF by default and could be enabled by software.

The crystal oscillator circuit has a built-in amplifier and an oscillator capacitor. Connect a crystal between IO OSC_IN/OSC_OUT and set XTALPDN = '1' to start the oscillation.

9 Reference Voltage

Reference voltage and current are provided for ADC, DAC, RC clock, PLL, temperature sensor, operational amplifier, comparator and FLASH. Before using any of the above modules, the BGP voltage reference should be turned on first.

When the chip is powered on, the BGP module is turned on automatically. The voltage reference is turned on by setting BGPPD = '0'. From OFF to ON, BGP needs about 6us to stabilize. BGP output voltage is about 1.2V, and accuracy is $\pm 0.8\%$.

10 ADC module

The chip integrated a synchronous double-sampling SAR ADC which is shut down by default when the chip is powered up. Before turning on ADC, the BGP module, 8M RC clock and PLL should be turned on first. In the default configuration, ADC clock is 48MHz, which corresponds to a conversion rate of 3Msps.

The synchronous double sampling circuit can sample the two input analog signals at the same time. After the sampling is completed, the ADC converts the two signals one by one and writes them into the corresponding data registers.

ADC takes 16 ADC clock cycles to complete one conversion, of which 13 are conversion cycles and 3 are sampling cycles. I.E. $f_{conv}=f_{adc}/16$. When the ADC clock is set to 48MHz, the conversion rate is 3Msps.

When the ADC is working at a lower frequency, the power consumption can be reduced by setting register CURRIT<1:0>.

ADC could work in different modes: One-time single channel trigger mode, continuous single channel sampling mode, One-time 1 to 20 channels scanning mode, continuous 1 to 20 channels scanning mode. It has a set of 20 independent registers for each analog channel.

The ADC trigger can be MCPWM/Timer trigger signals T0, T1, T2 and T3 happened for the preset number of times, or software trigger event.

ADC_DC stores the DC offset of ADC. Usually, in the calibration phase, the ADC DC offset value is obtained by measuring the AVSS (internal ground) of Channel 15 (counting from 0) and stored in flash. In the system loading phase, the DC offset is written into the ADC_DC register by software.

The ADC has two ranges set by the ADC X_GAIN (X = 0, 1): 3.6 V and 7.2 V. At the 7.2 V range, this corresponds to a maximum input signal amplitude of ± 5 V because the chip is powered at 5 V. At the 3.6 V range, this corresponds to a maximum input signal amplitude of ± 3.6 V. When measuring the output signal of an op amp, select the specific ADC gain based on the maximum signal that the op amp can output.

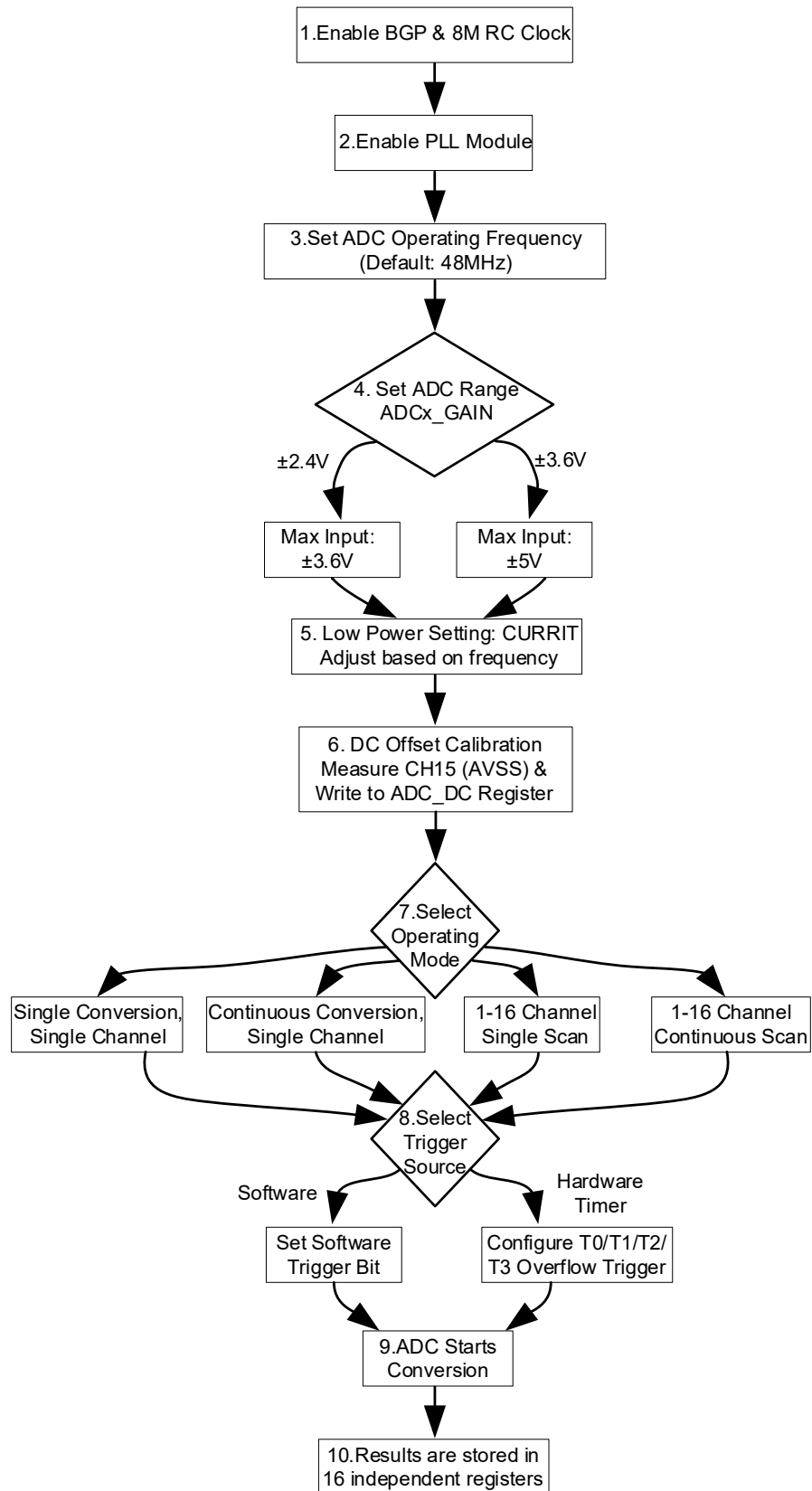


Figure 10-1ADC Configuration Flowchart

11 Operational Amplifier

4-channel of rail-to-rail OPAs are integrated, with a built-in feedback resistor $R2/R1$. A resistor $R0$ is required to be connected in series to the external pin. The resistance of feedback resistors $R2:R1$ can be adjusted by register $RES_OPA0<1:0>$ to achieve different gain. For the corresponding value of specific register, please refer to the analog register table.

The close-loop gain of OPA is $R2/(R1+R0)$, where $R0$ is the resistance of the external resistor.

For the application of MOS resistance direct sampling, it is recommended to connect an external resistance of $>20k\Omega$ to reduce the current flowing into the chip pin when the MOS is turned off;

For the application of small resistance sampling, it is recommended to connect an external resistor of 100Ω .

The OPA can select one of the output signals of the 4-channels amplifiers by setting $OPAOUT_EN<2:0>$, and send it to the P2.7 IO port through a buffer for measurement (see the corresponding relationship in the datasheet 'Pin Function Description"). Because of this buffer, the OPA is able to be output to an IO while operating normally.

When the chip is powered on, the OPA module is OFF by default. It can be turned on by setting $OPAxPDN = '1'$, and turn on the BGP module before turning on the amplifier.

For built-in clamp diodes are integrated between the positive and negative OPA inputs, the motor phase line could be directly connected to the OPA input through a matching resistor, thereby simplifying the external circuit for MOSFET current sampling.

12 Comparator

Built-in 3-channel rail-to-rail comparators with programmable comparator speed, hysteresis voltage, and signal source.

The comparison delay of the comparator can be set to < 30nS/200 nS through Register CMP_FT. The hysteresis voltage is set to 20 mV/0 mV by the CMP_HYS.

The comparator positive input signal source can be set by register CMPx_SELP [2:0]; the comparator negative input signal source can be set by register CMPx_SELN [1:0] (X = 0/1/2 for comparators CMP0/CMP1/CMP2) .

When the chip is powered on, the comparator module is OFF by default. The comparator is turned on by setting CMPxPDN = '1', and turn on the BGP module before turning on the comparator.

13 Temperature sensor

The chip has a temperature sensor with an accuracy of $\pm 2^{\circ}\text{C}$. The temperature sensor will be calibrated in factory, and the calibration value is saved in the flash info area.

When the chip is powered on, the temperature sensor module is OFF by default. Turn on the BGP module before turning on the temperature sensor.

The temperature sensor is turned on by setting $\text{TMPPDN} = '1'$, and it takes about $2\mu\text{s}$ to be stable after turning on. Thus, it should be turned on at least $2\mu\text{s}$ ahead before the ADC measures the sensor output.

14 DAC module

The chip contains two 12-bit DACs, and the maximum range of the output signal can be set to 1.2 V/4.85 V using the DAC0_GAIN and DAC1_GAIN registers.

DAC0 can route the DAC0 output to the P0.0 pin through the configuration register DAC0OUT_EN = 1, and DAC1 can route the DAC1 output to the P0.0 pin through the configuration register DAC1OUT_EN = 1, which can drive a load resistor of > 5k Ω and a load capacitance of 50pF. Normally, DAC0 and DAC1 are not output at the same time to avoid signal contention.

The maximum output bit rate of DAC is 1MHz.

When the chip is powered on, the DAC module is OFF by default. DAC0 can be turned on by setting DAC0PDN = 1, and DAC1 can be turned on by setting DAC1PDN = 1. Before turning on the DAC module, you need to turn on the BGP module.

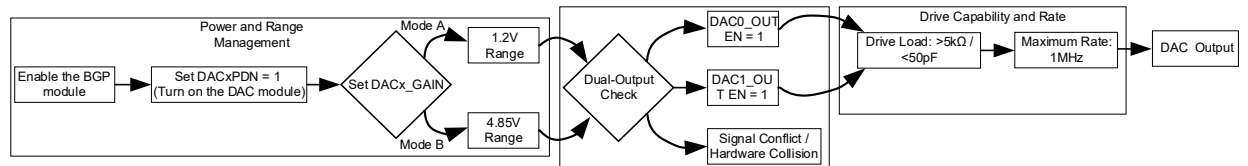


Figure 14-1 DAC Configuration Flowchart

15 Processor core

- 32-bit Cortex-M0 + DSP dual-core processor
- Two-wire SWD debug pin
- System frequency is up to 96MHz

16 Storage resources

16.1 Flash

- built-in flash including 64kB/128kB main area and 1.5kB NVR
- Endurance: 100,000 Cycles(min)
- Data retention: more than 100 years
- Single byte program: 7.5us(max), Sector erase: 5ms(max)
- Sector size 512bytes, supporting Sector erase/program and in-application program
- Flash data anti-theft by programming the last word of flash to any words other than 0xFFFFFFFF

16.2 SRAM

- built-in 12kB SRAM

17 MCPWM for motor drive

- MCPWM operating frequency is up to 96MHz
- It can generate 6 pairs of non-overlapping PWM signals (complementary mode) or 12 independent non-overlapping PWM signals (edge-aligned mode). The module consists of two chopper modules, with each group sharing one dead-time configuration.
- Support edge-aligned PWM
- Support software control IO mode
- Support IO polarity control
- Internal short circuit protection to avoid short circuit due to configuration error
- External short circuit protection, enabling fast shutdown by monitoring the external signals
- Internal ADC sampling interrupt
- Preload MCPWM register configuration and update simultaneously
- Programmable load time and period

18 Timer

- 4-channel standard timer, 2-channel 16-bit timer, 2-channel 32-bit timer.
- Support capture mode for measuring external signal/pulse width
- Support comparison mode for timed interruption of edge-aligned PWM

19 Hall sensor interface

- Built-in 1024 cycles filtering
- 3-channel Hall signal input
- 24-bit counter, with overflow and capture interrupt

20 DSP

- Customized DSP instruction set for motor control algorithm, , three-stage pipeline architecture
- Operating frequency is up to 96MHz
- 32/16-bit divider, could finish one division calculation in 12 cycles (96MHz)
- 32-bit hardware SQRT, could finish one SQRT calculation in 8 cycles (96MHz)
- Q15 format Cordic trigonometric function module, could finish sin/cos/artanc calculation in 20 cycles (96MHz)
- DSP has independent program memory and data memory, DSP could execute its program independently, and can also be called by MCU to perform a certain calculation as a AHB slave like a coprocessor
- Support DSP IRQ and pause state for data exchange purpose with MCU

21 General Purpose Peripheral

- Two UART, full-duplex operation, support 8/9 data bit, 1/2 stop bit, odd/even/no parity mode, with 1 byte tx buffer, 1 byte rx buffer, support Multi-drop Slave/Master mode, support 300 to 115200 baud rate
- One SPI, support master-slave mode
- One IIC, support master-slave mode
- Hardware watchdog, driven by 32kHz RC clock and which is independent of system high-speed clock, the minimum reset interval was $4096/32\text{kHz} \approx 128\text{ms}$, and the maximum reset interval was $511 \times 4096/32\text{kHz} \approx 64\text{s}$.

22 Gate drive module

22.1 Module parameters

The internal gate driver module of the chip has 4 different parameter specifications. According to the different gate driver circuit parameters, the gate driver module is divided into 4 models, which are G1~G3、G6 respectively. The comparison table is as Table 22-1.

Table 22-1 Device-Gate driver circuit version comparison table

Chip model	Model of gate drive module
LKS32MC070FLRBT8	G6
LKS32MC071DOC8T8	G6
LKS32MC074FF8Q8	G6
LKS32MC074DF8Q8	G2
LKS32MC074DOF8Q8	G6
LKS32MC076FNBQ8	G2

"YYWWX*" is the data code and chip version number, see the third line of the chip silk print. "YYWWX" is the production date, "*" is optional, and is usually A, B, C, D... or blank, which represents the version number of the chip pre-driver.

22.1.1 Gate drive module G2

Table22-2 Gate Driver Module G2 Parameter

Parameter	Minim al	Typica l	Max	Unit	Explain
Absolute Maximum Ratings					
Low side and logic fixed supply VCC	-0.3		+25.0	V	Relative to the ground
High side floating supply VB	-0.3		+250	V	
High side offset VS	VB-25		VB+0.3	V	
High side output HO _{1,2,3}	VS-0.3		VB+0.3	V	
Low side output LO _{1,2,3}	-0.3		VCC+0.3	V	
Logic input HIN/LIN _{1,2,3}	-0.3		VCC+0.3	V	
Allowable offset voltage slew rate dVs/dt			50	V/ns	
Junction temperature TJ	-40		150	°C	
Storage temperature Ts	-55		150	°C	
Lead temperature			300	°C	Weld for 10 s
Recommended Operating Conditions					
Low side and logic fixed supply VCC	+7		+20.0	V	Relative to the ground

High side floating supply VB	VS+8		VS+20	V	
High side offset VS	-5		200	V	
High side output HO _{1,2,3}	VS		VB	V	
Low side output LO _{1,2,3}	0		VCC	V	
Logic input HIN/LIN _{1,2,3}	0		VCC	V	
Ambient temperature T _A	-40		105	°C	
Gate driver Electrical Characteristic					
Quiescent VCC supply current		50	100	uA	HIN=LIN=0V
Quiescent VBS supply current		20	40	uA	HIN=LIN=0V
Floating supply leakage I _{LK}			10	uA	VB=VS=220V
VCC supply under-voltage trigger voltage	4.0	4.7	6.7	V	
VBS supply under-voltage trigger voltage	3.9	5.6	6.9	V	
VCC supply under-voltage lock -on voltage	3.6	4.4	6.4	V	
VBS supply under-voltage lock -on voltage	3.5	5.0	6.2	V	
VCC supply under-voltage hysteresis voltage	0.25	0.3	0.8	V	
VBS supply under-voltage hysteresis voltage	0.25	0.6	0.8	V	
High level input threshold voltage V _{IH}	2.8			V	
Low level input threshold voltage V _{IL}			0.8	V	
Input bias current I _{source}		32	120	uA	HIN=LIN=5V
Input bias current I _{sink}			1	uA	HIN=LIN=0V
High level output, V _{BIAS} -V _O			1	V	IO=20mA
Low level output, V _O			1	V	IO=20mA
High level output short current I _{O+}	650	1000		mA	VCC/VBS=15V
Low level output short current I _{O-}	650	1000		mA	VCC/VBS=15V
Turn-on propagation delay T _{on}		15	30	ns	CL=1nF
Turn-off propagation delay T _{off}		12	30	ns	
Turn-on rise time T _r		270	500	ns	
Turn-off fall time T _f		80	150	ns	
Dead time D _T	100	200	400	ns	
Delay matching M _T			80	ns	Ton & Toff for (HS-LS)

22.1.2 Gate drive module G6

A bootstrap diode is integrated in the predrive.



Table22-3 Gate Driver Module G6 Parameter

Parameter	Minimum	Typical	Maximum	Unit	Description
Limit parameter					
Supply voltage VCC	-0.3		+22.0	V	Relative to ground
Floating voltage VB _{1, 2, 3}	-0.3		+250	V	
			VS+22		
Floating bias VS _{1, 2, 3}	VB-25		VB+0.3	V	074DO
			60		Ohters
High-side output voltage HO _{1, 2, 3}	VS-0.3		VB+0.3	V	
Low-side output voltage LO _{1, 2, 3}	-0.3		VCC+0.3	V	
Logic input HIN/LIN _{1, 2, 3}	-0.3		VCC+0.3	V	
Swing rate of switching voltage dVs/dt			50	V/ns	
Temperature junction (TJ)	-40		150	°C	
Storage temperature (TS)	-55		150	°C	
Welding temperature			300	°C	Welding 10s
Recommended operating conditions					
Supply voltage VCC	+5.0		+20.0	V	Relative to ground
Floating voltage VB _{1, 2, 3}	VS+8		200	V	
			VS+20		
Floating bias VS _{1, 2, 3}	-5		VB+0.3	V	074DO
			+60		Ohters
High-side output voltage HO _{1, 2, 3}	VS _{1,2,3}		VB _{1,2,3}	V	
Low-side output voltage LO _{1, 2, 3}	0		VCC	V	
Logic input HIN/LIN _{1, 2, 3}	0		5	V	
Operating temperature T _A	-40		105	°C	
Electrical parameters of type 6N type gate driver					
VCC static current I _{QCC}		110		uA	HIN=LIN=0/5V
VB static current I _{QBS}		25	50	uA	HIN=LIN=0V
Floating voltage leakage current I _{LK}			10	uA	VB=VS=200V, VCC=0V
drive current I _{O+}	0.65	1		A	
drive current I _{O-}	0.65	1		A	

VCC undervoltage rising edge trigger voltage	3.5	4.2	4.5	V	
VCC undervoltage falling edge trigger voltage	2.8	3.8	4.4	V	
VCC undervoltage lockout hysteresis	0.2	0.4		V	
VBS undervoltage rising edge trigger voltage	2.5	3.8	5	V	
VBS undervoltage falling edge trigger voltage	2.2	3.5	4.3	V	
VBS undervoltage lockout hysteresis	0.2	0.3		V	
High input threshold V_{IH}	2.8			V	
Low input threshold V_{IL}			0.8	V	
Output rise time T_r		20	30	ns	$C_L=1nF$
Output fall time T_f		12	30	ns	
Turn-on delay time T_{on}		250	500	ns	
Shutdown delay time T_{off}		120	200	ns	
Dead zone D_T	50	150	400	ns	
Delay matching M_T			80	ns	
LDO linear adjustment parameters					
LDO output voltage: V_{LDO}	4.8	5.0	5.2	V	The factory test records the 5V LDO voltage in the flash area for the software to read. For details about Flash NVR correction addresses, see the data manual
LDO Output on-load current I_{LDO}		30		mA	
Load regulation	-0.297		+0.397	%	Load current:0~35mA
Linear adjustment rate		0		%	VCC from 7 to 22V
Short-circuit current	122		142	mA	

22.1.3 Gate drive module G7

Table 22-4 Gate Driver Module G7 Parameter

Parameter	Minimum	Typical	Maximum	Unit	Description
Limit parameter					
Supply voltage VCC	-0.3		+25.0	V	Relative to ground
Floating voltage VB _{1, 2, 3}	-0.3		+650	V	
Floating bias VS _{1, 2, 3}	VB-25		VB+0.3	V	
High-side output voltage HO _{1, 2, 3}	VS-0.3		VB+0.3	V	
Low-side output voltage LO _{1, 2, 3}	-0.3		VCC+0.3	V	
Logic input HIN/LIN _{1, 2, 3}	-0.3		VCC+0.3	V	
Swing rate of switching voltage dVs/dt			50	V/ns	
Temperature junction (TJ)	-40		150	°C	
Storage temperature (TS)	-55		150	°C	
Welding temperature			300	°C	Welding 10s
Recommended operating conditions					
Supply voltage VCC	+13		+20.0	V	Relative to ground
Floating voltage VB _{1, 2, 3}	VS+13		VS+20	V	
Floating bias VS _{1, 2, 3}	-5		600	V	
High-side output voltage HO _{1, 2, 3}	VS		VB	V	
Low-side output voltage LO _{1, 2, 3}	0		VCC	V	
Logic input HIN/LIN _{1, 2, 3}	0		VCC	V	
Operating temperature T _A	-40		105	°C	
Electrical parameters of type 6N type gate driver					
VCC static current I _{QCC}			2300	uA	HIN=LIN=0V
VB static current I _{QBS}			100	uA	HIN=LIN=0V
Floating voltage leakage current I _{LK}			50	uA	VB=VS=620V
VCC supply under-voltage trigger voltage	11	12	12.8	V	
VCC supply under-voltage lock -on voltage	9.5	10.4	11	V	
VCC supply under-voltage hysteresis voltage	1	1.6	2	V	
High input threshold V _{IH}	1.7		2.4	V	
Low input threshold V _{IL}	0.8	1.0	1.2	V	
High level output short current I _{O+}	115	200		mA	
Low level output short current I _{O-}	250	350		mA	

Short circuit trip level V_{CIN_REF}	0.455	0.48	0.505	V	$V_{CC}=15V$
Fault output voltage V_{FOL}			0.95	V	
Fault output pulse width t_{FO}	20	65		μs	
Output rise time T_r		65		ns	$C_L=1nF$
Output fall time T_f		25		ns	
Turn-on delay time T_{on}	350	500	700	ns	
Shutdown delay time T_{off}	350	500	700	ns	
Delay matching M_T			60	ns	$T_{on} \& T_{off}$ for (HS-LS)
CIN detection input filter time $T_{FLT-CIN}$	100	300	500	ns	CIN 0->1V, test CIN rising edge to LO falling edge delay

22.2 Recommended application diagram

22.2.1 G2

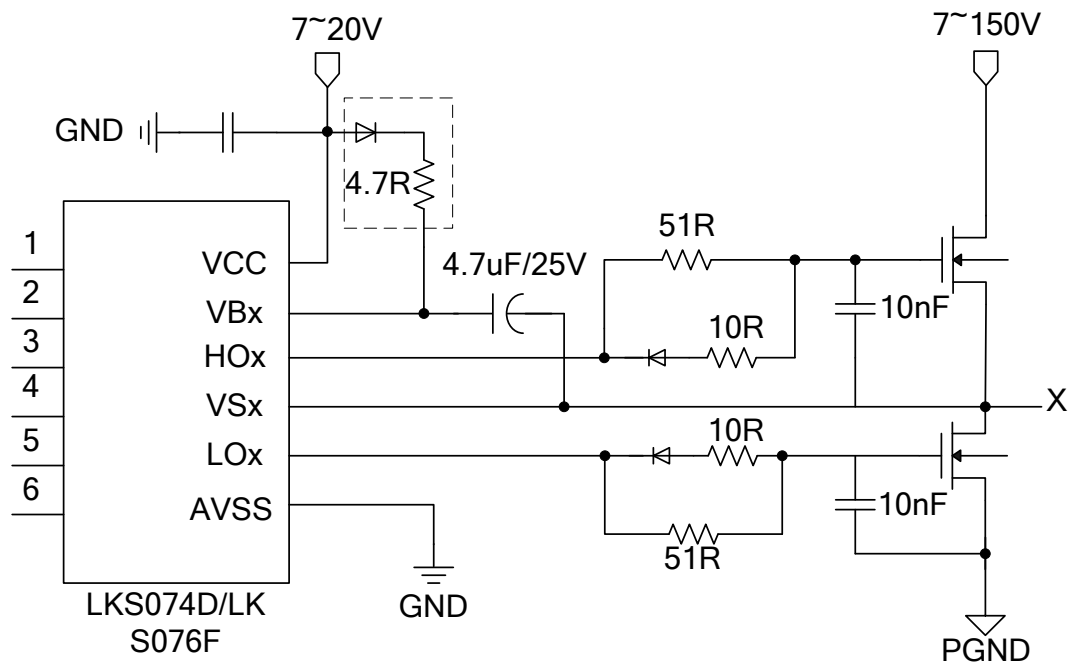


Figure22-1 Gate Driver Module G2 Application Diagram

It's recommended to add bootstrap diode between VBx and VCC for G2.

22.2.2 G6

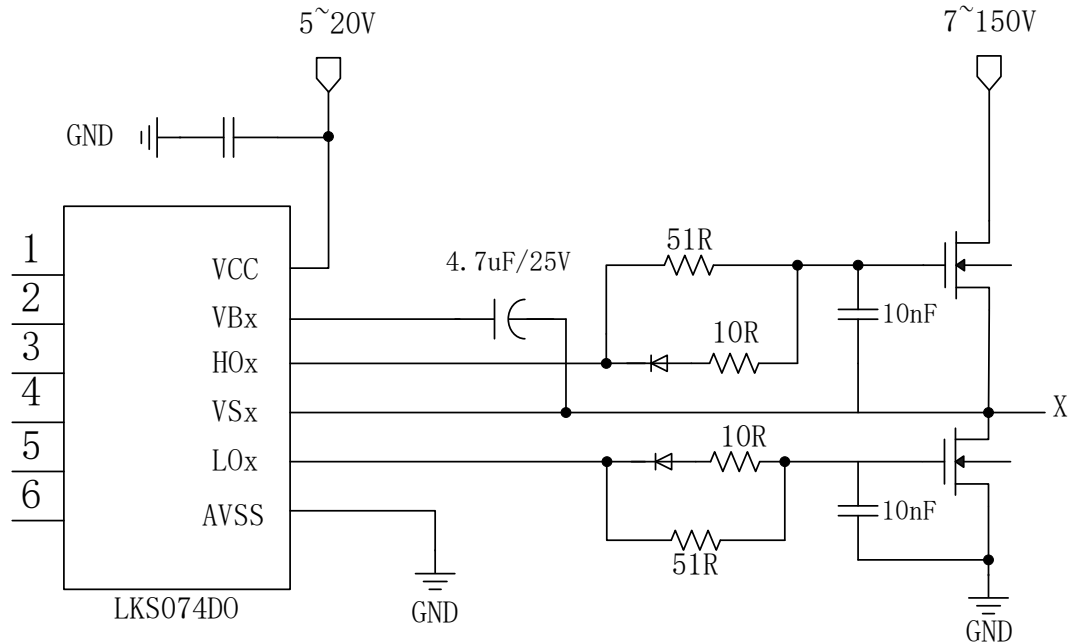


Figure22-2 Gate Driver Module G6 Application Diagram

Gate Driver Module G6 has built-in bootstrap diode, so the bootstrap on board won't be necessary. But you could still use a bootstrap diode for compatibility concern.

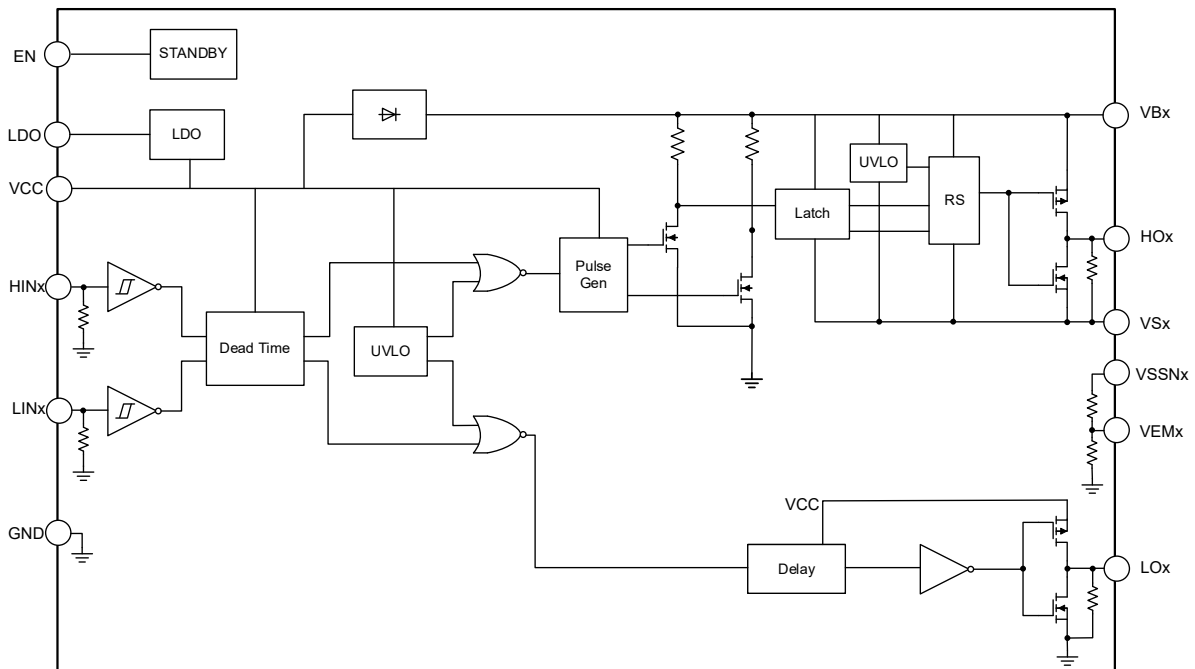


Figure22-3 Gate Driver Module G6 internal block diagram

The gate driver module G6 has built-in VS voltage detection function. For the MCU with VEM pin led out by 070FL/071DO, the VSx shown in the diagram and VSSNx are shorted inside the chip, and

the VS voltage of the corresponding phase line can be obtained by measuring the VEMx voltage to the ground. The resistance of the inner part is 50K to 3.3K, and the corresponding partial voltage ratio is about 16:1.

Only the gate drive module pins are shown in the figure, where x = 1,2,3 corresponding to the three sets of MOS gate drive outputs. The application diagram of each set is shown in Figure22-4.

The corresponding relationship between the input and output polarities of the grid drive module is as follows:

Table22-5 Gate Driver Module G1/G2/G3/G6 truth table

{HIN, LIN}	HO	LO	
00	0	0	Upper and lower tubes are turned off
01	0	1	Lower tube conduction
10	1	0	Upper tube conduction
11	0	0	Upper and lower tubes are conducted at the same time, and hardware short circuit protection

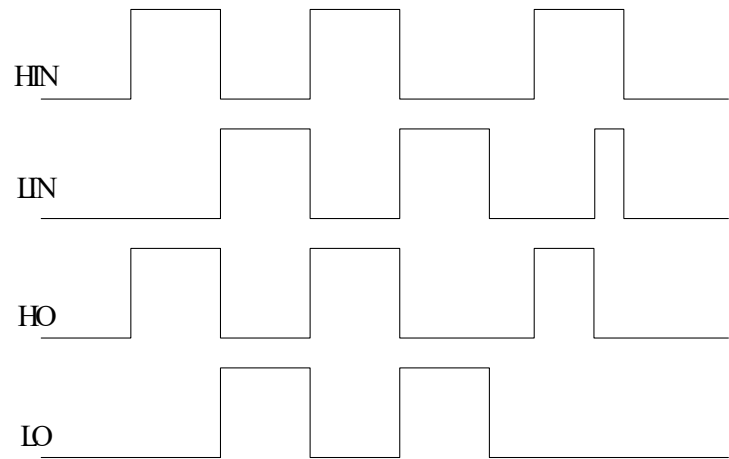


Figure 22-5 Gate Driver Module G1/G2/G3/G6 polarity illustration

22.2.3 G7

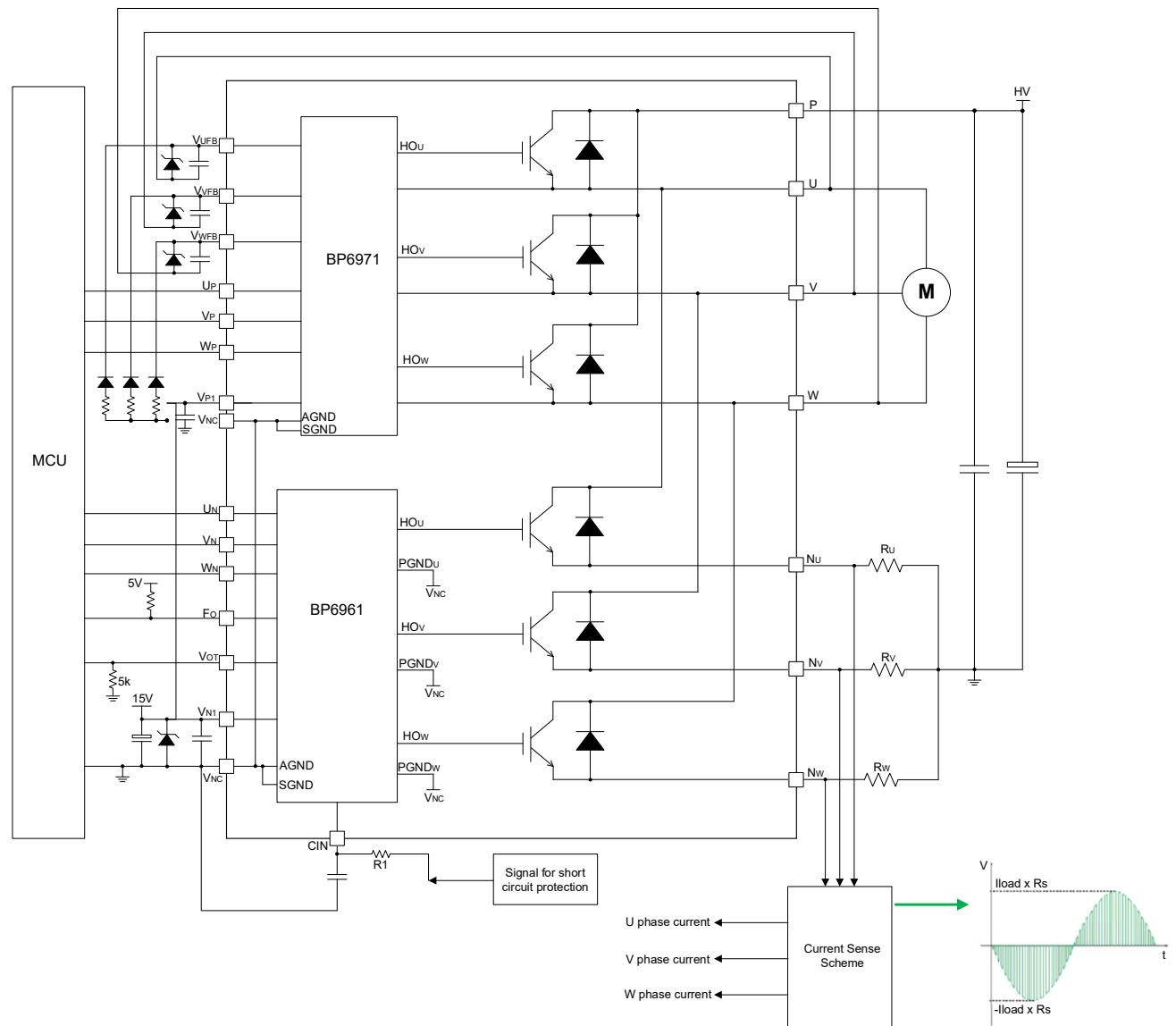


Figure 22-6 Typical Application Diagram of G7 Gate Driver Module

As shown in the figure, the low-side pre-driver integrates the FO function. The FO pin is connected to GPIO P0.7 of the MCU and is active-low.

Configure P0.7 to the MCPWM_BKIN1 function. When overcurrent pulls the FO pin low, the MCU's PWM output will be shut down.

The input-output polarity correspondence of the gate driver module is as follows:

Table 22-6 Truth Table for Polarity of G7 Gate Driver Module

{HIN, LIN}	HO	LO	
00	0	0	Both high-side and low-side switches off
01	0	1	Low-side switch conducting
10	1	0	High-side switch conducting
11	0	0	Simultaneous conduction of high-side and low-side switches,

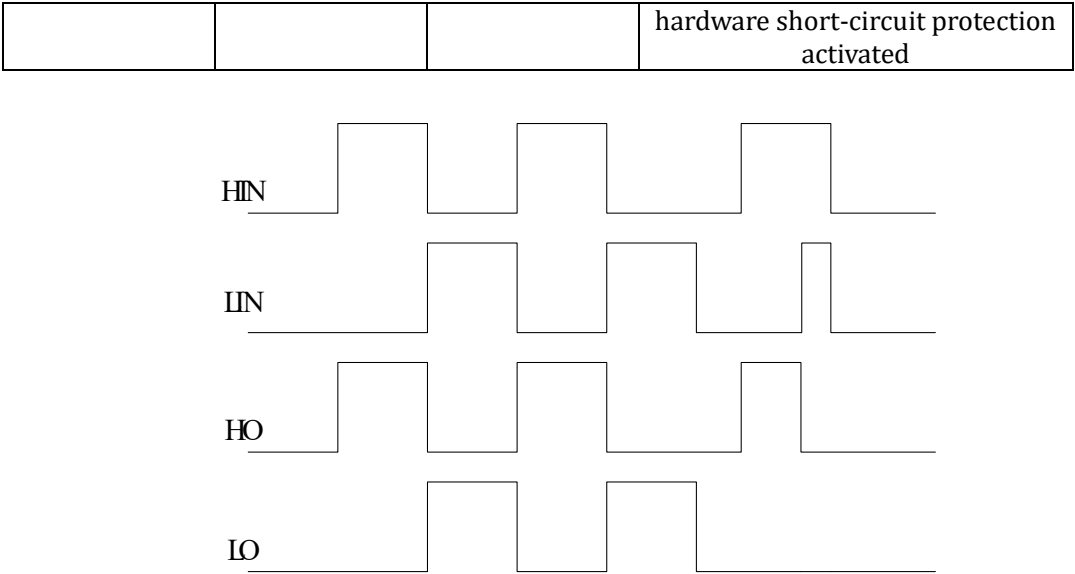


Figure 22-7 Polarity Timing Diagram of G7 Gate Driver Module

23 Special IO multiplexing

Notes for Special IO Multiplexing of LKS07x

The SWD protocol includes two signals: SWCLK and SWDIO. SWCLK is a clock signal. To the chip, it is an input and will always be an input. SWDIO is a data signal. It switches between the input state and the output state during data transmission, and the default is the input state.

Some LKS07x SWD pins also have GPIO function. The IO multiplexed by SWCLK is P2.14 and the IO multiplexed by SWDIO is P2.15. The precautions are as follows:

- The default state of GPIO multiplexing is disabled, IO are used as SWD. After the hard reset of the chip, the initial state of IOs are SWD. Both IOs of SWD are fixed pull-up inside the chip (the internal pull-up resistor of the chip is about 12K). Please pay attention to the initial IO voltage level if application has specific requirements.
- When GPIO multiplexing is enabled, tools such as KEIL cannot directly access the chip, i.e., the Debug and erase download functions cannot access the chip since SWD are now general GPIO. If the program needs to be downloaded again, there are two solutions.
- Firstly, it is recommended to use Linko's dedicated offline downloader to erase. It is recommended to leave a certain margin before switching SWD to GPIO, such as about 100ms, to ensure that the offline downloader can erase the chip and prevent the deadlock. This margin is to ensure a successful offline downloader erasing. A greater margin means a greater probability of the successful one-time erasion.
- Secondly, the application should have a GPIO multiplexing exit mechanism. For example, some other IO invert (usually input), indicates that the SWDIO is required externally, and the software needs to be reconfigured to disable the multiplexing. At this moment, the KEIL function can access the chip via SWD again.

In SSOP24L package and QFN5*5 40L-0.75 package, SWDIO is directly bonded with P0.0 and P2.15, and the corresponding GPIO can be directly enabled. It is recommended that SWDCLK keep unchanged (constant 1 or constant 0) when multiplexing SWDIO

For LKS077E, SWDCLK is bonded with P2.6 and the corresponding GPIO can be directly enabled. If SWDIO and SWDCLK are multiplexed at the same time, considerations for SWDCLK multiplexing are as follows:

- The default state of GPIO multiplexing is disabled, IO are used as SWD. After the hard reset of the chip, the initial state of IOs are SWD. Both IOs of SWD are fixed pull-up inside the chip (the internal pull-up resistor of the chip is about 300K). Please pay attention to the initial IO voltage level if application has specific requirements.
- When GPIO multiplexing is enabled, tools such as KEIL cannot directly access the chip, i.e., the Debug and erase download functions cannot access the chip since SWD are now general GPIO. If the program needs to be downloaded again, there are two solutions.
- Firstly, it is recommended to use Linko's dedicated offline downloader to erase. It is recommended to leave a certain margin before switching SWD to GPIO, such as about 100ms, to ensure that the offline downloader can erase the chip and prevent the deadlock. This margin is



to ensure a successful offline downloader erasing. A greater margin means a greater probability of the successful one-time erasion.

- Secondly, the application should have a GPIO multiplexing exit mechanism. For example, some other IO invert (usually input), indicates that the SWDIO is required externally, and the software needs to be reconfigured to disable the multiplexing. At this moment, the KEIL function can access the chip via SWD again.

When SWDCLK and SWDIO pins are used as GPIO, they should not act at the same time. That is, when SWDCLK multiplexing is enabled and changes, SWDIO can remain at level 0 (similar to time division multiplexing).

For RSTN signal, the default is for the external reset pin of LKS07x chip.

LKS07x allow users to multiplex RSTN as other IOs, and the multiplexed IO is P0.2. The precautions are as follows:

- The default state of reset IO multiplexing is disabled, and the software needs to write 1 to SYS_RST_CFG[5] to multiplex RSTN as GPIO. I.e., the initial state of P0[2] is RSTN. RSTN is provided with a pull-up resistor inside the chip (the internal pull-up resistor of the chip is about 300K). Attention shall be paid when the application has requirements for initial electric level.
- The default state of P0[2] is used as external reset, and the program can only be executed after the RSTN is released. The application needs to ensure that the RSTN has sufficient protection, such as the peripheral circuit with a pull-up resistor. It is better to add a capacitor.
- After RST IO multiplexing is enabled, the external reset is unavailable to the chip. If a hard reset is required, the reset source can only be power-down/watchdog reset.
- The multiplexing of RSTN does not affect the use of KEIL.

Bit [5] in the SYS_RST_CFG register controls the switch for multiplexing RSTN and P0.2.

24 Ordering Information

Tray Package:

Package Type	Quantity per disc/tube	Quantity in box	Quantity in case
SOP16/ESOP16L	3000/ disc	6000PCS	48000PCS
SSOP24	4000/ disc	8000PCS	64000PCS
SSOP24	50/ pipe	10000PCS	4000/100000PCS
QFN 8*8	260/ disc	2600PCS	15600PCS
QFN 4*4/5*5/6*6	490/ disc	4900PCS	29400PCS
QFN 3*3	5000/ disc	5000PCS	40000PCS
LQFP48/TQFP48 0707	250/ disc	2500PCS	15000PCS
LQFP64 1010	160/ disc	1600PCS	9600PCS
LQFP100 1414	90/ disc	900PCS	5400PCS
TSSOP20/28	4000/ disc	8000PCS	64000PCS

Reel Package:

Package Type		Quantity per disc/tube	Quantity per box	Quantity boxes per case	Quantity per case
Braid -13 inches	SOP/ESOP8	4000	8000	8	64000
Braid -13 inches	SOP/ESOP16	3000	6000	8	48000
Braid -13 inches	SSOP24	4000	8000	8	64000
Braid -13 inches	TSSOP20	4000	8000	8	64000
Braid -13 inches	D/QFN3*3	5000	10000	8	80000
Braid -13 inches	D/QFN4*4	5000	10000	8	80000
Braid -13 inches	D/QFN5*5	5000	10000	8	80000
Pipe	SOP16	50	10000	10	100000
Pipe	SOP14/SSOP24	50	10000	10	100000
Pipe	TSSOP24	54	6480	6	38880



25 Version history

Table25-1Document version history

Time	Version No.	Description
2026.09.20	1.41	Revise pull-up resistors
2026.08.31	1.40	Revise the external reference source of the ADC
2026.06.24	1.39	Add model 078K.
2026.06.22	1.38	Revise the rising/falling edge trigger voltage of G6
2026.06.10	1.37	Revise the description of CAN in the selection table
2026.06.01	1.36	Revision 071 DOC8T8 Pin Description
2026.04.01	1.35	Revised 071 DOC8T8 package dimensions
2026.03.17	1.34	Revise the floating voltage and floating bias of the G6 gate drive
2026.03.12	1.33	Revised floating voltage rating for G6 gate drive
2026.03.09	1.32	Revise the CMP trip voltage parameters
2026.01.26	1.31	Add the configuration description block diagram for the DAC module.
2026.01.20	1.30	Add ADC configuration flowchart
2026.01.08	1.29	Remove non-matching model types from the selection table.
2025.12.28	1.31	Revise the MCPWM module description to: Two chopper modules, with each group sharing one dead-time configuration.
2025.12.24	1.30	Revise the block diagrams of gate drive modules G2 and G6.
2025.12.09	1.29	ADC01 adds a separator
2025.11.03	1.28	Revised OPA Module Common-Mode Level
2025.10.15	1.27	Add Disposal Instructions
2025.08.29	1.26	071DOC8T8 adjust font
2025.08.22	1.25	Update naming rules
2025.08.01	1.24	Adding pre-driver GPIO functionality to MC071C8T8 P0.3 pin
2025.07.21	1.23	Delete the Flash section: erase/program one sector while accessing another
2025.01.02	1.22	Update the offset voltage of the CMP
2024.11.14	1.21	Add 074FF8Q8, updated the distinction between pre-driven PGND and MCU GND
2024.09.29	1.20	The belly Pad grounding of a QFN package is defined as Pin0
2024.08.21	1.19	Add internal predrive connection diagram
2024.08.04	1.18	Order package information updates to confirm package information by package type and package form
2024.06.04	1.17	Updated the VEM pin description of the G6 predrive module, Complete some errata
2024.04.15	1.16	QFN40L package size updated, adding the gate drive module G6 LDO linear adjustment rate parameter
2024.03.16	1.15	Add 070FL/071DO gate driver internal block diagram and VEM pins description
2024.02.19	1.14	Add a description of the 5V LDO output powering the MCU, updated

		the Die ESD level
2024.01.19	1.13	Remove CAN from 074D/DO pin diagram, correct VB and VS voltage range in gate module G6, supplement ADC module channel number description
2023.11.30	1.12	Update new model 076
2023.11.20	1.11	Add description of OPA offset
2023.10.22	1.10	Modify the device selection table
2023.09.25	1.09	Update welding temperature, modify non-volatile memory Sector erase description
2023.09.05	1.08	Update new models 070FL
2023.08.21	1.07	Modified 071DO, increased the number of 074D/DO ADC channels
2023.08.10	1.06	Update new models 071DO and 074DO
2023.07.27	1.05	Modified/updated 07x 6N new model 074D/074F
2023.07.21	1.04	Updated supplementary features for Pin20 and Pin21
2023.07.04	1.03	Modify the opa output signal range, power supply range,sleep power consumption and Vcm
2023.05.07	1.02	Update the number of times the flash can be erased repeatedly
2023.04.07	1.01	Update package description
2023.03.16	1.0	Initial version

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